

ProASIC^{PLUS} Flash Family FPGAs



Features and Benefits

High Capacity

- 75,000 to 1 million System Gates
- 27k to 198kbits of Two-Port SRAM
- 66 to 712 User I/Os

Reprogrammable Flash Technology

- 0.22μ 4LM Flash-based CMOS Process
- Live at Power-Up, Single-Chip Solution
- No Configuration Device Required
- Retains Programmed Design during Power-Down/Power-Up Cycles

Performance

- 3.3V, 32-bit PCI (up to 50 MHz)
- Two Integrated PLLs
- External System Performance up to 150 MHz

Secure Programming

- The Industry's Most Effective Security Key (FlashLockTM) Prevents Read Back of Programming Bitstream

Low Power

- Low Impedance Flash Switches
- Segmented Hierarchical Routing Structure
- Small, Efficient, Configurable (Combinatorial or Sequential) Logic Cells

High Performance Routing Hierarchy

- Ultra-Fast Local and Long-Line Network
- High Speed Very Long-Line Network

- High Performance, Low Skew, Splittable Global Network
- 100% Routability and Utilization

I/O

- Schmitt-Trigger Option on Every Input
- 2.5V/3.3V Support with Individually-Selectable Voltage and Slew Rate
- Bidirectional Global I/Os
- Compliance with PCI Specification Revision 2.2
- Boundary-Scan Test IEEE Std. 1149.1 (JTAG) Compliant
- Pin Compatible Packages across ProASIC^{PLUS} Family

Unique Clock Conditioning Circuitry

- PLL with Flexible Phase, Multiply/Divide and Delay Capabilities
- Internal and/or External Dynamic PLL Configuration
- Two LVPECL Differential Pairs for Clock or Data Inputs

Standard FPGA and ASIC Design Flow

- Flexibility with Choice of Industry-Standard Frontend Tools
- Efficient Design through Frontend Timing and Gate Optimization

ISP Support

- In-System Programming (ISP) via JTAG Port

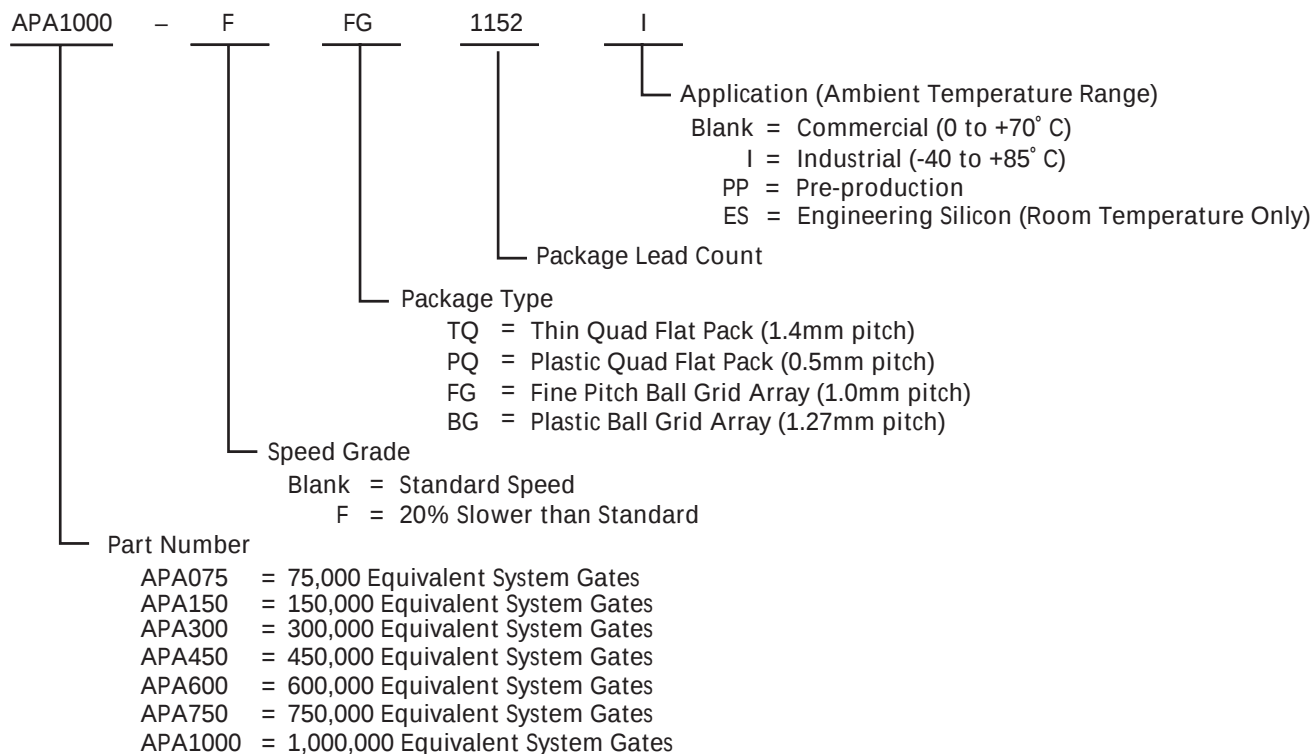
SRAMs and FIFOs

- ACTgen Netlist Generation Ensures Optimal Usage of Embedded Memory Blocks
- 24 SRAM and FIFO Configurations with Synchronous and Asynchronous Operation up to 150 MHz (typical)

Table 1 • ProASIC^{PLUS} Product Profile

Device	APA075	APA150	APA300	APA450	APA600	APA750	APA1000
Maximum System Gates	75,000	150,000	300,000	450,000	600,000	750,000	1,000,000
Maximum Tiles (Registers)	3,072	6,144	8,192	12,288	21,504	32,768	56,320
Embedded RAM Bits (k=1,024 bits)	27k	36k	72k	108k	126k	144k	198k
Embedded RAM Blocks (256x9)	12	16	32	48	56	64	88
LVPECL	2	2	2	2	2	2	2
PLL	2	2	2	2	2	2	2
Global Networks	4	4	4	4	4	4	4
Maximum Clocks	24	32	32	48	56	64	88
Maximum User I/Os	158	242	290	344	454	562	712
JTAG ISP	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PCI	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Package (by pin count)							
TQFP	100, 144	100	–	–	–	–	–
PQFP	208	208	208	208	208	208	208
PBGA	–	456	456	456	456	456	456
FBGA	144	144, 256	144, 256	144, 256, 484	256, 484, 676	676, 896	896, 1152

Ordering Information



Plastic Device Resources

User I/Os*										
Device	TQFP 100-Pin	TQFP 144-Pin	PQFP 208-Pin	PBGA 456-Pin	FBGA 144-Pin	FBGA 256-Pin	FBGA 484-Pin	FBGA 676-Pin	FBGA 896-Pin	FBGA 1152-Pin
APA075	66	107	158		100					
APA150	66		158	242	100	186				
APA300			158	290	100	186				
APA450			158	344	100	186	344			
APA600			158	356		186	370	454		
APA750			158	356				454	562	
APA1000			158	356					642	712

Package Definitions

TQFP = Thin Quad Flat Pack, PQFP = Plastic Quad Flat Pack, PBGA = Plastic Ball Grid Array, FBGA = Fine Pitch Ball Grid Array

*Each pair of PECL I/Os were counted as one user I/O.

General Guideline

Maximum performance numbers in this datasheet are based on characterized data. Actel does not guarantee performance beyond the limits specified within the datasheet.

Product Availability

	Speed Grade		Application	
	Std.	-F*	C	I
APA075 Device				
100-Pin Thin Quad Flat Pack (TQFP)	✓	✓	✓	✓
144-Pin Thin Quad Flat Pack (TQFP)	✓	✓	✓	✓
208-Pin Plastic Quad Flat Pack (PQFP)	✓	✓	✓	✓
144-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
APA150 Device				
100-Pin Thin Quad Flat Pack (TQFP)	✓	✓	✓	✓
208-Pin Plastic Quad Flat Pack (PQFP)	✓	✓	✓	✓
456-Pin Plastic Ball Grid Array (PBGA)	✓	✓	✓	✓
144-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
256-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
APA300 Device				
208-Pin Plastic Quad Flat Pack (PQFP)	✓	✓	✓	✓
456-Pin Plastic Ball Grid Array (PBGA)	✓	✓	✓	✓
144-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
256-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
APA450 Device				
208-Pin Plastic Quad Flat Pack (PQFP)	✓	✓	✓	✓
456-Pin Plastic Ball Grid Array (PBGA)	✓	✓	✓	✓
144-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
256-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
484-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
APA600 Device				
208-Pin Plastic Quad Flat Pack (PQFP)	✓	✓	✓	✓
456-Pin Plastic Ball Grid Array (PBGA)	✓	✓	✓	✓
256-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
484-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
676-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
APA750 Device				
208-Pin Plastic Quad Flat Pack (PQFP)	✓	✓	✓	✓
456-Pin Plastic Ball Grid Array (PBGA)	✓	✓	✓	✓
676-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
896-Pin Plastic Ball Grid Array (FBGA)	✓	✓	✓	✓
APA1000 Device				
208-Pin Plastic Quad Flat Pack (PQFP)	✓	✓	✓	✓
456-Pin Plastic Ball Grid Array (PBGA)	✓	✓	✓	✓
896-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓
1152-Pin Fine Pitch Ball Grid Array (FBGA)	✓	✓	✓	✓

Notes:

*-F parts are only available as commercial temperature devices.

Applications: C = Commercial Availability: ✓ = Available

I = Industrial

PP = Product Planned

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General Description

The ProASIC^{PLUS} family of devices, Actel's second generation Flash FPGAs, offers enhanced performance over Actel's ProASIC family. It combines the advantages of ASICs with the benefits of programmable devices through nonvolatile Flash technology. This enables engineers to create high-density systems using existing ASIC or FPGA design flows and tools. In addition, the ProASIC^{PLUS} family offers a unique clock conditioning circuit based on two on-board phase-locked loops (PLLs). The family offers up to 1 million system gates, support for up to 198kbits of two-port SRAM and up to 712 user I/Os, all providing 50 MHz PCI performance.

Advantages to the designer extend beyond performance. Unlike SRAM-based FPGAs, four levels of routing hierarchy simplify routing, while the use of Flash technology allows all functionality to be live at power-up. No external Boot PROM is required to support device programming. While on-board security mechanisms prevent all access to the program information, reprogramming can be performed in-system to support future design iterations and field upgrades. The device's architecture mitigates the complexity of ASIC migration at higher user volume. This makes ProASIC^{PLUS} a cost-effective solution for applications in the networking, communications, computing, and avionics markets.

The ProASIC^{PLUS} family achieves its nonvolatility and reprogrammability through an advanced Flash-based 0.22µm LVCMOS process with four-layers of metal. Standard CMOS design techniques are used to implement logic and control functions, including the PLLs and LVPECL inputs. This results in predictable performance fully compatible with gate arrays.

The ProASIC^{PLUS} architecture provides granularity comparable to gate arrays. The device core consists of a Sea-of-Tiles™. Each tile can be configured as a flip-flop, latch, or three-input/one-output logic function by programming the appropriate Flash switches. The

combination of fine granularity, flexible routing resources, and abundant Flash switches allow 100% utilization and over 95% routability for highly congested designs. Tiles and larger functions are interconnected through a four-level routing hierarchy.

Embedded two-port SRAM blocks with built-in FIFO/RAM control logic can have user-defined depth and width. Users can also select programming for synchronous or asynchronous operation, as well as parity generations or checking.

The unique clock conditioning circuitry in each device includes two clock conditioning blocks. Each block provides a PLL core, delay lines, phase shifts (0°, 90°, 180°, 270°), and clock multipliers/dividers, as well as the circuitry needed to provide bidirectional access to the PLL. The PLL block contains four programmable frequency dividers, which allow the incoming clock signal to be divided by a wide range of factors from 1 to 64. The clock conditioning circuit also delays or advances the incoming reference clock up to 8 ns (in increments of 0.25 ns). The PLL can be configured internally or externally during operation without redesigning or reprogramming the part. In addition to the PLL, there are two LVPECL differential input pairs to accommodate high speed clock and data inputs.

To support customer needs for more comprehensive, lower cost board-level testing, Actel's ProASIC^{PLUS} devices are fully compatible with IEEE Standard 1149.1 for test access port and boundary-scan test architecture. For more information concerning the Flash FPGA implementation, please refer to the "[Boundary Scan \(JTAG\)](#)" on page 1-10.

ProASIC^{PLUS} devices are available in a variety of high-performance plastic packages. Those packages and the performance features discussed above are described in more detail in the following sections.

ProASIC^{PLUS} Architecture

The proprietary ProASIC^{PLUS} architecture provides granularity comparable to gate arrays.

The ProASIC^{PLUS} device core consists of a Sea-of-Tiles™ (Figure 1-1). Each tile can be configured as a three-input logic function (e.g., NAND gate, D-Flip-Flop, etc.) by programming the appropriate Flash switch interconnections (Figure 1-2 on page 1-3 and Figure 1-3 on page 1-3). Tiles and larger functions are connected with any of the four levels of routing hierarchy. Flash switches are distributed throughout the device to provide nonvolatile, reconfigurable interconnect programming. Flash switches are programmed to connect signal lines to the appropriate logic cell inputs and outputs. Dedicated high-performance lines are connected as needed for fast, low-skew global signal distribution throughout the core. Maximum core utilization is possible for virtually any design.

ProASIC^{PLUS} devices also contain embedded two-port SRAM blocks with built-in FIFO/RAM control logic. Programming options include synchronous or asynchronous operation, two-port RAM configurations, user defined depth and width, and parity generation or checking. Please see the "Embedded Memory Configurations" on page 1-20 for more information.

Flash Switch

Unlike SRAM FPGAs, ProASIC^{PLUS} uses a live on power-up ISP Flash switch as its programming element.

In the ProASIC^{PLUS} Flash switch, two transistors share the floating gate, which stores the programming information. One is the sensing transistor, which is only used for writing and verification of the floating gate voltage. The other is the switching transistor. It can be used in the architecture to connect/separate routing nets or to configure logic. It is also used to erase the floating gate (Figure 1-2 on page 1-3).

Logic Tile

The logic tile cell (Figure 1-3 on page 1-3) has three inputs (any or all of which can be inverted) and one output (which can connect to both ultra-fast local and efficient long-line routing resources). Any three-input, one-output logic function (except a three-input XOR) can be configured as one tile. The tile can be configured as a latch with clear or set or as a flip-flop with clear or set. Thus, the tiles can flexibly map logic and sequential gates of a design.

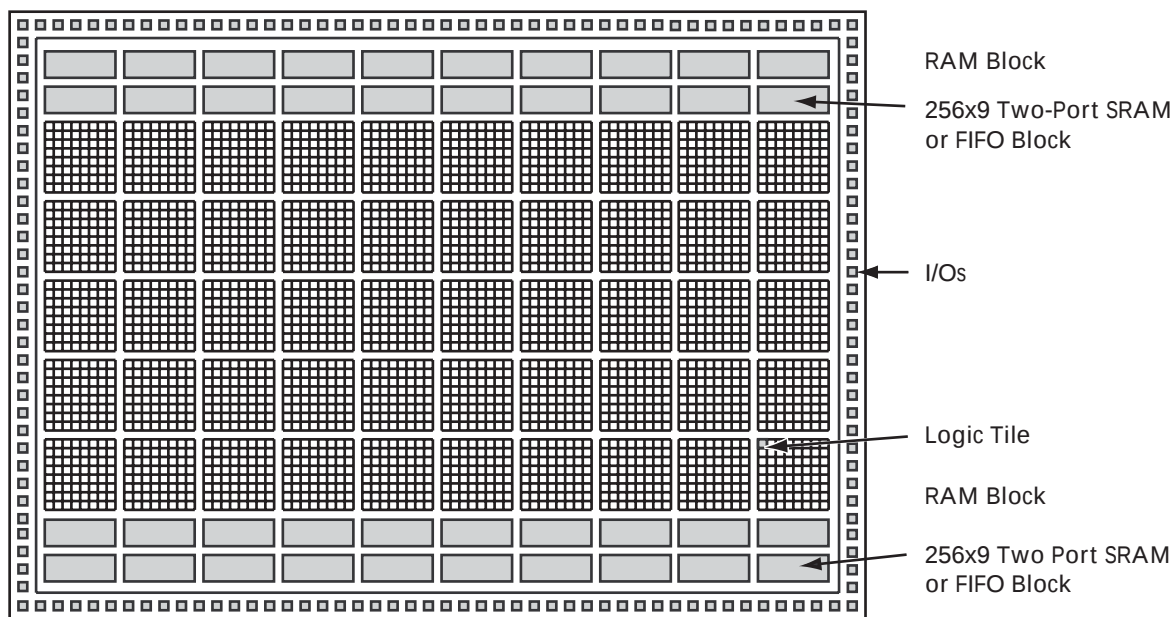


Figure 1-1 • The ProASIC^{PLUS} Device Architecture

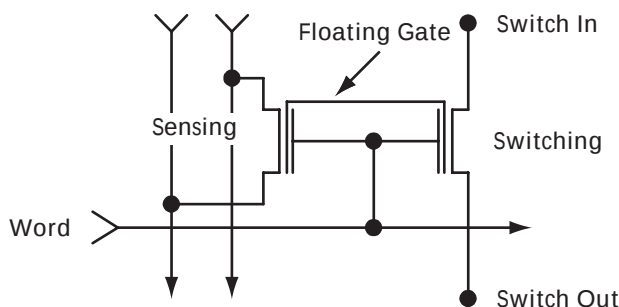


Figure 1-2 • Flash Switch

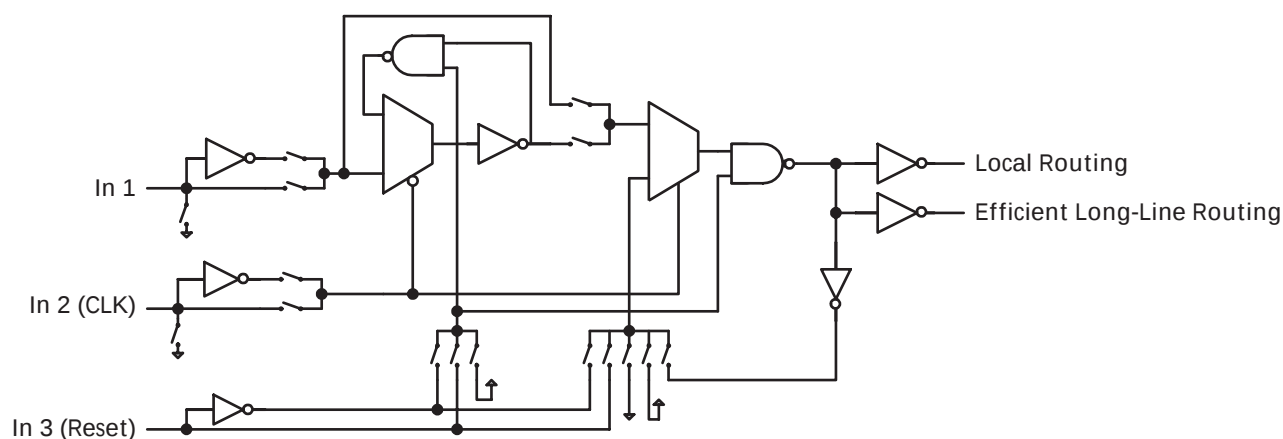


Figure 1-3 • Core Logic Tile

Routing Resources

The routing structure of ProASIC^{PLUS} devices is designed to provide high performance through a flexible four-level hierarchy of routing resources: ultra-fast local resources, efficient long-line resources, high speed very long-line resources, and high performance global networks.

The ultra-fast local resources are dedicated lines that allow the output of each tile to connect directly to every input of the eight surrounding tiles (Figure 1-4 on page 1-4).

The efficient long-line resources provide routing for longer distances and higher fanout connections. These resources vary in length (spanning 1, 2, or 4 tiles), run both vertically and horizontally, and cover the entire ProASIC^{PLUS} device (Figure 1-5 on page 1-4). Each tile can

drive signals onto the efficient long-line resources, which can in turn, access every input of every tile. Active buffers are inserted automatically by routing software to limit the loading effects due to distance and fanout.

The high-speed very long-line resources, which span the entire device with minimal delay, are used to route very long or very high fanout nets. (Figure 1-6 on page 1-5).

The high-performance global networks are low skew, high fanout nets that are accessible from external pins or from internal logic (Figure 1-7 on page 1-6). These nets are typically used to distribute clocks, resets, and other high fanout nets requiring a minimum skew. The global networks are implemented as clock trees, and signals can be introduced at any junction. These can be employed hierarchically with signals accessing every input on all tiles.

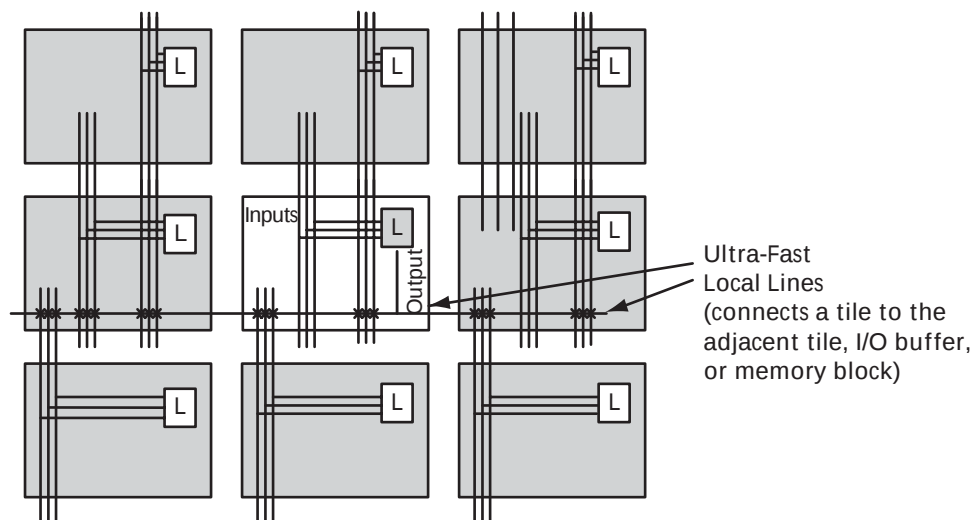


Figure 1-4 • Ultra-Fast Local Resources

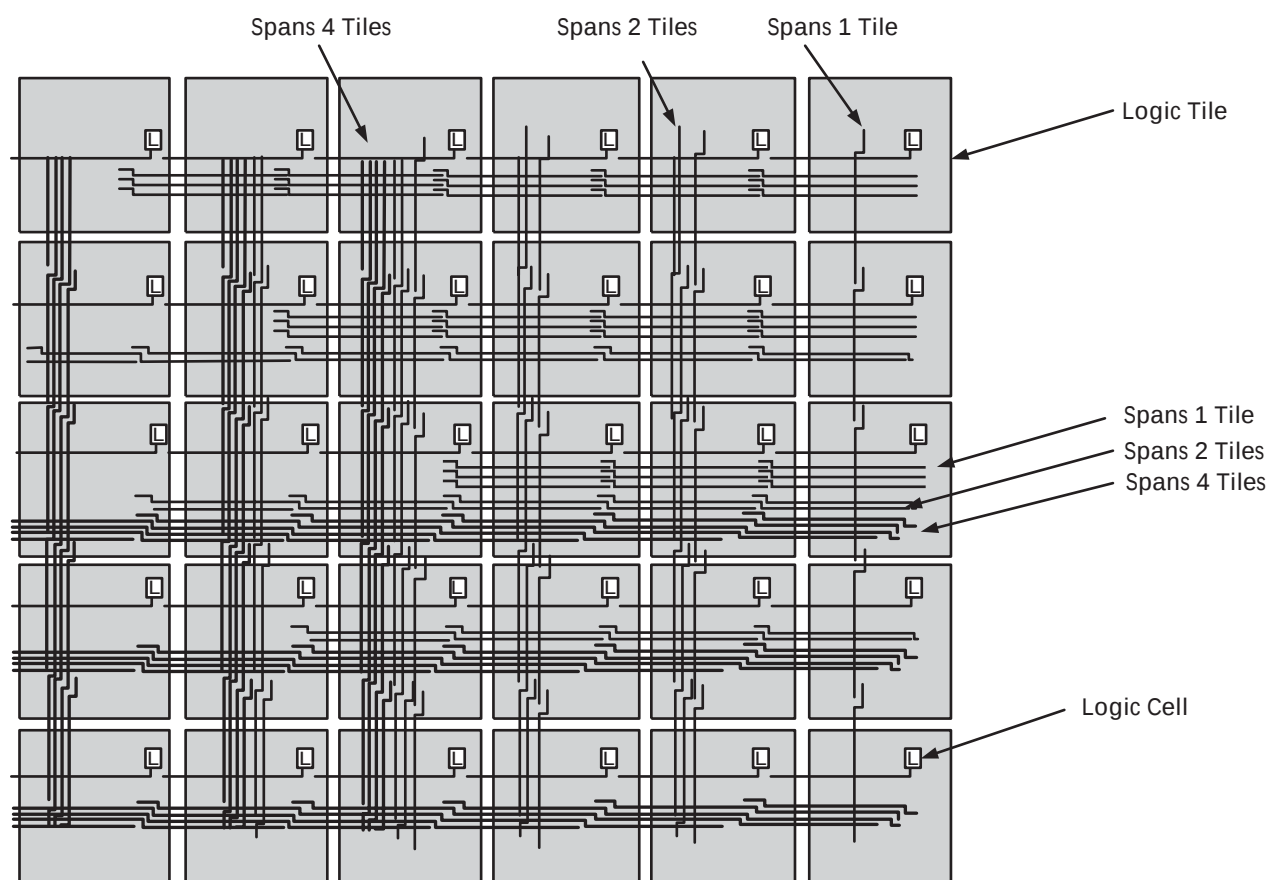


Figure 1-5 • Efficient Long-Line Resources

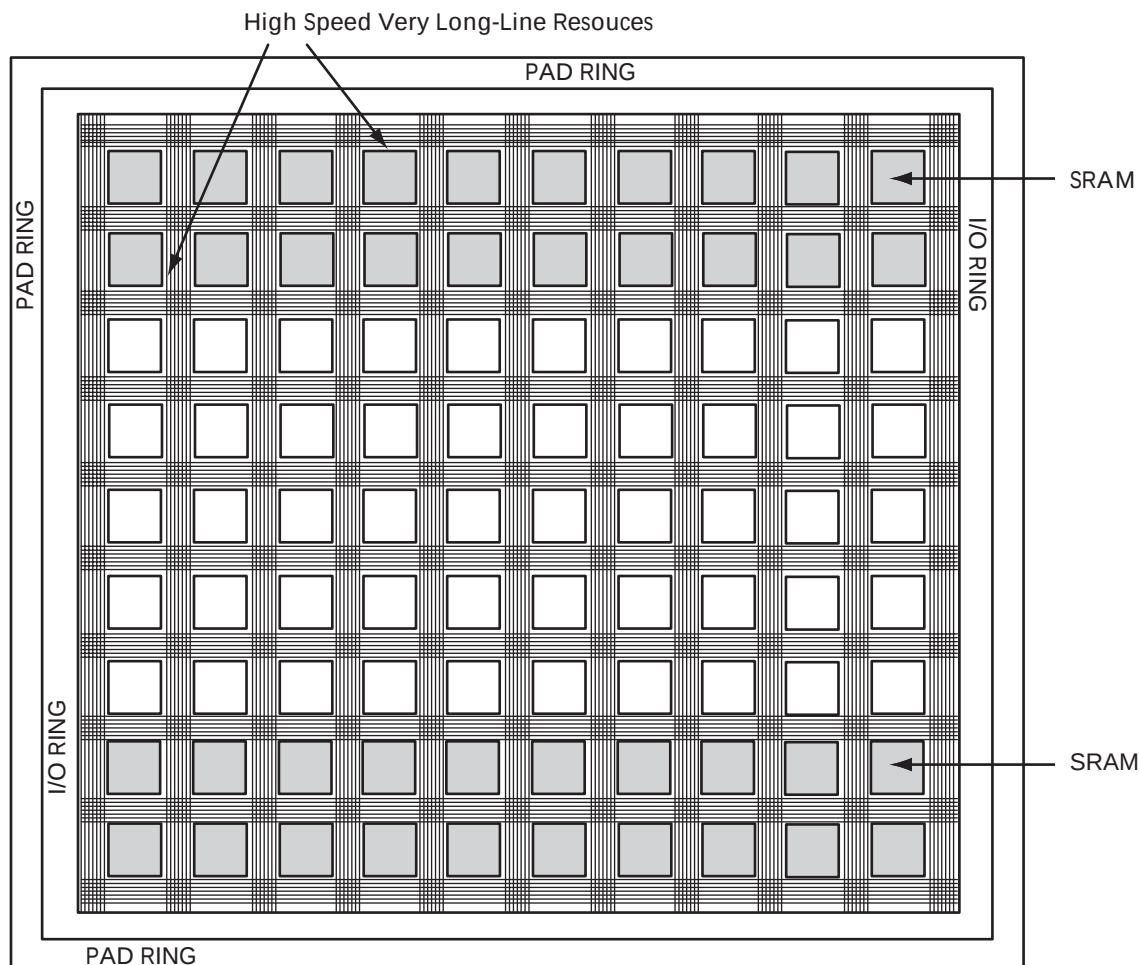


Figure 1-6 • High Speed Very Long-Line Resources

Clock Resources

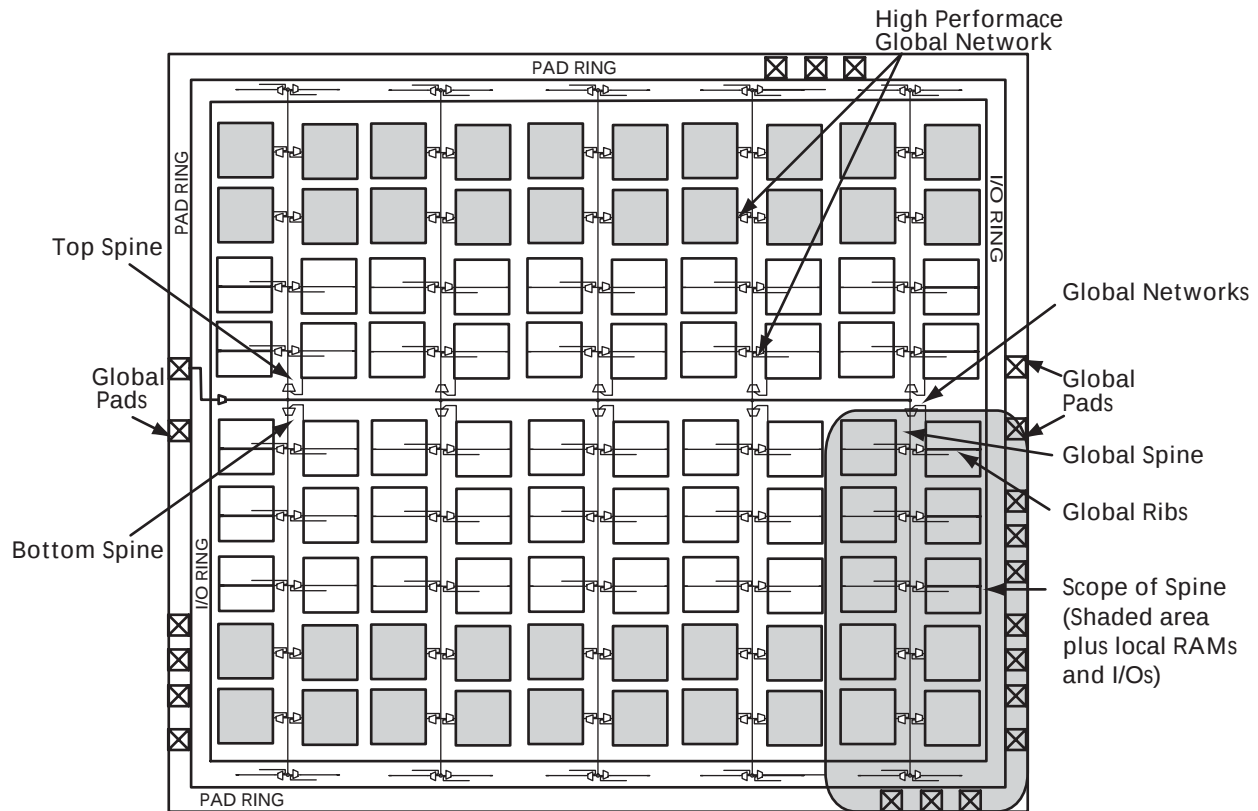
The ProASIC^{PLUS} family offers powerful and flexible control of circuit timing through the use of analog circuitry. Each chip has two clock conditioning blocks containing a phase-locked loop (PLL) core, delay lines, phase shifter (0°, 90°, 180°, 270°), clock multiplier/dividers and all the circuitry needed for the selection and interconnection of inputs to the global network (thus providing bidirectional access to the PLL). This permits the PLL block to drive inputs and/or outputs via the two global lines on each side of the chip (four total lines). This circuitry is discussed in more detail in the "ProASICPLUS Clock Management System" on page 1-11.

Clock Trees

One of the main architectural benefits of ProASIC^{PLUS} is the set of power and delay friendly global networks.

ProASIC^{PLUS} offers four global trees. Each of these trees is based on a network of spines and ribs that reach all the tiles in their regions (Figure 1-7 on page 1-6). This flexible clock tree architecture allows users to map up to 88 different internal/external clocks in an APA1000 device. Details on the clock spines and various numbers of the family are given in Table 1-1 on page 1-6.

The flexible use of the ProASIC^{PLUS} clock spine allows the designer to cope with several design requirements. Users implementing clock-resource intensive applications can easily route external or gated internal clocks using global routing spines. Users can also drastically reduce delay penalties and save buffering resources by mapping critical high-fanout nets to spines. For design hints on using these features, refer to Actel's *Efficient Use of ProASIC Clock Trees* application note.



Note: This figure shows routing for only one global path.

Figure 1-7 • High Performance Global Network

Table 1-1 • Clock Spines

	APA075	APA150	APA300	APA450	APA600	APA750	APA1000
Global Clock Networks (Trees)	4	4	4	4	4	4	4
Clock Spines/Tree	6	8	8	12	14	16	22
Total Spines	24	32	32	48	56	64	88
Top or Bottom Spine Height (Tiles)	16	24	32	32	48	64	80
Tiles in Each Top or Bottom Spine	512	768	1,024	1,024	1,536	2,048	2,560
Total Tiles	3,072	6,144	8,192	12,288	21,504	32,768	56,320

Array Coordinates

During many place-and-route operations in Actel's Designer software tool, it is possible to set constraints that require array coordinates.

Table 1-2 on page 1-7 is provided as a reference. The array coordinates are measured from the lower left (0,0). They can be used in region constraints for specific groups, designated by a wildcard, and containing core cells, I/Os, and memories.

I/O and cell coordinates are used for placement constraints. Two coordinate systems are needed because there is not a one-to-one correspondence between I/O

cells and core cells. In addition, the I/O coordinate system changes depending on the die/package combination.

Core cell coordinates start at the lower left corner (1,1) or (1,5) if memories are present at the bottom. Memory coordinates use the same system and are indicated in Table 1-2 on page 1-7. The memory coordinates for an APA1000 are illustrated in Figure 1-8 on page 1-7. For more information on how to use constraints, see the *Designer User's Guide* or online help for ProASIC^{PLUS} software tools.

Table 1-2 • Array Coordinates

Device	Logic Tile				Memory Rows		All	
	Min.		Max.		Bottom	Top		
	x	y	x	y	y	y	Min.	Max.
APA075	1	1	96	32	–	(33,33) or (33, 35)	0,0	97, 37
APA150	1	1	128	48	–	(49,49) or (49, 51)	0,0	129, 53
APA300	1	5	128	68	(1,1) or (1,3)	(69,69) or (69, 71)	0,0	129, 73
APA450	1	5	192	68	(1,1) or (1,3)	(69,69) or (69, 71)	0,0	193, 73
APA600	1	5	224	100	(1,1) or (1,3)	(101,101) or (101, 103)	0,0	225, 105
APA750	1	5	256	132	(1,1) or (1,3)	(133,133) or (133, 135)	0,0	257, 137
APA1000	1	5	352	164	(1,1) or (1,3)	(165,165) or (165, 167)	0,0	353, 169

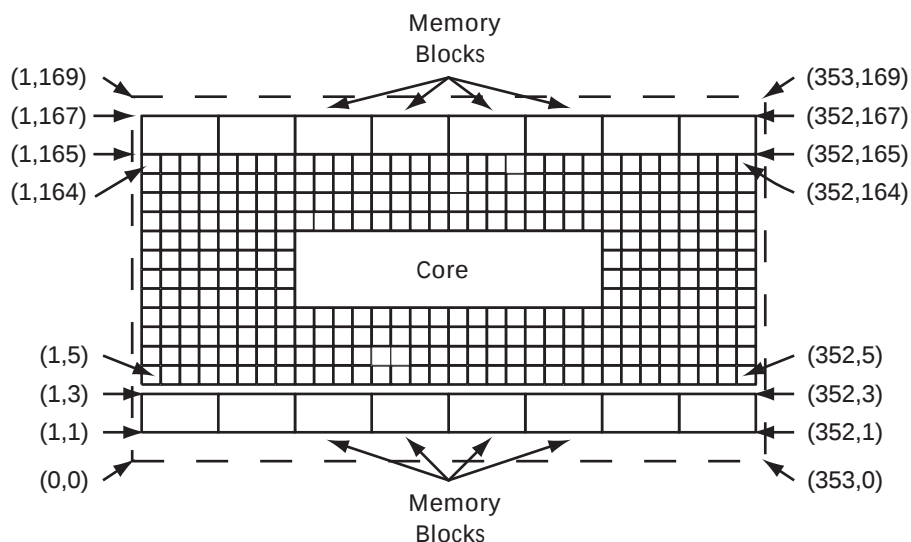


Figure 1-8 • Core Cell Coordinates for the APA1000

Input/Output Blocks

To meet complex system demands, the ProASIC^{PLUS} family offers devices with a large number of user I/O pins, up to 712 on the APA1000. If the I/O pad power supply (V_{DDP}) is 3.3V, each I/O can be selectively configured at the 2.5V and 3.3V threshold levels¹. Table 1-3 shows the available supply voltage configurations (the PLL block uses an independent 2.5V supply on the AVDD and AGND pins). All I/Os include ESD protection circuits. Each I/O has been tested to 2000V to the human body model (per JESD22 (HBM)).

Table 1-3 • ProASIC^{PLUS} I/O Power Supply Voltages

	V_{DDP}	
	2.5V	3.3V
Input Compatibility	2.5V	3.3V, 2.5V
Output Drive	2.5V	3.3V, 2.5V ¹

Note: V_{DD} is always 2.5V.

1. Please refer to the mixed-mode interfacing section in the *I/O Features in ProASIC^{PLUS} Flash FPGAs* application note for details.

Six or seven standard I/O pads are grouped with a GND pad and either a V_{DD} (core power) or V_{DDP} (I/O power) pad. Two reference bias signals circle the chip. One protects the cascaded output drivers, while the other creates a virtual V_{DD} supply for the I/O ring.

I/O pads are fully configurable to provide the maximum flexibility and speed. Each pad can be configured as an input, an output, a tristate driver, or a bidirectional buffer (Figure 1-9 and Table 1-4).

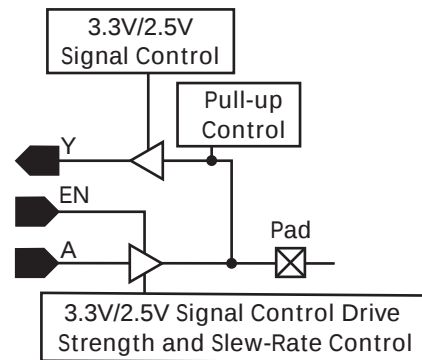


Figure 1-9 • I/O Block Schematic Representation

Table 1-4 • I/O Features

Function	Description
I/O pads configured as inputs	- Individually selectable 2.5V or 3.3V threshold levels - Optional pull-up resistor - Optionally configurable as Schmitt trigger input. The Schmitt trigger input option can be configured as an input only, not a bidirectional buffer. This input type may be slower than a standard input under certain conditions and has a typical hysteresis of 0.35V. I/O macros with an "S" in the standard I/O library have added Schmitt capabilities. 3.3V PCI Compliant
I/O pads configured as outputs	- Individually selectable 2.5V or 3.3V compliant output signals 2.5V – JEDEC JESD 8-5 3.3V – JEDEC JESD 8-A (LVTTTL and LVCMOS) 3.3V PCI compliant - Ability to drive LVTTTL and LVCMOS levels - Selectable drive strengths - Selectable slew rates - Tristate
I/O pads configured as bidirectional buffers	- Individually selectable 2.5V or 3.3V compliant output signals 2.5V – JEDEC JESD 8-5 3.3V – JEDEC JESD 8-A (LVTTTL and LVCMOS) 3.3V PCI compliant - Optional pull-up resistor - Selectable drive strengths - Selectable slew rates - Tristate

Power-Up Sequencing

While ProASIC^{PLUS} devices are live at power-up, the order of V_{DD} and V_{DDP} power-up is important during system start-up. V_{DD} should be powered up before (or coincident with) V_{DDP} on ProASIC^{PLUS} devices. Failure to follow these guidelines may result in undesirable pin behavior during system start-up. For more information, refer to Actel's [ProASIC^{PLUS} Family Devices Power-Up Behavior](#) application note.

LVPECL Input Pads

In addition to standard I/O pads and power pads, ProASIC^{PLUS} devices have a single LVPECL input pad on both the east and west sides of the device, along with AVDD and AGND pins to power the PLL block. The LVPECL pad cell consists of an input buffer (containing a

low voltage differential amplifier) and a signal and its complement, PPECL (I/P) (PECLN) and NPECL (PECLREF). The LVPECL input pad cell differs from the standard I/O cell in that it is operated from V_{DD} only.

Since it is exclusively an input, it requires no output signal, output enable signal, or output configuration bits. As a special high-speed differential input, it also does not require pull ups. Recommended termination for LVPECL inputs is shown in [Figure 1-10](#). The LVPECL pad cell compares voltages, as illustrated in [Figure 1-11](#), on the PPECL (I/P) pad and the NPECL pad and sends the results to the global MUX ([Figure 1-14 on page 1-13](#)). This high speed, low skew output essentially controls the clock conditioning circuit.

LVPECLs are designed to meet LVPECL JEDEC receiver standard levels ([Table 1-5](#)).

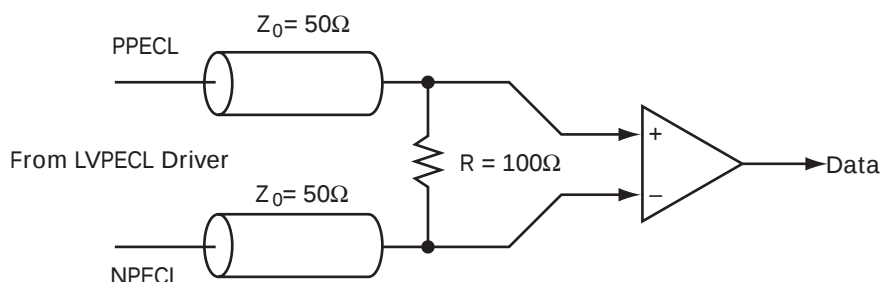


Figure 1-10 • Recommended Termination for LVPECL Inputs

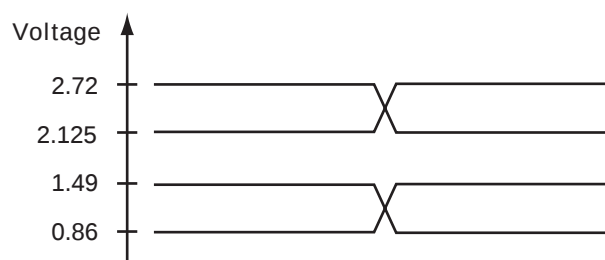


Figure 1-11 • LVPECL High and Low Threshold Values

Table 1-5 • LVPECL Receiver Specifications

Symbol	Parameter	Min.	Max	Units
V_{IH}	Input High Voltage	1.49	2.72	V
V_{IL}	Input Low Voltage	0.86	2.125	V
V_{ID}	Differential Input Voltage	0.3	V_{DD}	V

Boundary Scan (JTAG)

ProASIC^{PLUS} devices are compatible with IEEE Standard 1149.1, which defines a set of hardware architecture and mechanisms for cost-effective board-level testing. The basic ProASIC^{PLUS} boundary-scan logic circuit is composed of the TAP (test access port), TAP controller, test data registers, and instruction register (Figure 1-12). This circuit supports all mandatory IEEE 1149.1 instructions (EXTEST, SAMPLE/PRELOAD and BYPASS) and the optional IDCODE instruction (Table 1-6).

Each test section is accessed through the TAP, which has five associated pins: TCK (test clock input), TDI and TDO (test data input and output), TMS (test mode selector) and TRST (test reset input). TMS, TDI and TRST are equipped with pull-up resistors to ensure proper

operation when no input data is supplied to them. These pins are dedicated for boundary-scan test usage. Actel recommends that a nominal 20kΩ pull-up resistor is added to TDO and TCK pins.

The TAP controller is a four-bit state machine (16 states) that operates as shown in Figure 1-13 on page 1-11. The '1's and '0's represent the values that must be present at TMS at a rising edge of TCK for the given state transition to occur. IR and DR indicate that the instruction register or the data register is operating in that state.

ProASIC^{PLUS} devices have to be programmed at least once for complete boundary-scan functionality to be available. If boundary-scan functionality is required prior to partial programming, refer to online [technical support](#) on the Actel website and search for ProASIC^{PLUS} BSDL.

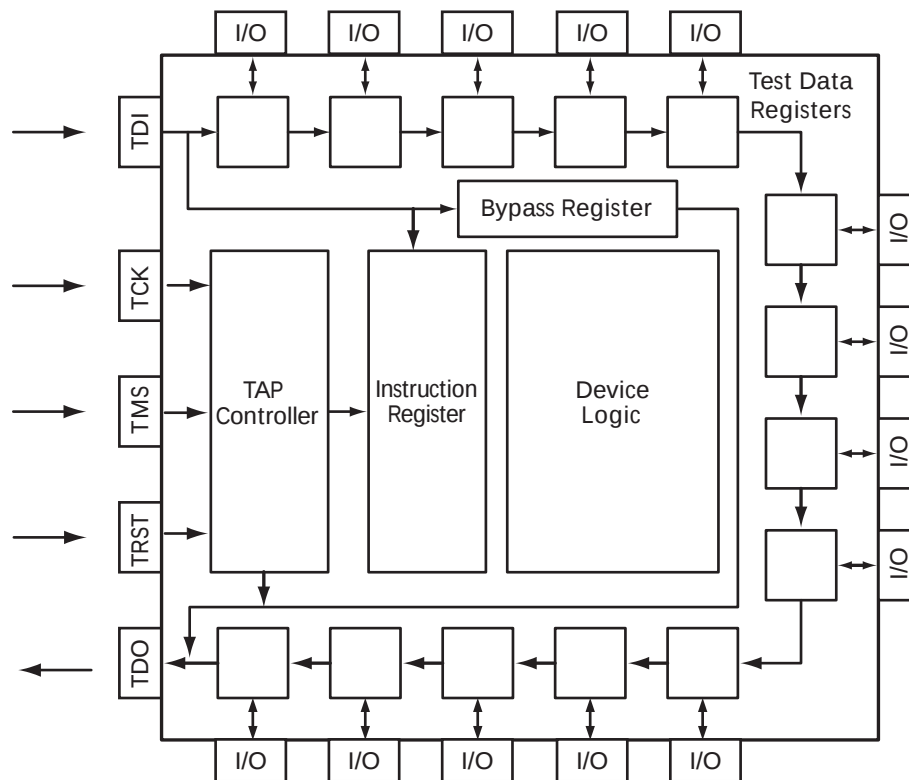


Figure 1-12 • ProASIC^{PLUS} JTAG Boundary Scan Test Logic Circuit

Table 1-6 • Boundary-Scan Opcodes

	Hex Opcode
EXTEST	00
SAMPLE/PRELOAD	01
IDCODE	0F
CLAMP	05
BYPASS	FF

The TAP controller receives two control inputs (TMS and TCK) and generates control and clock signals for the rest of the test logic architecture. On power-up, the TAP controller enters the Test-Logic-Reset state. To guarantee a reset of the controller from any of the possible states, TMS must remain high for five TCK cycles. The TRST pin may also be used to asynchronously place the TAP controller in the Test-Logic-Reset state.

ProASIC^{PLUS} devices support three types of test data registers: bypass, device identification, and boundary

scan. The bypass register is selected when no other register needs to be accessed in a device. This speeds up test data transfer to other devices in a test data path. The 32-bit device identification register is a shift register with four fields (lowest significant byte (LSB), ID number, part number and version). The boundary-scan register observes and controls the state of each I/O pin.

Each I/O cell has three boundary-scan register cells, each with a serial-in, serial-out, parallel-in, and parallel-out

pin. The serial pins are used to serially connect all the boundary-scan register cells in a device into a boundary-scan register chain, which starts at the TDI pin and ends at the TDO pin. The parallel ports are connected to the internal core logic tile and the input, output, and control ports of an I/O buffer to capture and load data into the register to control or observe the logic state of each I/O.

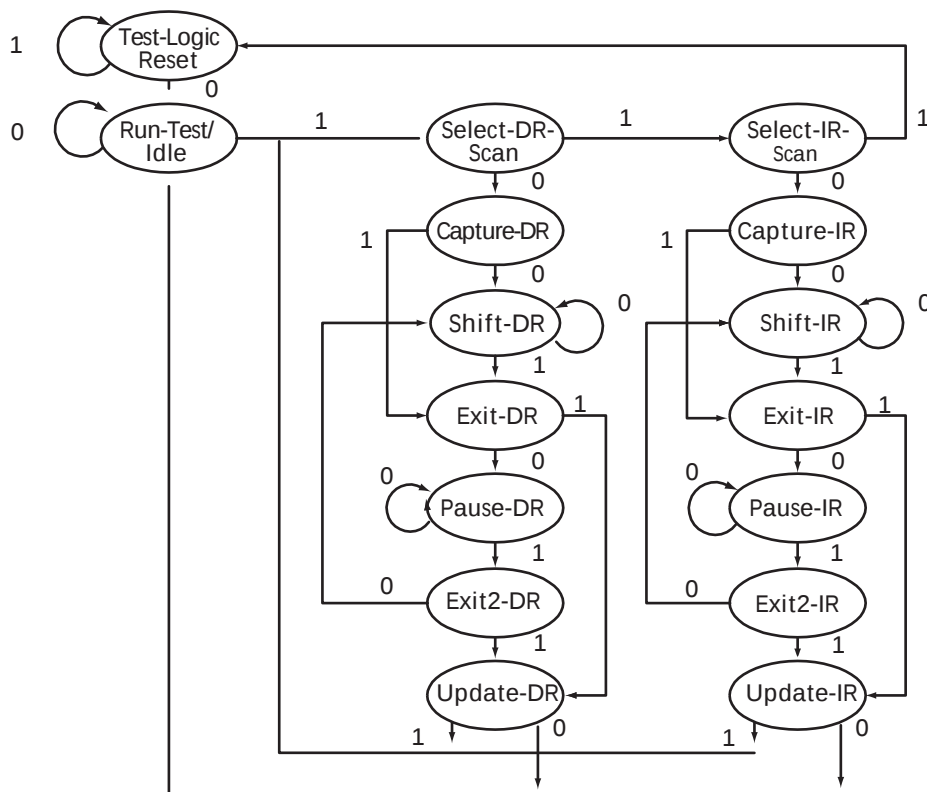


Figure 1-13 • TAP Controller State Diagram

Timing Control and Characteristics

ProASIC^{PLUS} Clock Management System

Introduction

ProASIC^{PLUS} devices provide designers with very flexible clock conditioning capabilities. Each member of the ProASIC^{PLUS} family contains two phase-locked loop (PLL) blocks which perform the following functions:

- Clock Phase Adjustment via Programmable Delay (250 ps steps from -8 ns to +8 ns)
- Clock Skew Minimization

- Clock Frequency Synthesis

Each PLL has the following key features:

- Input Frequency Range (f_{IN}) = 1.5 to 180 MHz
- Feedback Frequency Range (f_{VCO}) = 1.5 to 180 MHz
- Output Frequency Range (f_{OUT}) = 6 to 180 MHz
- Output Phase Shift = 0°, 90°, 180°, and 270°
- Output Duty Cycle = 50%
- Low Output Jitter (max at 25°C)
 - $f_{VCO} < 10$ MHz. Jitter $\pm 1\%$ or better

- $10 \text{ MHz} < f_{VCO} < 60 \text{ MHz}$. Jitter $\pm 2\%$ or better
- $f_{VCO} > 60 \text{ MHz}$. Jitter $\pm 1\%$ or better

Note: Jitter(ps) = Jitter(%)*(10/Frequency (MHz))

For Example:

Jitter in picoseconds at 1 MHz = $1(\%)*(10/1 \text{ (MHz)}) = 10\text{ps}$

- Maximum Acquisition Time = 80 μ s
- Low Power Consumption – 6.9 mW (max – analog supply) + 7.0 μ W/MHz (max – digital supply)

Physical Implementation

Each side of the chip contains a clock conditioning circuit based upon a 180 MHz PLL block (Figure 1-14 on page 1-13). Two global multiplexed lines extend along each side of the chip to provide bidirectional access to the PLL on that side (neither MUX can be connected to the opposite side's PLL). Each global line has optional LVPECL input pads (described below). The global lines may be driven by either the LVPECL global input pad or the outputs from the PLL block or both. Each global line can be driven by a different output from the PLL. Unused global pins can be configured as regular I/Os or left unconnected. They default to an input with pull-up. The two signals available to drive the global networks are as follows (Figure 1-15 on page 1-14, Table 1-7 on page 1-14, and Table 1-8 on page 1-15):

Global A (secondary clock)

- Output from Global MUX A
- Conditioned version of PLL output (f_{OUT}) – delayed or advanced
- Divided version of either of the above
- Further delayed version of either of the above (0.25 ns, 0.50 ns, or 4.00 ns delay)¹

Global B

- Output from Global MUX B
- Delayed or advanced version of f_{OUT}
- Divided version of either of the above
- Further delayed version of either of the above (0.25 ns, 0.50 ns, or 4.00 ns delay)¹

Functional Description

Each PLL block contains four programmable dividers as shown in Figure 1-14 on page 1-13. These allow frequency scaling of the input clock signal as follows:

- The n divider divides the input clock by integer factors from 1 to 32.

- The m divider in the feedback path allows multiplication of the input clock by integer factors ranging from 1 to 64.
- The two dividers together can implement any combination of multiplication and division resulting in a clock frequency between 24 and 180 MHz exiting the PLL core. This clock has a fixed 50% duty cycle.
- The output frequency of the PLL core is given by the following formula (f_{REF} is the reference clock frequency):

$$f_{OUT} = f_{REF} * m/n$$

- The third and fourth dividers (u and v) permit the signals applied to the global network to each be further divided by integer factors ranging from 1 to 4.

The implementations:

$$f_{GLB} = m/(n*u)$$

$$f_{GLA} = m/(n*v)$$

enable the user to define a wide range of frequency multipliers and divisors. The clock conditioning circuit can advance or delay the clock up to 8 ns (in increments of 0.25 ns) relative to the positive edge of the incoming reference clock. The system also allows for the selection of output frequency clock phases of 0°, 90°, 180°, and 270°.

Prior to the application of signals to the rib drivers, they pass through programmable delay units, one per global network. These units permit the delaying of global signals relative to other signals to assist in the control of input set-up times. Not all possible combinations of input and output modes can be used. The degrees of freedom available in the bidirectional global pad system and in the clock conditioning circuit have been restricted. This avoids unnecessary and unwieldy design kit and software work.

Lock Signal

An active-high Lock signal (added via the ACTgen PLL development tool) indicates that the PLL has locked to the incoming clock signal. Users can employ the Lock signal as a soft reset of the logic driven by GLB and/or GLA.

PLL Configuration Options

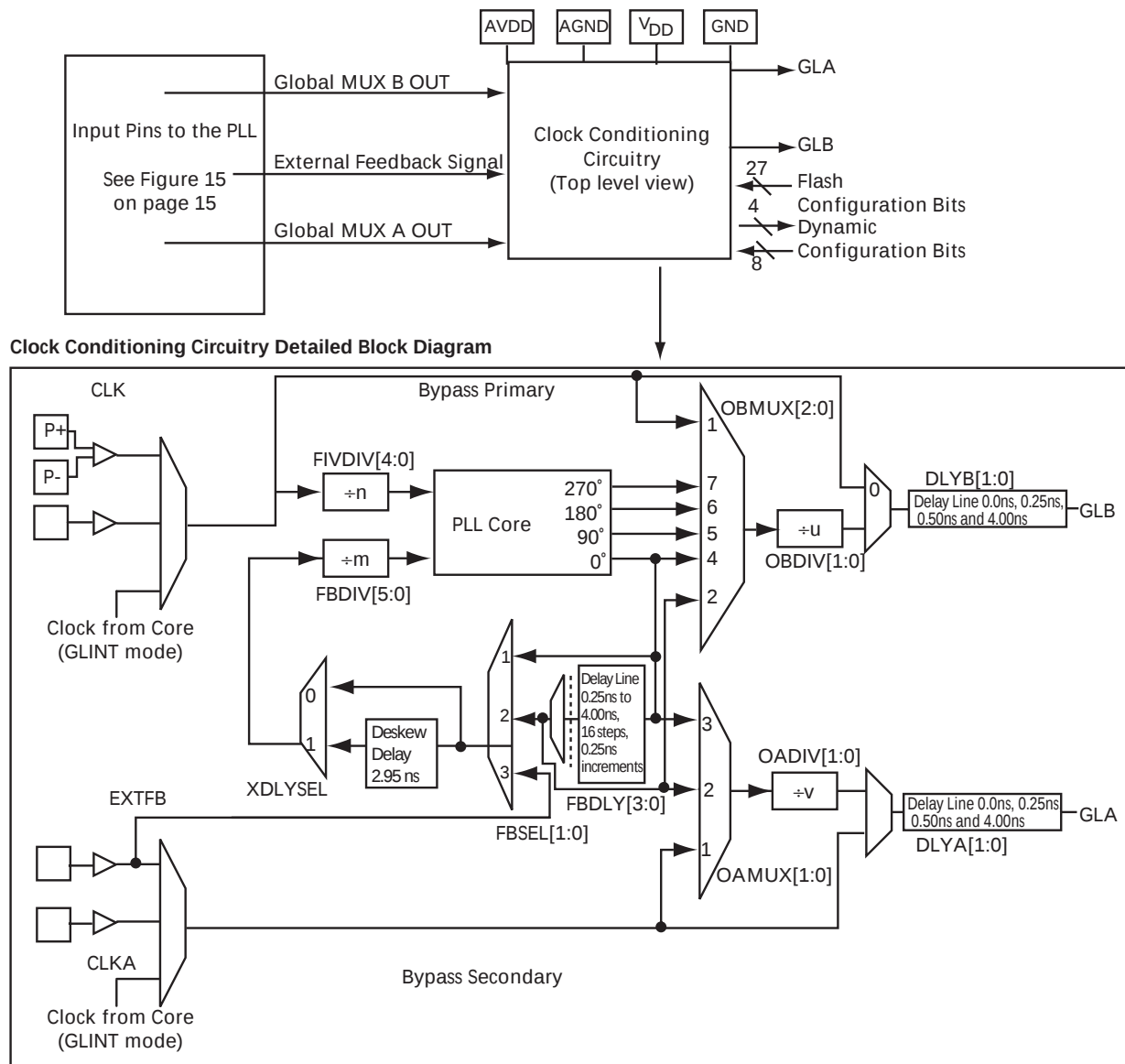
The PLL can be configured during design (via Flash-configuration bits set in the programming bitstream) or dynamically during device operation, thus eliminating the need for complete reprogramming. The dynamic configuration bits are loaded into a serial-in/parallel-out shift register provided in the clock conditioning circuit of

1. This mode is available through the delay feature of the Global MUX driver.

each PLL and then latched into the PLL block. The JTAG ports can be used along with a built-in user JTAG interface hardware to load the configuration shift register externally. Another option is internal dynamic configuration via user-designed hardware. Refer to

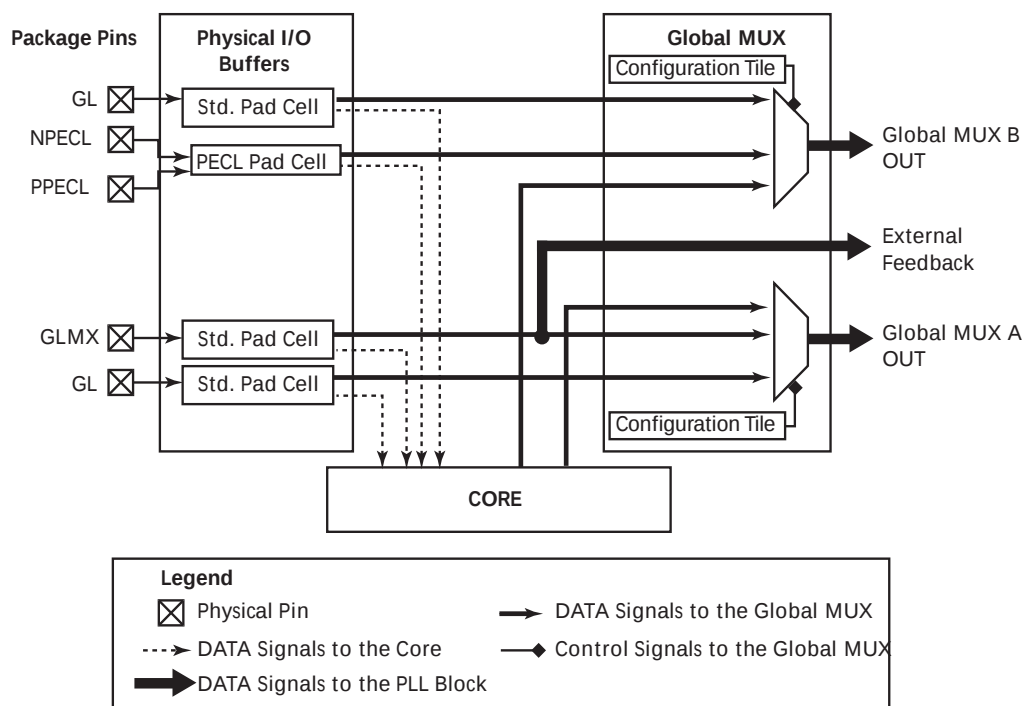
Actel's [ProASIC^{PLUS} PLL Dynamic Reconfiguration Using JTAG](#) application note for more information.

For information on the clock conditioning circuit, refer to Actel's [Using ProASIC^{PLUS} Clock Conditioning Circuits](#) application note..



1. FBDLY is a programmable delay line from 0 to 4 ns in 250 ps increments.
2. DLYA, DLYB, DLYAFB are programmable delay lines, each with selectable values 0, 250 ps, 500 ps, and 4 ns.
3. OBDIV will also divide the phase-shift since it takes place after the PLL Core.

Figure 1-14 • PLL Block – Top-Level View and Detailed PLL Block Diagram



Note: When a signal from an I/O tile is connected to the core, it cannot be connected to the Global MUX at the same time.

Figure 1-15 • Input Connectors to ProASIC^{PLUS} Clock Conditioning Circuitry

Table 1-7 • Clock-Conditioning Circuitry MUX Settings

MUX	Datapath	Comments
FBSEL		
1	Internal Feedback	
2	Internal Feedback and Advance Clock Using FBDLY	-0.25 to -4 ns in 0.25ns increments
3	External Feedback (EXTFB)	
XDLYSEL		
0	Feedback Unchanged	
1	Deskew feedback by advancing clock by system delay	Fixed delay of -2.95 ns
OBMUX		
	GLB	
0	Primary bypass, no divider	
1	Primary bypass, use divider	
2	Delay Clock Using FBDLY	+0.25 to +4 ns in 0.25ns increments
4	Phase Shift Clock by 0°	
5	Phase Shift Clock by +90°	
6	Phase Shift Clock by +180°	
7	Phase Shift Clock by +270°	
OAMUX		
	GLA	
0	Secondary bypass, no divider	
1	Secondary bypass, use divider	
2	Delay Clock Using FBDLY	+0.25 to +4 ns in 0.25ns increments
3	Phase Shift Clock by 0°	

Table 1-8 • Clock-Conditioning Circuitry Delay-Line Settings

Delay Line	Delay Value (ns)
DLYB	
0	0
1	+0.25
2	+0.50
3	+4.0
DLYA	
0	0
1	+0.25
2	+0.50
3	+4.0

Sample Implementations

Frequency Synthesis

Figure 1-16 on page 1-16 illustrates an example where the PLL is used to multiply a 33 MHz external clock up to 133 MHz. Figure 1-17 on page 1-16 uses two dividers to synthesize a 50 MHz output clock from a 40 MHz input reference clock. The input frequency of 40 MHz is multiplied by 5 and divided by 4, giving an output clock (GLB) frequency of 50 MHz. When dividers are used, a given ratio can be generated in multiple ways, allowing the user to stay within the operating frequency ranges of the PLL. For example, in this case the input divider could have been 2 and the output divider also 2, giving us a division of the input frequency by 4 to go with the feedback loop division (effective multiplication) by 5.

Adjustable Clock Delay

Figure 1-18 on page 1-17 illustrates the delay of the input clock by employing one of the adjustable delay lines. This is easily done in ProASIC^{PLUS} by bypassing the PLL core entirely and using the output delay line. Notice also that the output clock can be effectively advanced relative to the input clock by using the delay line in the feedback path. This is shown in Figure 1-19 on page 1-17.

Clock Skew Minimization

Figure 1-20 on page 1-18 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the "input" clock. The input clock is fed to the reference clock input of the PLL. The output clock (GLA) feeds a clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to Actel's [Using ProASIC^{PLUS} Clock Conditioning Circuits](#) application note for more information.

Logic Tile Timing Characteristics

Timing characteristics for ProASIC^{PLUS} devices fall into three categories: family dependent, device dependent, and design dependent. The input and output buffer characteristics are common to all ProASIC^{PLUS} family members. Internal routing delays are device dependent. Design dependency means that actual delays are not determined until after placement and routing of the user's design are complete. Delay values may then be determined by using the Timer utility or performing simulation with post-layout delays.

Critical Nets and Typical Nets

Propagation delays are expressed only for typical nets, which are used for initial design performance evaluation. Critical net delays can then be applied to the most timing critical paths. Critical nets are determined by net property assignment prior to placement and routing. Refer to the Actel [Designer User's Guide](#) or online help for details on using constraints.

Timing Derating

Since ProASIC^{PLUS} devices are manufactured with a CMOS process, device performance will vary with temperature, voltage, and process. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and optimal process variations. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case process variations (within process specifications).

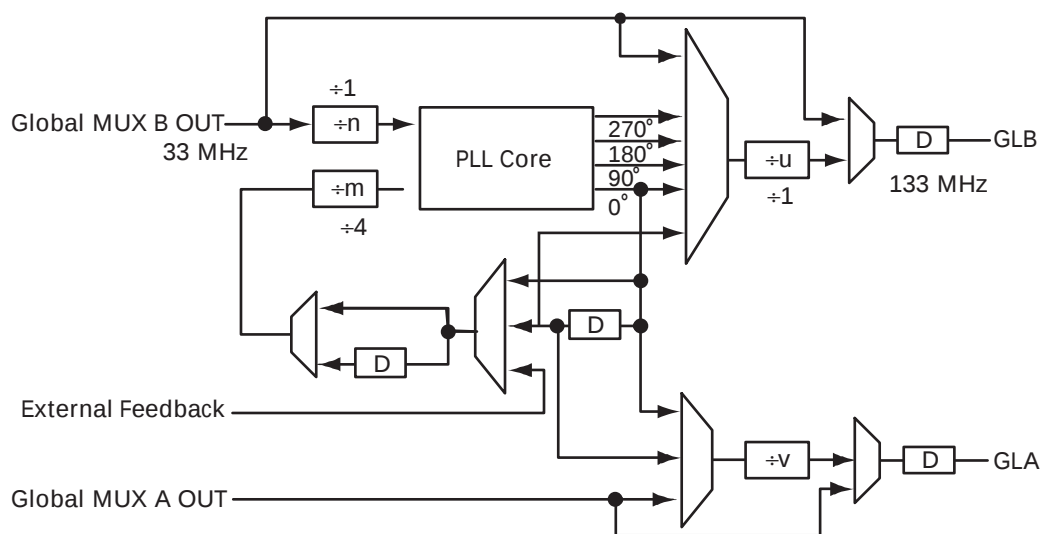


Figure 1-16 • Using the PLL 33 MHz In, 133 MHz Out

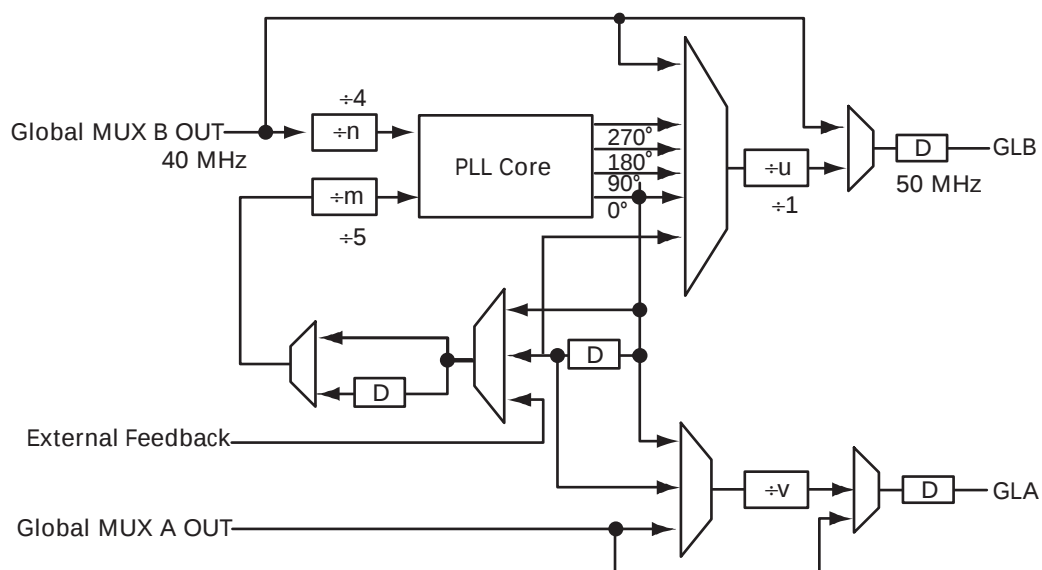


Figure 1-17 • Using the PLL 40 MHz In, 50 MHz Out

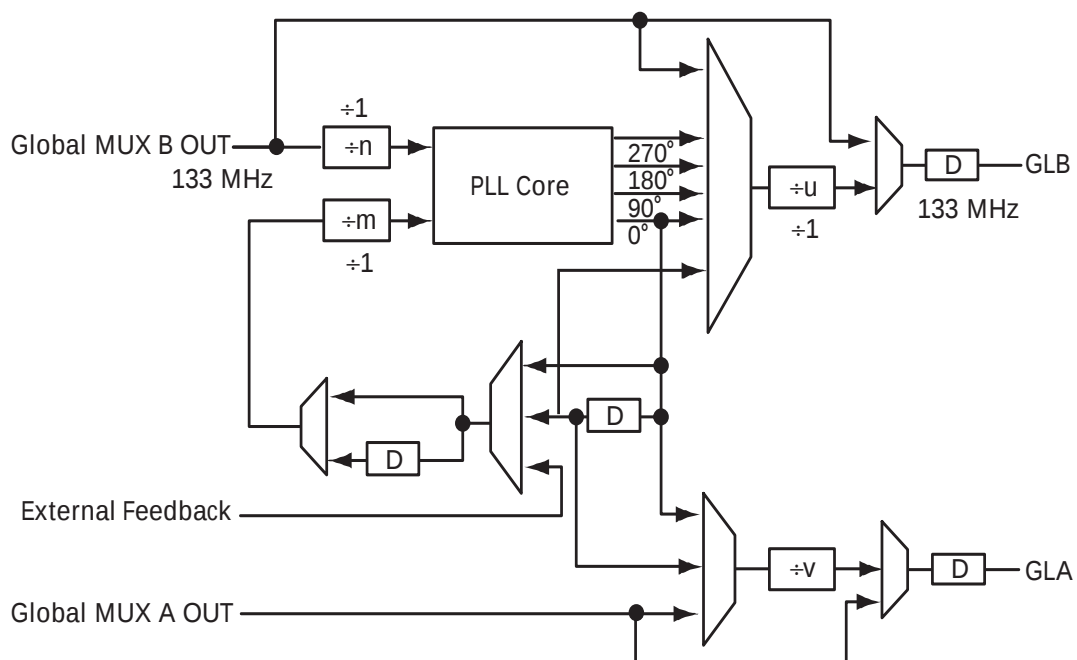


Figure 1-18 • Using the PLL to Delay the Input Clock

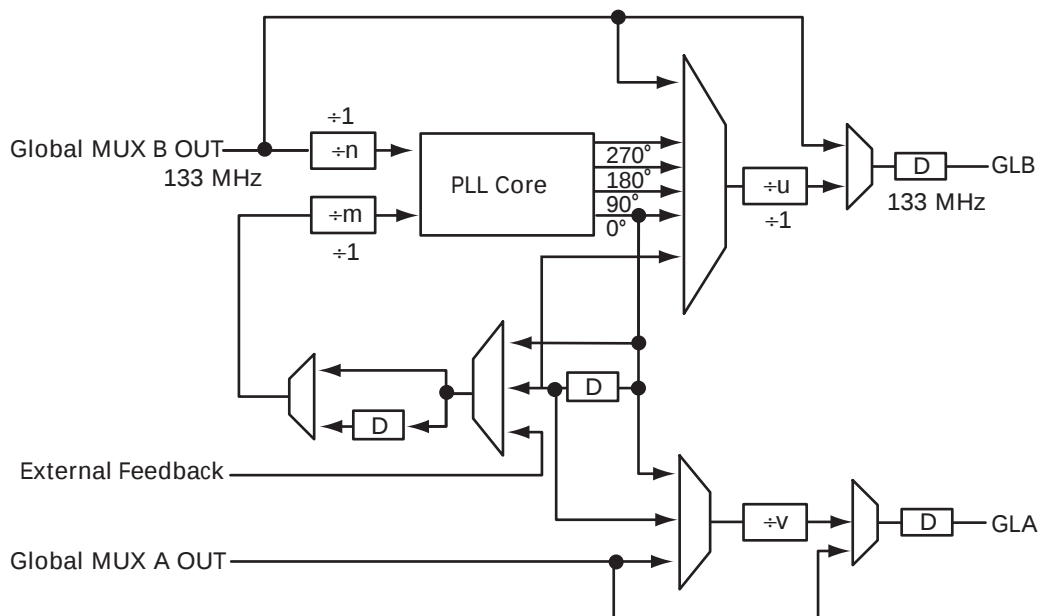
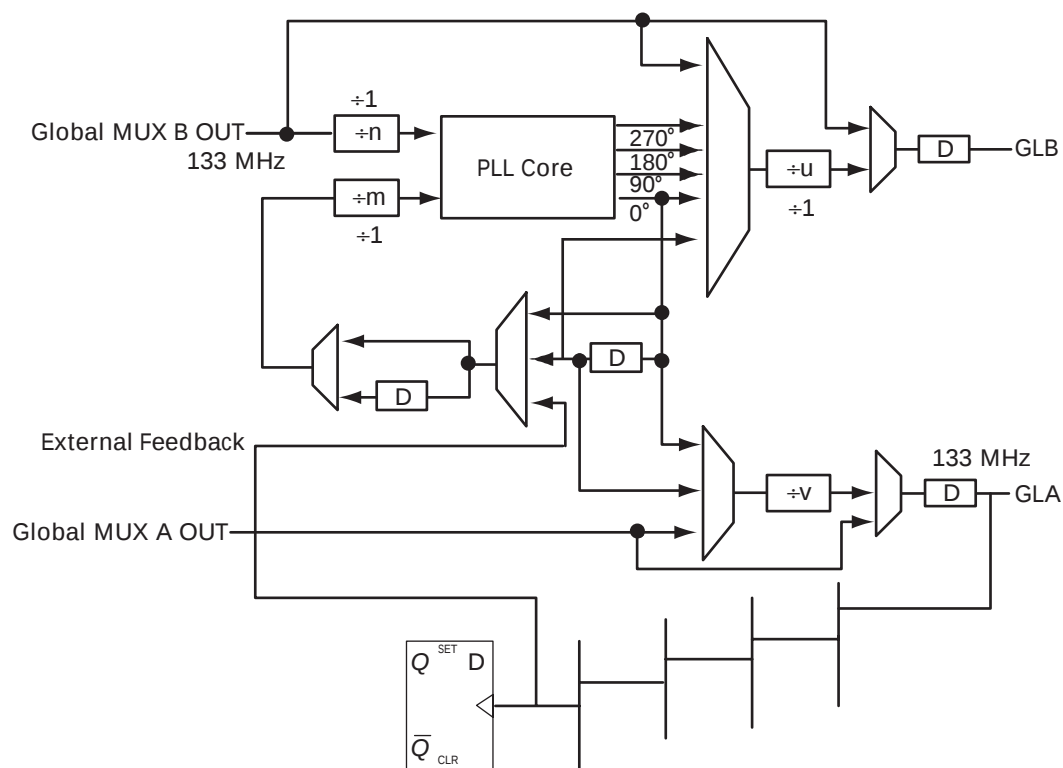


Figure 1-19 • Using the PLL to "Advance" the Input Clock



PLL Electrical Specifications

Parameter	Value	Notes
Frequency Ranges		
Reference Frequency f _{IN} (min.)	1.5 MHz	Clock conditioning circuitry (min.) lowest input frequency
Reference Frequency f _{IN} (max.)	180 MHz	Clock conditioning circuitry (max.) highest input frequency
OSC Frequency f _{VCO} (min.)	24 MHz	Lowest output frequency voltage controlled oscillator
OSC Frequency f _{VCO} (max.)	180 MHz	Highest output frequency voltage controlled oscillator
Clock Conditioning Circuitry f _{OUT} (min.)	6 MHz	Lowest output frequency clock conditioning circuitry
Clock Conditioning Circuitry f _{OUT} (max.)	180 MHz	Highest output frequency clock conditioning circuitry
Long Term Jitter Peak-to-Peak Max.*		
Temperature	Frequency MHz	
25°C (or higher)	f _{VCO} <10	Jitter(ps) = Jitter(%)*(10/Frequency (MHz)) For Example: Jitter in picoseconds at 1 MHz = 1(%)*(10/1 (MHz)) = 10ps
	10<f _{VCO} <60	
	f _{VCO} >60	
0°C	±1% ±2% ±1%	
–40°C	±1.5% ±2.5% ±1%	
Acquisition Time from Cold Start		
Acquisition Time (max.)	30 μs	f _{VCO} ≤ 40 MHz
Acquisition Time (max.)	80 μs	f _{VCO} > 40 MHz
Power Consumption		
Analog Supply Power (max*)	6.9 mW	
Digital Supply Current (max)	7 μW/MHz	
Duty Cycle	50% ±0.5%	

Note: *High clock frequencies (>60 MHz)

User Security

ProASIC^{PLUS} devices have FlashLock protection bits that, once programmed, block the entire programmed contents from being read externally. If locked, the user can only reprogram the device employing the user-defined security key. This protects the device from being read back and duplicated. Since programmed data is stored in nonvolatile memory cells (which are actually very small capacitors), rather than in the wiring, physical deconstruction cannot be used to compromise data. This approach is further hampered by the placement of the memory cells beneath the four metal layers (whose removal cannot be accomplished without disturbing the charge in the capacitor). This is the highest security provided in the industry. For more information, refer to

Actel's *Design Security in Nonvolatile Flash and Antifuse FPGAs* white paper.

Embedded Memory Floorplan

The embedded memory is located across the top and bottom of the device in 256x9 blocks (Figure 1-1 on page 1-2). Depending upon the device, up to 88 blocks are available to support a variety of memory configurations. Each block can be programmed as an independent memory or combined (using dedicated memory routing resources) to form larger, more complex memories. A single memory configuration could include blocks from both the top and bottom memory locations.

Embedded Memory Configurations

The embedded memory in the ProASIC^{PLUS} family provides great configuration flexibility (Table 1-9 on page 1-20). Unlike many other programmable vendors each ProASIC^{PLUS} block is designed and optimized as a two-port memory (1 read, 1 write). This provides 198kbits of total memory for two-port and single port usage in the APA1000 device.

Each memory can be configured as FIFO or SRAM, with independent selection of synchronous or asynchronous read and write ports (Table 1-10). Additional characteristics include programmable flags as well as parity checking and generation. Figure 1-21 on page 1-21 and Figure 1-22 on page 1-22 show the block diagrams of the basic SRAM and FIFO blocks. Table 1-11 on page 1-22 and Table 1-12 on page 1-23 describe memory block SRAM and FIFO interface signals, respectively. A single memory is designed to operate at up to 150 MHz (standard speed grade typical conditions).

Each block contains a 256 word, 9-bit wide (1 read port, 1 write port) memory. The memory blocks may be combined in parallel to form wider memories or stacked to form deeper memories (Figure 1-23 on page 1-23). This provides optimal bit widths of 9 (1 block), 18, 36, and 72, and optimal depths of 256, 512, 768, and 1,024. Refer to Actel's *A Guide to ACTgen Macros* for more information.

Figure 1-24 on page 1-24 gives an example of optimal memory usage. Ten blocks with 23,040 bits have been used to generate three memories of various widths and depths. Figure 1-25 on page 1-24 shows how memory can be used in parallel to create extra read ports. In this example, using only 10 of the 88 available blocks of the APA1000 yields an effective 6,912 bits of multiple port memories. The Actel ACTgen software facilitates building wider and deeper memories for optimal memory usage.

Table 1-9 • ProASIC^{PLUS} Memory Configurations by Device

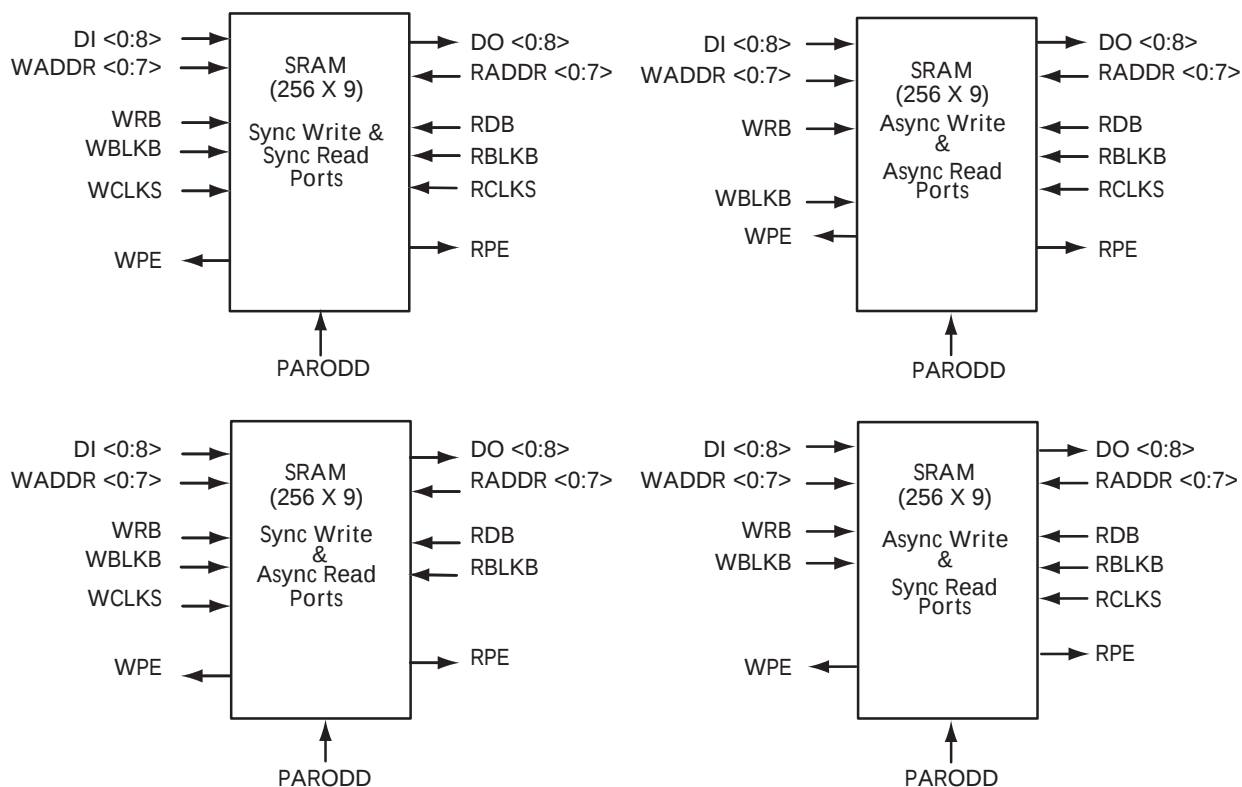
Device	Bottom	Top	Maximum Width		Maximum Depth	
			D	W	D	W
APA075	0	12	256	108	1,536	9
APA150	0	16	256	144	2,048	9
APA300	16	16	256	144	2,048	9
APA450	24	24	256	216	3,072	9
APA600	28	28	256	252	3,584	9
APA750	32	32	256	288	4,096	9
APA1000	44	44	256	396	5,632	9

Table 1-10 • Basic Memory Configurations

Type	Write Access	Read Access	Parity	Library Cell Name
RAM	Asynchronous	Asynchronous	Checked	RAM256x9AA
RAM	Asynchronous	Asynchronous	Generated	RAM256x9AAP
RAM	Asynchronous	Synchronous Transparent	Checked	RAM256x9AST
RAM	Asynchronous	Synchronous Transparent	Generated	RAM256x9ASTP
RAM	Asynchronous	Synchronous Pipelined	Checked	RAM256x9ASR
RAM	Asynchronous	Synchronous Pipelined	Generated	RAM256x9ASRP
RAM	Synchronous	Asynchronous	Checked	RAM256x9SA
RAM	Synchronous	Asynchronous	Generated	RAM256xSAP
RAM	Synchronous	Synchronous Transparent	Checked	RAM256x9SST
RAM	Synchronous	Synchronous Transparent	Generated	RAM256x9SSTP
RAM	Synchronous	Synchronous Pipelined	Checked	RAM256x9SSR
RAM	Synchronous	Synchronous Pipelined	Generated	RAM256x9SSRP
FIFO	Asynchronous	Asynchronous	Checked	FIFO256x9AA

Table 1-10 • Basic Memory Configurations (Continued)

Type	Write Access	Read Access	Parity	Library Cell Name
FIFO	Asynchronous	Asynchronous	Generated	FIFO256x9AAP
FIFO	Asynchronous	Synchronous Transparent	Checked	FIFO256x9AST
FIFO	Asynchronous	Synchronous Transparent	Generated	FIFO256x9ASTP
FIFO	Asynchronous	Synchronous Pipelined	Checked	FIFO256x9ASR
FIFO	Asynchronous	Synchronous Pipelined	Generated	FIFO256x9ASRP
FIFO	Synchronous	Asynchronous	Checked	FIFO256x9SA
FIFO	Synchronous	Asynchronous	Generated	FIFO256x9SAP
FIFO	Synchronous	Synchronous Transparent	Checked	FIFO256x9SST
FIFO	Synchronous	Synchronous Transparent	Generated	FIFO256x9SSTP
FIFO	Synchronous	Synchronous Pipelined	Checked	FIFO256x9SSR
FIFO	Synchronous	Synchronous Pipelined	Generated	FIFO256x9SSRP



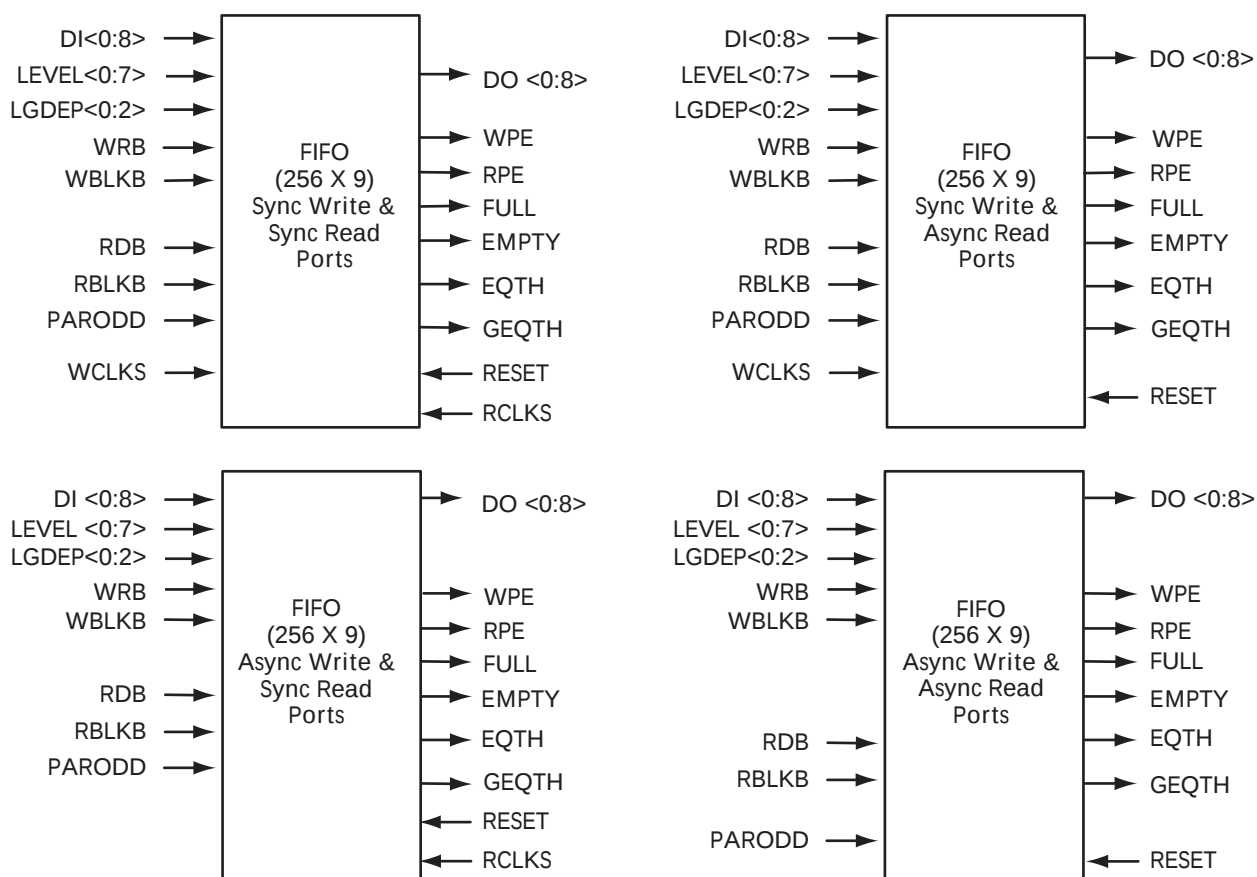
Note: To save area while using embedded memories, the memory blocks contain multiplexers (called DMUX) for each output signal. These DMUX cells do not consume any core logic tiles and connect directly to high speed routing resources between the memory blocks. They are used when memories are cascaded and are automatically inserted by the software tools.

Figure 1-21 • Example SRAM Block Diagrams

Table 1-11 • Memory Block SRAM Interface Signals

SRAM Signal	Bits	In/Out	Description
WCLKS	1	IN	Write clock used on synchronization on write side
RCLKS	1	IN	Read clock used on synchronization on read side
RADDR<0:7>	8	IN	Read address
RBLKB	1	IN	Read block select (active LOW)
RDB	1	IN	Read pulse (active LOW)
WADDR<0:7>	8	IN	Write address
WBLKB	1	IN	Write block select (active LOW)
DI<0:8>	9	IN	Input data bits <0:8>, <8> can be used for parity in
WRB	1	IN	Write pulse (active LOW)
DO<0:8>	9	OUT	Output data bits <0:8>, <8> can be used for parity out
RPE	1	OUT	Read parity error (active HIGH)
WPE	1	OUT	Write parity error (active HIGH)
PARODD	1	IN	Selects odd parity generation/detect when high, even when low

Note: Not all signals shown are used in all modes.



Note: To save area while using embedded memories, the memory blocks contain multiplexers (called DMUX) for each output signal. These DMUX cells do not consume any core logic tiles and connect directly to high speed routing resources between the memory blocks. They are used when memories are cascaded and are automatically inserted by the software tools.

Figure 1-22 • Basic FIFO Block Diagrams

Table 1-12 • Memory Block FIFO Interface Signals

FIFO Signal	Bits	In/Out	Description
WCLKS	1	IN	Write clock used for synchronization on write side
RCLKS	1	IN	Read clock used for synchronization on read side
LEVEL <0:7>	8	IN	Direct configuration implements static flag logic
RBLKB	1	IN	Read block select (active LOW)
RDB	1	IN	Read pulse (active LOW)
RESET	1	IN	Reset for FIFO pointers (active LOW)
WBLKB	1	IN	Write block select (active LOW)
DI<0:8>	9	IN	Input data bits <0:8>, <8> will be generated if PARGEN is true
WRB	1	IN	Write pulse (active LOW)
FULL, EMPTY	2	OUT	FIFO flags. FULL prevents write and EMPTY prevents read
EQTH, GEQTH	2	OUT	EQTH is true when the FIFO holds the number of words specified by the LEVEL signal. GEQTH is true when the FIFO holds (LEVEL) words or more
DO<0:8>	9	OUT	Output data bits <0:8>
RPE	1	OUT	Read parity error (active HIGH)
WPE	1	OUT	Write parity error (active HIGH)
LGDEP <0:2>	3	IN	Configures DEPTH of the FIFO to 2 ^(LGDEP+1)
PARODD	1	IN	Parity generation/detect – Even when low, odd when high

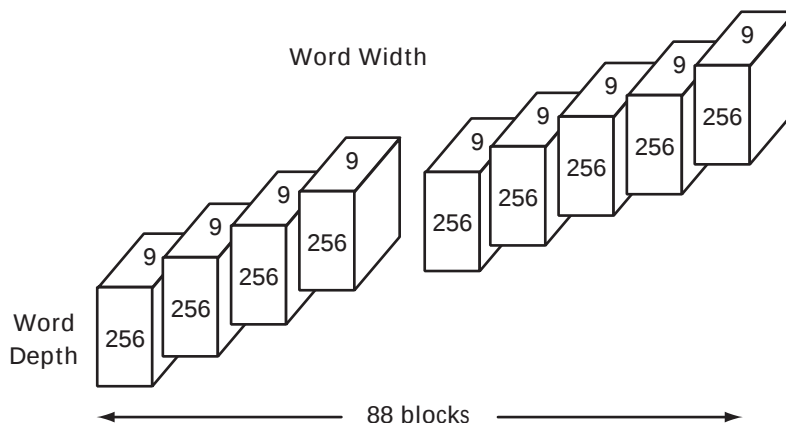
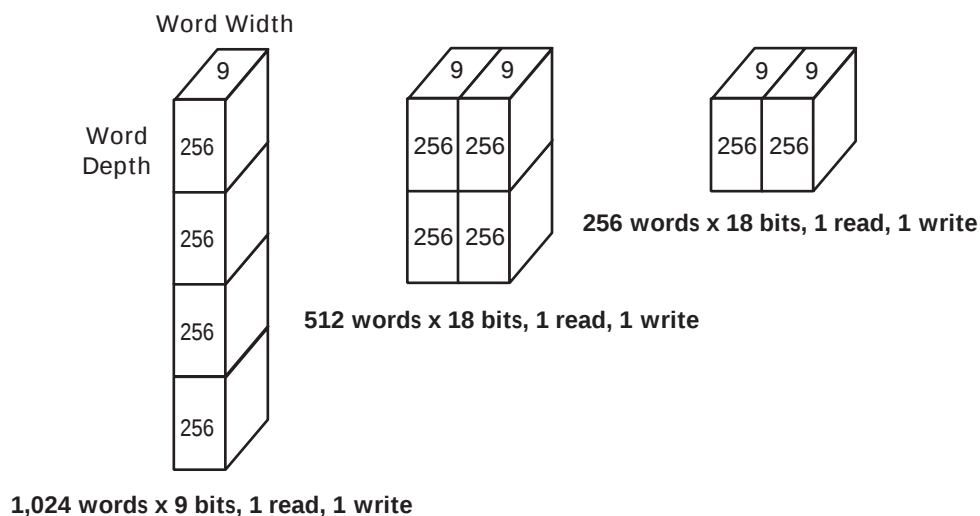


Figure 1-23 • APA1000 Memory Block Architecture



Total Memory Blocks Used = 10
Total Memory Bits = 23,040

Figure 1-24 • Example Showing Memories with Different Widths and Depths

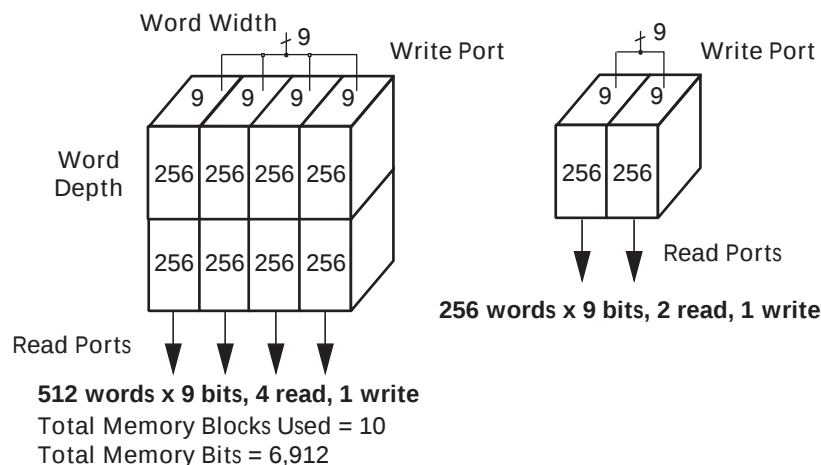


Figure 1-25 • Multiport Memory Usage

Design Environment

The ProASICPLUS family of FPGAs is fully supported by both Actel's Libero™ Integrated Design Environment (IDE) and Actel's Designer FPGA Development Software. Actel's Designer software provides a comprehensive suite of backend development tools for FPGA development. The Designer software includes timing-driven place-and-route, a world-class integrated static timing analyzer and constraints editor, a design netlist schematic viewer, and SmartPower, a tool that allows the user to quickly estimate the power consumption in a design.

Libero IDE provides an integrated design manager that seamlessly integrates design tools while guiding the user through the design flow, managing all design and log files, and passing necessary design data among tools (Figure 1-26 on page 1-25). Libero IDE includes Synplicity® Synplify AE for Actel, Mentor Graphics™ ViewDraw AE for Actel, Actel's own Designer software, Model Technology™ ModelSim AE HDL Simulator, and SynapticAD™ WaveFormer Lite AE.

ISP

The user can generate *.bit or *.stp programming files from the Designer software and can use these files to program a device.

ProASIC^{PLUS} devices can be programmed in system. For more information on ISP of ProASIC^{PLUS} devices, refer to

the *In-System Programming ProASIC^{PLUS} Devices* and *Performing Internal In-System Programming Using Actel's ProASIC^{PLUS} Devices* application notes. Prior to being programmed for the first time, the ProASIC^{PLUS} device I/Os are inputs with pull-ups.

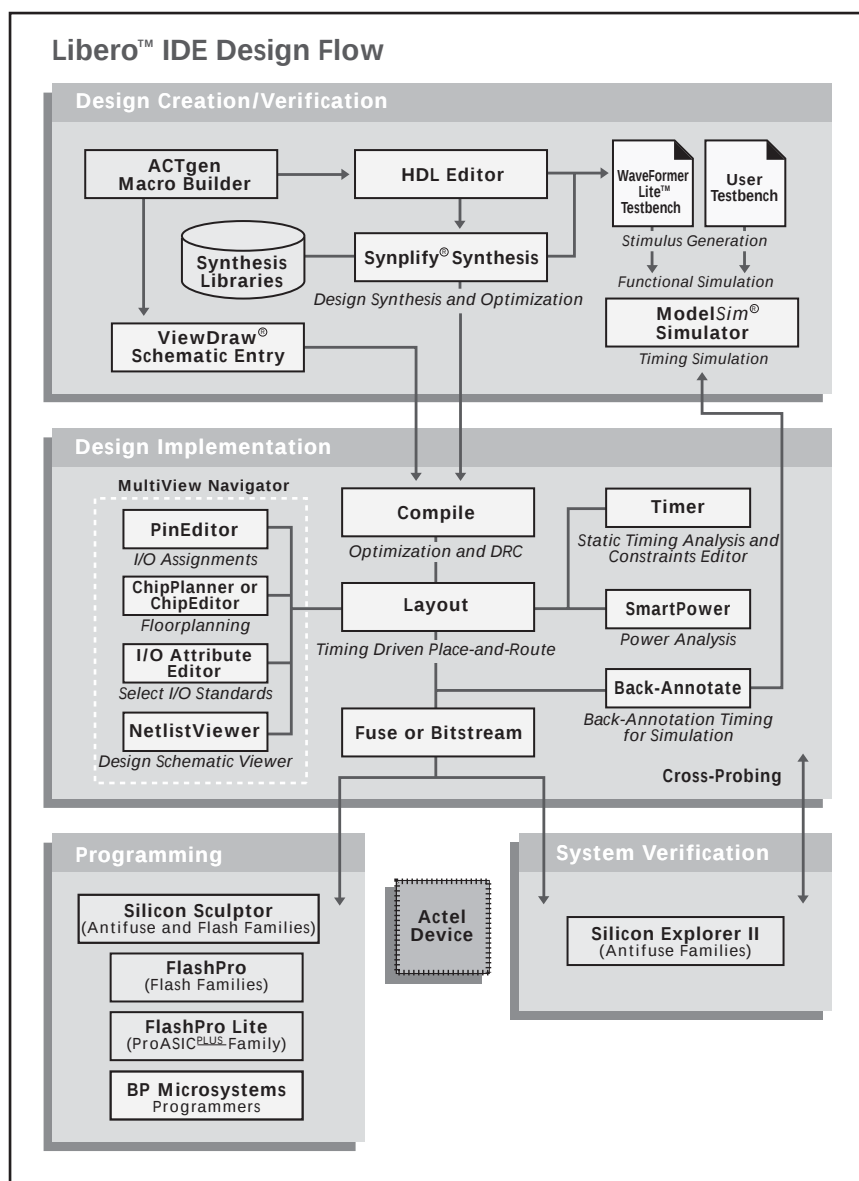


Figure 1-26 • Design Flow

Related Documents

Application Notes

Efficient Use of ProASIC Clock Trees

<http://www.actel.com/documents/clocktree.pdf>

I/O Features in ProASIC^{PLUS} Flash FPGAs

<http://www.actel.com/documents/PAPLUSLVPECL.pdf>

ProASIC^{PLUS} Family Devices Power-Up Behavior

http://www.actel.com/documents/PAPLUS_PowerUp.pdf

ProASIC^{PLUS} PLL Dynamic Reconfiguration Using JTAG

<http://www.actel.com/documents/PAPLUSPLLdynamicAN.pdf>

Using ProASIC^{PLUS} Clock Conditioning Circuits

<http://www.actel.com/documents/PAPLUSPLLan.pdf>

In-System Programming ProASIC^{PLUS} Devices

http://www.actel.com/documents/External_ISP_AN.pdf

Performing Internal In-System Programming Using Actel's ProASIC^{PLUS} Devices

<http://www.actel.com/documents/PAPlusISPAN.pdf>

White Paper

Design Security in Nonvolatile Flash and Antifuse FPGAs

<http://www.actel.com/documents/DesignSecurity.pdf>

User's Guide

Designer User's Guide

<http://www.actel.com/documents/designerUG.pdf>

Flash Macro Library Guide

http://www.actel.com/documents/PA_libguide.pdf

Package Thermal Characteristics

The ProASIC^{PLUS} family is available in several package types with a range of pin counts. Actel has selected packages based on high pin count, reliability factors, and superior thermal characteristics.

Thermal resistance defines the ability of a package to conduct heat away from the silicon, through the package to the surrounding air. Junction-to-ambient thermal resistance is measured in degrees Celsius/Watt and is represented as Theta ja (Θ_{ja}). The lower the thermal resistance, the more efficiently a package will dissipate heat.

A package's maximum allowed power (P) is a function of maximum junction temperature (T_J), maximum ambient operating temperature (T_A), and junction-to-ambient thermal resistance Θ_{ja} . Maximum junction temperature is the maximum allowable temperature on the active surface of the IC and is 110° C. P is defined as:

$$P = \frac{T_J - T_A}{\Theta_{ja}}$$

Θ_{ja} is a function of the rate (in linear feet per minute – lfm) of airflow in contact with the package. When the estimated power consumption exceeds the maximum allowed power, other means of cooling, such as increasing the airflow rate, must be used.

Table 1-13 • Package Thermal Characteristics

Package Type	Pin Count	Θ_{jc}	Θ_{ja} Still Air	Θ_{ja} 300 ft./min.	Units
Thin Quad Flat Pack (TQFP)	100	12	37.5	30	°C/W
Thin Quad Flat Pack (TQFP)	144	11	32	24	°C/W
Plastic Quad Flat Pack (PQFP)	208	8	30	23	°C/W
PQFP with Heatspreader	208	3.8	20	17	°C/W
Plastic Ball Grid Array (PBGA)	456	3	15.6	12	°C/W
Fine Pitch Ball Grid Array (FBGA)	144	3.8	38.8	26.7	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.8	25	22	°C/W
Fine Pitch Ball Grid Array (FBGA) ¹	484	3.2	20	15	°C/W
Fine Pitch Ball Grid Array (FBGA) ²	484	3.2	20.5	16.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	11.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.3	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12	8.9	°C/W

Notes:

1. Depopulated Array
2. Full Array

Calculating Typical Power Dissipation

ProASIC^{PLUS} device power is calculated with both a static and an active component. The active component is a function of both the number of tiles utilized and the system speed. Power dissipation can be calculated using the following formula:

$$P_{\text{total}} = P_{\text{dc}} + P_{\text{ac}}$$

where:

- $P_{\text{dc}} = 12.5 \text{ mW}$ (Typically $2.5\text{V} \times 5\text{mA}$)

P_{dc} includes the static components of:

$$P_{\text{VDDP}} + P_{\text{VDD}} + P_{\text{AVDD}}$$

- $P_{\text{ac}} = P_{\text{clock}} + P_{\text{storage}} + P_{\text{logic}} + P_{\text{inputs}} + P_{\text{outputs}} + P_{\text{memory}} + P_{\text{pll}}$

P_{clock} , the clock component of power dissipation, is given by

$$P_{\text{clock}} = (P1 + P2 * R - P7 * R^2) * F_s$$

where:

- $P1 = 100 \text{ } \mu\text{W/MHz}$ is the basic power consumption of the clock tree per MHz of the clock
- $P2 = 1.3 \text{ } \mu\text{W/MHz}$ is the incremental power consumption of the clock tree per storage tile – also per MHz of the clock
- $P7 = 0.00003 \text{ } \mu\text{W/MHz}$ is a correction factor for highly loaded clock-trees
- $R =$ the number of storage tiles clocked by this clock
- $F_s =$ the clock frequency

P_{storage} , the storage-tile (Register) component of AC power dissipation, is given by

$$P_{\text{storage}} = P5 * m_s * F_s$$

where:

- $P5 = 1.1 \text{ } \mu\text{W/MHz}$ is the average power consumption of a storage-tile per MHz of its output toggling rate. The maximum output toggling rate is $F_s/2$
- $m_s =$ the number of storage tiles (Register) switching during each F_s cycle
- $F_s =$ the clock frequency

P_{logic} , the logic-tile component of AC power dissipation, is given by

$$P_{\text{logic}} = P3 * m_c * F_s$$

where:

- $P3 = 1.4 \text{ } \mu\text{W/MHz}$, is the average power consumption of a logic tile per MHz of its output toggling rate. The maximum output toggling rate is $F_s/2$
- $m_c =$ the number of logic tiles switching during each F_s cycle
- $F_s =$ the clock frequency

P_{outputs} , the I/O component of AC power dissipation, is given by

$$P_{\text{outputs}} = (P4 + (C_{\text{load}} * V_{\text{DDP}}^2)) * p * F_p$$

where:

- $P4 = 326 \text{ } \mu\text{W/MHz}$ is the intrinsic power consumption of an output pad normalized per MHz of the output frequency. This is the total I/O current $V_{\text{DD}} + V_{\text{DDP}}$
- C_{td} = the output load
- $p =$ the number of outputs
- $F_p =$ the average output frequency

The input's component of AC power dissipation is given by

$$P_{\text{inputs}} = P8 * q * F_q$$

where:

- $P8 = 29 \text{ } \mu\text{W/MHz}$ is the intrinsic power consumption of an input pad normalized per MHz of the input frequency
- $q =$ the number of inputs
- $F_q =$ the average input frequency

$$P_{\text{pll}} = P9 * N_{\text{pll}}$$

where:

- $P9 = 7.5 \text{ mW}$. This value has been estimated at maximum PLL clock frequency
- $N_{\text{pll}} =$ number of PLLs used

Finally, P_{memory} , the memory component of AC power consumption, is given by

$$P_{\text{memory}} = P6 * N_{\text{memory}} * F_{\text{memory}} * E_{\text{memory}}$$

where:

- $P6 = 175 \text{ } \mu\text{W/MHz}$ is the average power consumption of a memory block per MHz of the clock
- $N_{\text{memory}} =$ the number of RAM/FIFO blocks (1 block = 256 words * 9 bits)

- F_{memory} = the clock frequency of the memory
- E_{memory} = the average number of active blocks divided by the total number of blocks (N) of the memory.
 - Typical values for E_{memory} would be 1/4 for a 1k x 8,9,16, 32 memory and 1/16 for a 4kx8, 9, 16, and 32 memory
 - In addition, an application-dependent component to E_{memory} can be considered. For example, for a 1kx8 memory using only 1 cycle out of 3, $E_{\text{memory}} = 1/4 * 1/3 = 1/12$

The following is an APA750 example using a shift register design with 13,440 storage tiles (Register) and 0 logic tiles. This design has one clock at 10 MHz, and 24 outputs toggling at 5 MHz. We then calculate the various components as follows:

P_{clock}

- $sF = 10 \text{ MHz}$
- $R = 13,440$

$$\Rightarrow P_{\text{clock}} = (P1 + P2 * R - P7 * R^2) * Fs = 124.2 \text{ mW}$$

P_{storage}

- $ms = 13,440$ (in a shift register 100% of storage-tiles are toggling at each clock cycle and $Fs = 10 \text{ MHz}$)

$$\Rightarrow P_{\text{storage}} = P5 * ms * Fs = 147.8 \text{ mW}$$

P_{logic}

- $m = 0$ (no logic tile in this shift-register)

$$\Rightarrow P_{\text{logic}} = 0 \text{ mW}$$

P_{outputs}

- $C_{\text{load}} = 40 \text{ pF}$
- $V_{\text{DDP}} = 3.3 \text{ V}$
- $p = 24$
- $Fp = 5 \text{ MHz}$

$$\Rightarrow P_{\text{outputs}} = (P4 + C_{\text{load}} * V_{\text{DDP}}^2) * p * Fp = 87.3 \text{ mW}$$

P_{inputs}

- $q = 1$
- $Fq = 10 \text{ MHz}$

$$\Rightarrow P_{\text{inputs}} = P8 * q * Fq = 0.3 \text{ mW}$$

P_{memory}

$$N_{\text{memory}} = 0 \text{ (no RAM/FIFO in this shift-register)}$$

$$\Rightarrow P_{\text{memory}} = 0 \text{ mW}$$

P_{ac}

$$\Rightarrow 360 \text{ mW}$$

P_{total}

$$P_{\text{dc}} + P_{\text{ac}} = 372 \text{ mW (Typical)}$$

Operating Conditions

Standard and –F parts are the same unless otherwise noted. –F parts are only available as commercial.

Table 1-14 • Absolute Maximum Ratings*

Parameter	Condition	Minimum	Maximum	Units
Supply Voltage Core (V_{DD})		–0.3	3.0	V
Supply Voltage I/O Ring (V_{DDP})		–0.3	4.0	V
DC Input Voltage		–0.3	$V_{DDP} + 0.3$	V
PCI DC Input Voltage		–1.0	$V_{DDP} + 1.0$	V
PCI DC Input Clamp Current (absolute)	$V_{IN} < -1$ or $V_{IN} = V_{DDP} + 1V$	10		mA
LVPECL Input Voltage		–0.3	$V_{DDP} + 0.5$	V
GND		0	0	V

Note: *Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. Exposure to absolute maximum rated conditions for extended periods may affect device reliability. Devices should not be operated outside the Recommended Operating Conditions.

Table 1-15 • Programming, Storage and Operating Limits

Product Grade	Programming Cycles	Program Retention	Storage Temperature		Operating
			Min.	Max.	T_J Max Junction Temperature
Commercial	500	20 years	–55°C	110°C	110°C
Industrial	500	20 years	–55°C	110°C	110°C

Note: This is a stress rating only. Functional operation at these or any other condition above those indicated in the operational and programming specification is not implied.

Table 1-16 • Supply Voltages

Mode	V_{DD}	V_{DDP}
Single Voltage	2.5V	2.5V
Mixed Voltage*	2.5V	3.3V

Note: *Please refer to the mixed-mode interfacing section in the I/O Features in ProASIC^{PLUS} Flash FPGAs application note for more information.

Table 1-17 • Recommended Maximum Operating Conditions Programming and PLL Supplies

Parameter	Condition	Commercial/Industrial		Units
		Minimum	Maximum	
V_{PP}	During Programming	15.8	16.5	V
	Normal Operation ¹	0	16.5	V
V_{PN}	During Programming	–13.8	–13.2	V
	Normal Operation ²	–13.8	0	V
I_{PP}	During Programming		25	mA
I_{PN}	During Programming		10	mA
AVDD		V_{DD}	V_{DD}	V
AGND		GND	GND	V

Notes:

1. Please refer to the "VPP Programming Supply Pin" on page 1-64 for more information.
2. Please refer to the "VPN Programming Supply Pin" on page 1-64 for more information.

Table 1-18 • Recommended Operating Conditions

Parameter	Symbol	Limits	
		Commercial	Industrial
DC Supply Voltage (2.5V I/Os)	V_{DD} & V_{DDP}	$2.5V \pm 0.2V$	$2.5V \pm 0.2V$
DC Supply Voltage (2.5V, 3.3V I/Os*)	V_{DDP} V_{DD}	$3.3V \pm 0.3V$ $2.5V \pm 0.2V$	$3.3V \pm 0.3V$ $2.5V \pm 0.2V$
Operating Ambient Temperature Range	T_A	0°C to 70°C	–40°C to 85°C
Maximum Operating Junction Temperature	T_J	110°C	110°C

Note: *Please refer to the mixed-mode interfacing section in the I/O Features in ProASIC^{PLUS} Flash FPGAs application note for more information.

Table 1-19 • DC Electrical Specifications ($V_{DDP} = 2.5V \pm 0.2V$)¹

Symbol	Parameter	Conditions		Commercial / Industrial ^{1,2}			Units
				Min.	Typ.	Max.	
V _{OH}	Output High Voltage High Drive (OB25LPH)	I _{OH} = –6 mA	2.1			V	
		I _{OH} = –12 mA	2.0				
		I _{OH} = –24 mA	1.7				
	Low Drive (OB25LPL)	I _{OH} = –3 mA	2.1				
		I _{OH} = –6 mA	1.9				
		I _{OH} = –8 mA	1.7				
V _{OL}	Output Low Voltage High Drive (OB25LPH)	I _{OL} = 8 mA			0.2	V	
		I _{OL} = 15 mA			0.4		
		I _{OL} = 24 mA			0.7		
	Low Drive (OB25LPL)	I _{OL} = 4 mA			0.2		
		I _{OL} = 8 mA			0.4		
		I _{OL} = 15 mA			0.7		
V _{IH}	Input High Voltage		1.7		V _{DDP} + 0.3	V	
V _{IL}	Input Low Voltage		–0.3		0.7	V	
R _{WEAKPULLUP}	Weak Pull-up Resistance (OTB25LPU)	V _{IN} ≥ 1.25V	6		56	kΩ	
HYST	Input Hysteresis Schmitt	See Table 1-4 on page 1-8	0.3	0.35	0.45	V	
I _{IN}	Input Current	with pull up (V _{IN} = GND)	–240		– 20	μA	
		without pull up (V _{IN} = GND or V _{DD})	–10		10	μA	
I _{DDQ}	Quiescent Supply Current (standby) Commercial	V _{IN} = GND ³ or V _{DD}	Std.		5.0	15	mA
			–F		5.0	25	mA
I _{DDQ}	Quiescent Supply Current (standby) Industrial	V _{IN} = GND ³ or V _{DD}	Std.		5.0	20	mA

Notes:

1. All process conditions. Junction Temperature: –40 to +110°C.
2. –F parts are only available as commercial.
3. No pull-up resistor.
4. This will not exceed 2mA total per device.

Table 1-19 • DC Electrical Specifications ($V_{DDP} = 2.5V \pm 0.2V$)¹ (Continued)

Symbol	Parameter	Conditions		Commercial / Industrial ^{1,2}			Units
				Min.	Typ.	Max.	
I _{OZ}	3-State Output Leakage Current	V _{OH} = GND or V _{DD}	Std.	-10		10	μA
			-F ⁴	-10		100	μA
I _{OSH}	Output Short Circuit Current High High Drive (OB25LPH) Low Drive (OB25LPL)	V _{IN} = V _{SS} V _{IN} = V _{SS}		-120 -100			mA
I _{OSL}	Output Short Circuit Current Low High Drive (OB25LPH) Low Drive (OB25LPL)	V _{IN} = V _{DDP} V _{IN} = V _{DDP}				100 30	mA
C _{I/O}	I/O Pad Capacitance					10	pF
C _{CLK}	Clock Input Pad Capacitance					10	pF

Notes:

1. All process conditions. Junction Temperature: -40 to +110°C.
2. -F parts are only available as commercial.
3. No pull-up resistor.
4. This will not exceed 2mA total per device.

Table 1-20 • DC Electrical Specifications ($V_{DDP} = 3.3V \pm 0.3V$ and $V_{DD} = 2.5V \pm 0.2V$)¹

Symbol	Parameter	Conditions	Commercial / Industrial ^{1,2}			Units
			Min.	Typ.	Max.	
V_{OH}	Output High Voltage 3.3V I/O, High Drive (OB33P)	$I_{OH} = -14 \text{ mA}$ $I_{OH} = -24 \text{ mA}$	$0.9 \cdot V_{DDP}$ 2.4			V
	3.3V I/O, Low Drive (OB33L)	$I_{OH} = -6 \text{ mA}$ $I_{OH} = -12 \text{ mA}$	$0.9 \cdot V_{DDP}$ 2.4			
	Output High Voltage 2.5V I/O, High Drive (OB25H) ³	$I_{OH} = -0.1 \text{ mA}$ $I_{OH} = -0.5 \text{ mA}$ $I_{OH} = -3.0 \text{ mA}$	2.1 2.0 1.7			V
	2.5V I/O, Low Drive (OB25L) ³	$I_{OH} = -0.1 \text{ mA}$ $I_{OH} = -0.5 \text{ mA}$ $I_{OH} = -1.0 \text{ mA}$	2.1 2.0 1.7			
V_{OL}	Output Low Voltage 3.3V I/O, High Drive (OB33P)	$I_{OL} = 15 \text{ mA}$ $I_{OL} = 20 \text{ mA}$ $I_{OL} = 28 \text{ mA}$			$0.1 \cdot V_{DDP}$ 0.4 0.7	V
	3.3V I/O, Low Drive (OB33L)	$I_{OL} = 7 \text{ mA}$ $I_{OL} = 10 \text{ mA}$ $I_{OL} = 15 \text{ mA}$			$0.1 \cdot V_{DDP}$ 0.4 0.7	
	Output Low Voltage 2.5V I/O, High Drive (OB25H) ³	$I_{OL} = 7 \text{ mA}$ $I_{OL} = 14 \text{ mA}$ $I_{OL} = 28 \text{ mA}$			0.2 0.4 0.7	V
	2.5V I/O, Low Drive (OB25L) ³	$I_{OL} = 5 \text{ mA}$ $I_{OL} = 10 \text{ mA}$ $I_{OL} = 15 \text{ mA}$			0.2 0.4 0.7	
V_{IH}	Input High Voltage 3.3V LVTTTL/LVCMOS 2.5V Mode		2 1.7		$V_{DDP} + 0.3$ $V_{DDP} + 0.3$	V
V_{IL}	Input Low Voltage 3.3V LVTTTL/LVCMOS 2.5V Mode		-0.3 -0.3		0.8 0.7	V
$R_{WEAKPULLUP}$	Weak Pull-up Resistance (IOB33U)	$V_{IN} \geq 1.5V$	7		43	k Ω
$R_{WEAKPULLUP}$	Weak Pull-up Resistance (IOB25U)	$V_{IN} \geq 1.5V$	7		43	k Ω
I_{IN}	Input Current	with pull up ($V_{IN} = \text{GND}$)	-300		-40	μA
		without pull up ($V_{IN} = \text{GND or } V_{DD}$)	-10		10	μA

Notes:

1. All process conditions. Junction Temperature: -40 to +110°C.
2. -F parts are only available as commercial.
3. Please refer to the mixed-mode interfacing section in the [I/O Features in ProASIC^{PLUS} Flash FPGAs](#) application note for guidelines and usage.
4. No pull-up resistor.
5. This will not exceed 2mA total per device.

Table 1-20 • DC Electrical Specifications ($V_{DDP} = 3.3V \pm 0.3V$ and $V_{DD} 2.5V \pm 0.2V$)¹ (Continued)

Symbol	Parameter	Conditions		Commercial / Industrial ^{1,2}			Units
				Min.	Typ.	Max.	
I_{DDQ}	Quiescent Supply Current (standby) Commercial	$V_{IN} = GND^4$ or V_{DD}	Std.		5.0	15	mA
			–F		5.0	25	mA
I_{DDQ}	Quiescent Supply Current (standby) Industrial	$V_{IN} = GND^4$ or V_{DD}	Std.		5.0	20	mA
I_{OZ}	3-State Output Leakage Current	$V_{OH} = GND$ or V_{DD}	Std.	–10		10	μA
			–F ⁴	–10		100	μA
I_{OSH}	Output Short Circuit Current High 3.3V High Drive (OB33P) 3.3V Low Drive (OB33L) 2.5V High Drive (OB25H) ³ 2.5V Low Drive (OB25L) ³	$V_{IN} = GND$ $V_{IN} = GND$ $V_{IN} = GND$ $V_{IN} = GND$		–200 –100 –20 –10			mA
I_{OSL}	Output Short Circuit Current Low 3.3V High Drive 3.3V Low Drive 2.5V High Drive ³ 2.5V Low Drive ³	$V_{IN} = V_{DD}$ $V_{IN} = V_{DD}$ $V_{IN} = V_{DD}$ $V_{IN} = V_{DD}$				200 100 200 100	mA
$C_{I/O}$	I/O Pad Capacitance					10	pF
C_{CLK}	Clock Input Pad Capacitance					10	pF

Notes:

1. All process conditions. Junction Temperature: –40 to +110°C.
2. –F parts are only available as commercial.
3. Please refer to the mixed-mode interfacing section in the [I/O Features in ProASIC^{PLUS} Flash FPGAs](#) application note for guidelines and usage.
4. No pull-up resistor.
5. This will not exceed 2mA total per device.

Table 1-21 • DC Specifications (3.3V PCI Operation)¹

Symbol	Parameter	Condition	Commercial / Industrial ^{2,3}		Units
			Min.	Max.	
V _{DD}	Supply Voltage for Core		2.3	2.7	V
V _{DDP}	Supply Voltage for I/O Ring		3.0	3.6	V
V _{IH}	Input High Voltage		0.5V _{DDP}	V _{DDP} + 0.5	V
V _{IL}	Input Low Voltage		−0.5	0.3V _{DDP}	V
I _{IPU}	Input Pull-up Voltage ⁴		0.7V _{DDP}		V
I _{IL}	Input Leakage Current ⁵	0 < V _{IN} < V _{CCI}	Std.	10	μA
			−F ⁶	100	μA
V _{OH}	Output High Voltage	I _{OUT} = −500 μA	0.9V _{DDP}		V
V _{OL}	Output Low Voltage	I _{OUT} = 1500 μA		0.1V _{DDP}	V
C _{IN}	Input Pin Capacitance (except CLK)			10	pF
C _{CLK}	CLK Pin Capacitance		5	12	pF

Notes:

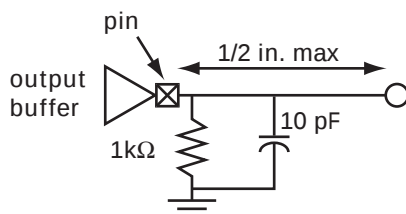
1. For PCI operation, use OTB33PH, OB33PH, IOB33PH, IB33, or IB33S macro library cell only.
2. All process conditions. Junction Temperature: −40 to +110°C.
3. −F parts are available as commercial only.
4. This specification is guaranteed by design. It is the minimum voltage to which pull-up resistors are calculated to pull a floated network. Designers with applications sensitive to static power utilization should ensure that the input buffer is conducting minimum current at this input voltage.
5. Input leakage currents include hi-Z output leakage for all bidirectional buffers with tristate outputs.
6. The sum of the leakage currents for all inputs shall not exceed 2mA per device.

Table 1-22 • AC Specifications (3.3V PCI Revision 2.2 Operation)

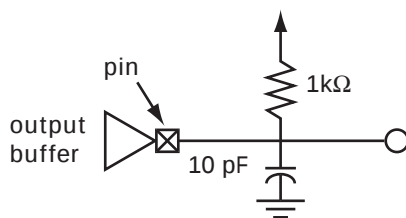
Symbol	Parameter	Condition	Commercial / Industrial		Units
			Min.	Max.	
$I_{OH(AC)}$	Switching Current High	$0 < V_{OUT} \leq 0.3V_{CCI}^*$	$-12V_{CCI}$		mA
		$0.3V_{CCI} \leq V_{OUT} < 0.9V_{CCI}^*$	$(-17.1 + (V_{DDP} - V_{OUT}))$		mA
		$0.7V_{CCI} < V_{OUT} < V_{CCI}^*$		See equation C – page 124 of the PCI Specification document rev. 2.2	
	(Test Point)	$V_{OUT} = 0.7V_{CC}^*$		$-32V_{CCI}$	mA
$I_{OL(AC)}$	Switching Current Low	$V_{CCI} > V_{OUT} \geq 0.6V_{CCI}^*$	$16V_{DDP}$		mA
		$0.6V_{CCI} > V_{OUT} > 0.1V_{CCI}^1$	$(26.7V_{OUT})$		mA
		$0.18V_{CCI} > V_{OUT} > 0^*$		See equation D – page 124 of the PCI Specification document rev. 2.2	
	(Test Point)	$V_{OUT} = 0.18V_{CC}$		$38V_{CCI}$	mA
I_{CL}	Low Clamp Current	$-3 < V_{IN} \leq -1$	$-25 + (V_{IN} + 1)/0.015$		mA
I_{CH}	High Clamp Current	$V_{CCI} + 4 > V_{IN} \geq V_{CCI} + 1$	$25 + (V_{IN} - V_{DDP} - 1)/0.015$		mA
$slew_R$	Output Rise Slew Rate	$0.2V_{CCI}$ to $0.6V_{CCI}$ load [*]	1	4	V/ns
$slew_F$	Output Fall Slew Rate	$0.6V_{CCI}$ to $0.2V_{CCI}$ load [*]	1	4	V/ns

Note: * Refer to the PCI Specification document rev. 2.2.

Pad Loading Applicable to the Rising Edge PCI



Pad Loading Applicable to the Falling Edge PCI



Tristate Buffer Delays

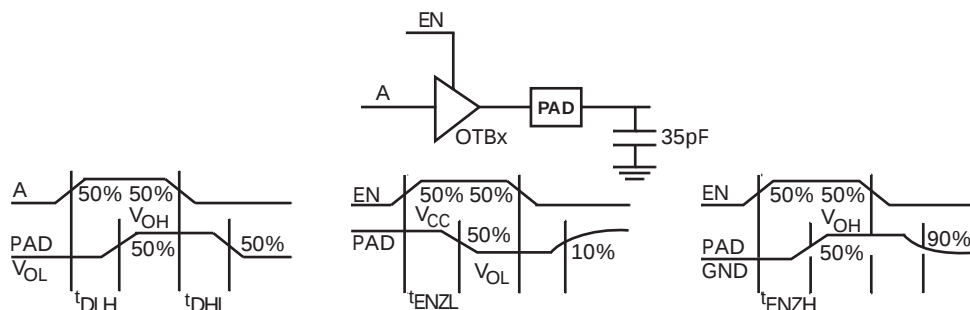


Figure 1-27 • Tristate Buffer Delays

Table 1-23 • Worst-Case Commercial Conditions

$V_{DDP} = 3.0V$, $V_{DD} = 2.3V$, 35 pF load, $T_j = 70^\circ C$

Macro Type	Description	Max t_{DLH}^1		Max t_{DHL}^2		Max t_{ENZH}^3		Max t_{ENZL}^4		Units
		STD	-F	STD	-F	STD	-F	STD	-F	
OTB33PH	3.3V, PCI Output Current, High Slew Rate	2.0	2.4	2.2	2.6	2.2	2.6	2.0	2.4	ns
OTB33PN	3.3V, High Output Current, Nominal Slew Rate	2.2	2.6	2.9	3.5	2.4	2.9	2.1	2.5	ns
OTB33PL	3.3V, High Output Current, Low Slew Rate	2.5	3.0	3.2	3.9	2.7	3.3	2.8	3.4	ns
OTB33LH	3.3V, Low Output Current, High Slew Rate	2.6	3.1	4.0	4.8	2.8	3.4	3.0	3.6	ns
OTB33LN	3.3V, Low Output Current, Nominal Slew Rate	2.9	3.5	4.3	5.2	3.2	3.8	4.1	4.9	ns
OTB33LL	3.3V, Low Output Current, Low Slew Rate	3.0	3.6	5.6	6.7	3.3	3.9	5.5	6.6	ns
OTB25HH	2.5V, High Output Current, High Slew Rate ⁵	3.1	3.8	1.8	2.2	2.8	3.4	1.7	2.0	ns
OTB25HN	2.5V, High Output Current, Nominal Slew Rate ⁵	3.1	3.7	2.7	3.3	2.9	3.5	2.7	3.2	ns
OTB25HL	2.5V, High Output Current, Low Slew Rate ⁵	3.1	3.7	3.9	4.7	2.9	3.5	3.8	4.6	ns
OTB25LH	2.5V, Low Output Current, High Slew Rate ⁵	4.6	5.6	2.9	3.5	4.6	5.5	2.9	3.4	ns
OTB25LN	2.5V, Low Output Current, Nominal Slew Rate ⁵	4.6	5.6	3.7	4.5	4.6	5.5	3.6	4.3	ns
OTB25LL	2.5V, Low Output Current, Low Slew Rate ⁵	4.6	5.6	5.1	6.1	4.5	5.4	4.8	5.8	ns
OTB25LPHH	2.5V, Low Power, High Output Current, High Slew Rate ⁶	2.0	2.4	2.1	2.5	2.3	2.7	2.0	2.4	ns
OTB25LPHN	2.5V, Low Power, High Output Current, Nominal Slew Rate ⁶	2.4	2.9	3.0	3.6	2.7	3.2	2.1	2.5	ns
OTB25LPHL	2.5V, Low Power, High Output Current, Low Slew Rate ⁶	2.9	3.5	3.2	3.8	3.1	3.8	2.7	3.2	ns
OTB25LPLH	2.5V, Low Power, Low Output Current, High Slew Rate ⁶	2.7	3.3	4.6	5.5	3.0	3.6	2.6	3.1	ns
OTB25LPLN	2.5V, Low Power, Low Output Current, Nominal Slew Rate ⁶	3.5	4.2	4.2	5.1	3.8	4.5	3.8	4.6	ns
OTB25LPLL	2.5V, Low Power, Low Output Current, Low Slew Rate ⁶	4.0	4.8	5.3	6.4	4.2	5.1	5.1	6.1	ns

Notes:

- t_{DLH} =Data-to-Pad HIGH
- t_{DHL} =Data-to-Pad LOW
- t_{ENZH} =Enable-to-Pad, Z to HIGH
- t_{ENZL} = Enable-to-Pad, Z to LOW
- Please refer to the mixed-mode interfacing section in the [I/O Features in ProASIC^{PLUS} Flash FPGAs](#) application note for guidelines and usage.
- Low power I/O work with $V_{DDP}=2.5V \pm 10\%$ only. $V_{DDP}=2.3V$ for delays.

Output Buffer Delays

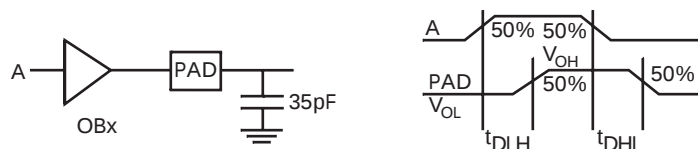


Figure 1-28 • Output Buffer Delays

Table 1-24 • Worst-Case Commercial Conditions

$V_{DDP} = 3.0V$, $V_{DD} = 2.3V$, 35 pF load, $T_J = 70^\circ C$

Macro Type	Description	Max t_{DLH}^1		Max t_{DHL}^2		Units
		STD	-F	STD	-F	
OB33PH	3.3V, PCI Output Current, High Slew Rate	2.0	2.4	2.2	2.6	ns
OB33PN	3.3V, High Output Current, Nominal Slew Rate	2.2	2.6	2.9	3.5	ns
OB33PL	3.3V, High Output Current, Low Slew Rate	2.5	3.0	3.2	3.9	ns
OB33LH	3.3V, Low Output Current, High Slew Rate	2.6	3.1	4.0	4.8	ns
OB33LN	3.3V, Low Output Current, Nominal Slew Rate	2.9	3.5	4.3	5.2	ns
OB33LL	3.3V, Low Output Current, Low Slew Rate	3.0	3.6	5.6	6.7	ns
OB25HH	2.5V, High Output Current, High Slew Rate ³	3.1	3.8	1.8	2.2	ns
OB25HN	2.5V, High Output Current, Nominal Slew Rate ³	3.1	3.7	2.7	3.3	ns
OB25HL	2.5V, High Output Current, Low Slew Rate ³	3.1	3.7	3.9	4.7	ns
OB25LH	2.5V, Low Output Current, High Slew Rate ³	4.6	5.6	2.9	3.5	ns
OB25LN	2.5V, Low Output Current, Nominal Slew Rate ³	4.6	5.6	3.7	4.5	ns
OB25LL	2.5V, Low Output Current, Low Slew Rate ³	4.6	5.6	5.1	6.1	ns
OB25LPHH	2.5V, Low Power, High Output Current, High Slew Rate ⁴	2.0	2.4	2.1	2.6	ns
OB25LPHN	2.5V, Low Power, High Output Current, Nominal Slew Rate ⁴	2.4	2.9	3.0	3.6	ns
OB25LPHL	2.5V, Low Power, High Output Current, Low Slew Rate ⁴	2.9	3.5	3.2	3.8	ns
OB25LPLH	2.5V, Low Power, Low Output Current, High Slew Rate ⁴	2.7	3.3	4.6	5.5	ns
OB25LPLN	2.5V, Low Power, Low Output Current, Nominal Slew Rate ⁴	3.5	4.2	4.2	5.1	ns
OB25LPLL	2.5V, Low Power, Low Output Current, Low Slew Rate ⁴	4.0	4.8	5.3	6.4	ns

Notes:

1. t_{DLH} = Data-to-Pad HIGH
2. t_{DHL} = Data-to-Pad LOW
3. Please refer to the mixed-mode interfacing section in the [I/O Features in ProASIC^{PLUS} Flash FPGAs](#) application note for guidelines and usage.
4. Low power I/O work with $V_{DDP}=2.5V \pm 10\%$ only. $V_{DDP}=2.3V$ for delays.

Input Buffer Delays

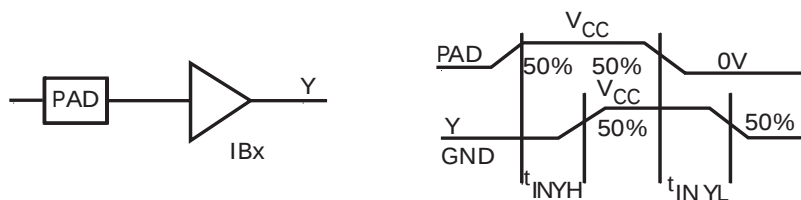


Figure 1-29 • Input Buffer Delays

Table 1-25 • Worst-Case Commercial Conditions

$V_{DDP} = 3.0V$, $V_{DD} = 2.3V$, $T_j = 70^{\circ}C$

Macro Type	Description	Max. $t_{IN YH}^1$		Max. $t_{IN YL}^2$		Units
		Std.	-F	Std.	-F	
IB25	2.5V, CMOS Input Levels ³ , No Pull-up Resistor	0.7	0.9	0.8	1.0	ns
IB25S	2.5V, CMOS Input Levels ³ , No Pull-up Resistor, Schmitt Trigger	0.7	0.9	0.8	1.0	ns
IB25LP	2.5V, CMOS Input Levels ³ , Low Power	0.9	1.1	0.6	0.8	ns
IB25LPS	2.5V, CMOS Input Levels ³ , Low Power, Schmitt Trigger	0.7	0.9	0.9	1.1	ns
IB33	3.3V, CMOS Input Levels ³ , No Pull-up Resistor	0.4	0.5	0.6	0.7	ns
IB33S	3.3V, CMOS Input Levels ³ , No Pull-up Resistor, Schmitt Trigger	0.6	0.7	0.8	0.9	ns

Notes:

1. $t_{IN YH}$ = Input Pad-to-Y HIGH
2. $t_{IN YL}$ = Input Pad-to-Y LOW
3. LVTTTL delays are the same as CMOS delays.
4. For LP Macros, $V_{DDP}=2.3V$ for delays.

Global Input Buffer Delays

Table 1-26 • Worst-Case Commercial Conditions

 $V_{DDP} = 3.0V$, $V_{DD} = 2.3V$, $T_J = 70^\circ$

Macro Type	Description	Max. t_{INYH}^1		Max. t_{INYL}^2		Units
		Std.	-F	Std.	-F	
GL25	2.5V, CMOS Input Levels ³ , No Pull-up Resistor	1.3	1.6	1.0	1.2	ns
GL25S	2.5V, CMOS Input Levels ³ , No Pull-up Resistor, Schmitt Trigger	1.3	1.6	1.0	1.2	ns
GL25LP	2.5V, CMOS Input Levels ³ , Low Power	1.1	1.2	1.0	1.3	ns
GL25LPS	2.5V, CMOS Input Levels ³ , Low Power, Schmitt Trigger	1.3	1.6	1.0	1.1	ns
GL33	3.3V, CMOS Input Levels ³ , No Pull-up Resistor	1.0	1.2	1.1	1.3	ns
GL33S	3.3V, CMOS Input Levels ³ , No Pull-up Resistor, Schmitt Trigger	1.0	1.2	1.1	1.3	ns
PECL	PPECL Input Levels	1.0	1.2	1.1	1.3	ns

Notes:

1. t_{INYH} = Input Pad-to-Y HIGH
2. t_{INYL} = Input Pad-to-Y LOW
3. LVTTTL delays are the same as CMOS delays.
4. For LP Macros, $V_{DDP}=2.3V$ for delays.

Predicted Global Routing Delay

Table 1-27 • Worst-Case Commercial Conditions¹ $V_{DDP} = 3.0V$, $V_{DD} = 2.3V$, $T_J = 70^\circ C$

Parameter	Description	Max.		Units
		Std.	-F	
t_{RCKH}	Input Low to High ²	1.1	1.3	ns
t_{RCKL}	Input High to Low ²	1.0	1.2	ns
t_{RCKH}	Input Low to High ³	0.8	1.0	ns
t_{RCKL}	Input High to Low ³	0.8	1.0	ns

Notes:

1. The timing delay difference between tile locations is less than 15ps.
2. Highly loaded row 50%.
3. Minimally loaded row.

Global Routing Skew

Table 1-28 • Worst-Case Commercial Conditions

 $V_{DDP} = 3.0V$, $V_{DD} = 2.3V$, $T_J = 70^\circ C$

Parameter	Description	Max.		Units
		Std.	-F	
t_{RCKSWH}	Maximum Skew Low to High	270	320	ps
t_{RCKSHH}	Maximum Skew High to Low	270	320	ps

Module Delays

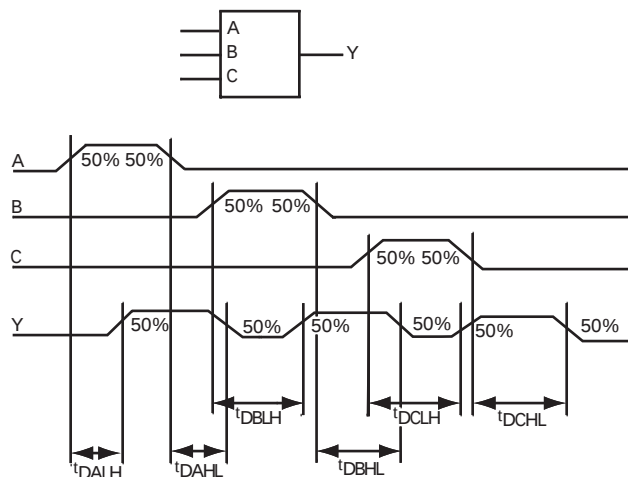


Figure 1-30 • Module Delays

Sample Macrocell Library Listing

Table 1-29 • Worst-Case Commercial Conditions¹

$V_{DD} = 2.3V$, $T_J = 70^\circ C$

Cell Name	Description		Standard		-F		Units
			Max	Min	Max	Min	
NAND2	2-Input NAND		0.5		0.6		ns
AND2	2-Input AND		0.7		0.8		ns
NOR3	3-Input NOR		0.8		1.0		ns
MUX2L	2-1 MUX with Active Low Select		0.5		0.6		ns
OA21	2-Input OR into a 2-Input AND		0.8		1.0		ns
XOR2	2-Input Exclusive OR		0.6		0.8		ns
LDL	Active Low Latch (LH/HL)	LH ²	0.9		1.1		ns
		HL ²	0.8		0.9		
		t _{setup}		0.7		0.8	
		t _{hold}		0.1		0.2	
DFFL	Negative Edge-Triggered D-type Flip-Flop (LH/HL)	LH ²	0.9		1.1		ns
		HL ²	0.8		1.0		
		t _{setup}		0.6		0.7	
		t _{hold}		0.0		0.0	

Notes:

1. Intrinsic delays have a variable component, coupled to the input slope of the signal. These numbers assume an input slope typical of local interconnect.
2. LH and HL refer to the Q transitions from Low to High and High to Low, respectively.

Table 1-30 • Recommended Operating Conditions

Parameter	Symbol	Limits
		Commercial/Industrial
Maximum Clock Frequency*	f_{CLOCK}	180 MHz
Maximum RAM Frequency*	f_{RAM}	150 MHz
Maximum Rise/Fall Time on Inputs* • Schmitt Mode (10% to 90%) • Non-schmitt Mode (10% to 90%)	t_R/t_F t_R/t_F	100 ns 10 ns
Maximum LVPECL Frequency*		180 MHz
Maximum t_{CK} Frequency (JTAG)	t_{CK}	10 MHz

Note: *–F parts will be 20% slower than standard commercial devices.

Table 1-31 • Slew Rates Measured at C = 30pF, Nominal Power Supplies and 25°C

Type	Trig. Level	Rising Edge (nS)	Slew Rate (V/nS)	Falling Edge (nS)	Slew Rate (V/nS)	PCI Mode
OB33PH	10%-90%	1.60	1.65	1.65	1.60	Yes
OB33PN	10%-90%	1.57	1.68	3.32	0.80	No
OB33PL	10%-90%	1.57	1.68	1.99	1.32	No
OB33LH	10%-90%	3.80	0.70	4.84	0.55	No
OB33LN	10%-90%	4.19	0.63	3.37	0.78	No
OB33LL	10%-90%	5.49	0.48	2.98	0.89	No
OB25HH ²	20%-60%	3.31	0.30	0.75	1.33	No
OB25HN ²	20%-60%	3.20	0.32	0.77	1.30	No
OB25HL ²	20%-60%	3.27	0.31	0.77	1.30	No
OB25LH ²	20%-60%	8.41	0.12	1.38	0.72	No
OB25LN ²	20%-60%	8.54	0.12	1.15	0.87	No
OB25LL ²	20%-60%	8.50	0.12	1.19	0.84	No
OB25LPHH	10%-90%	1.55	1.29	1.56	1.28	No
OB25LPHN	10%-90%	1.70	1.18	2.08	0.96	No
OB25LPHL	10%-90%	1.97	1.02	2.09	0.96	No
OB25LPLH	10%-90%	3.57	0.56	3.93	0.51	No
OB25LPLN	10%-90%	4.65	0.43	3.28	0.61	No
OB25LPLL	10%-90%	5.52	0.36	3.44	0.58	No

Notes:

1. Standard and –F parts.
2. Please refer to the mixed-mode interfacing section in the I/O Features in ProASIC^{PLUS} Flash FPGAs application note for guidelines and usage.

Embedded Memory Specifications

This section discusses ProASIC^{PLUS} SRAM/FIFO embedded memory and its interface signals, including timing diagrams that show the relationships of signals as they pertain to single embedded memory blocks (Table 1-32). Table 1-10 on page 1-20 shows basic SRAM and FIFO configurations. Simultaneous Read and Write to the same location must be done with care. On such accesses the DI bus is output to the DO bus.

Enclosed Timing Diagrams—SRAM Mode:

- "Synchronous SRAM Read, Access Timed Output Strobe (Synchronous Transparent)"
- "Synchronous SRAM Read, Pipeline Mode Outputs (Synchronous Pipelined)"
- "Asynchronous SRAM Write"
- "Asynchronous SRAM Read, Address Controlled, RDB=0"
- "Asynchronous SRAM Read, RDB Controlled"
- "Synchronous SRAM Write"

• Embedded Memory Specifications

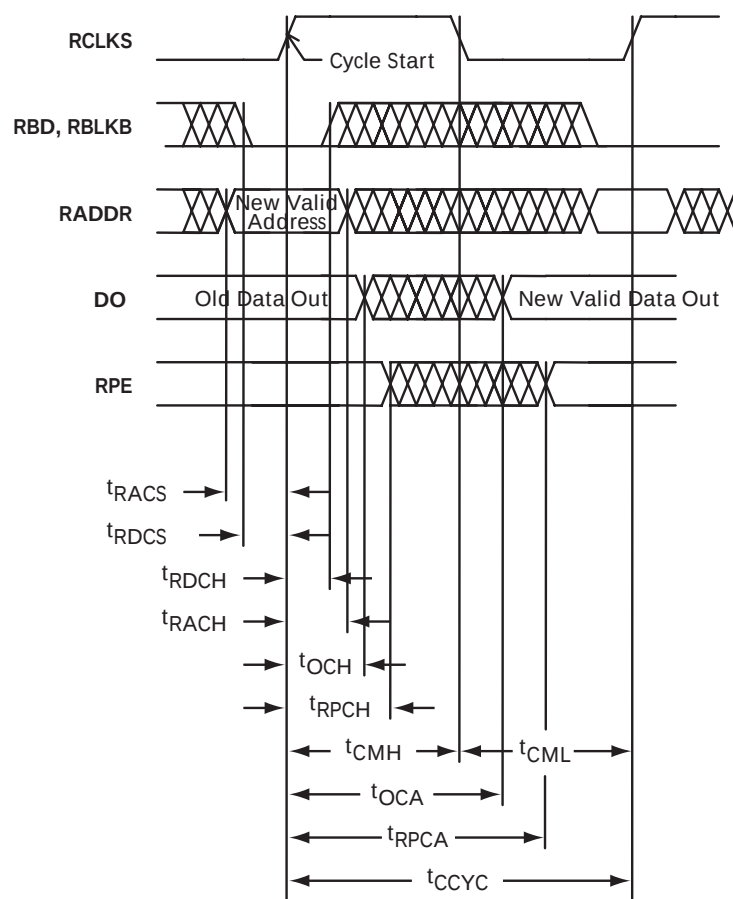
The difference between synchronous transparent and pipeline modes is the timing of all the output signals from the memory. In transparent mode, the outputs will change within the same clock cycle to reflect the data requested by the currently valid access to the memory. If clock cycles are short (high clock speed), the data requires most of the clock cycle to change to valid values (stable signals). Processing of this data in the same clock cycle is nearly impossible. Most designers add registers at all outputs of the memory to push the data processing into the next clock cycle. An entire clock cycle can then be used to process the data. To simplify use of this memory setup, suitable registers have been implemented as part of the memory primitive and are available to the user in the synchronous pipeline mode. In this mode, the output signals will change shortly after the second rising edge, following the initiation of the read access.

Table 1-32 • Memory Block SRAM Interface Signals

SRAM Signal	Bits	In/Out	Description
WCLKS	1	IN	Write clock used on synchronization on write side
RCLKS	1	IN	Read clock used on synchronization on read side
RADDR<0:7>	8	IN	Read address
RBLKB	1	IN	True read block select (active LOW)
RDB	1	IN	True read pulse (active LOW)
WADDR<0:7>	8	IN	Write address
WBLKB	1	IN	Write block select (active LOW)
DI<0:8>	9	IN	Input data bits <0:8>, <8> can be used for parity in
WRB	1	IN	Negative true write pulse
DO<0:8>	9	OUT	Output data bits <0:8>, <8> can be used for parity out
RPE	1	OUT	Read parity error (active HIGH)
WPE	1	OUT	Write parity error (active HIGH)
PARODD	1	IN	Selects odd parity generation/detect when high, even when low

Note: Not all signals shown are used in all modes.

Synchronous SRAM Read, Access Timed Output Strobe (Synchronous Transparent)



Note: The plot shows the normal operation status.

Figure 1-31 • Synchronous SRAM Read, Access Timed Output Strobe (Synchronous Transparent)

Table 1-33 • $T_J = 0^{\circ}\text{C to } 110^{\circ}\text{C}$; $V_{DD} = 2.3\text{V to } 2.7\text{V}$

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
CCYC	Cycle time	7.5		ns	
CMH	Clock high phase	3.0		ns	
CML	Clock low phase	3.0		ns	
OCA	New DO access from RCLKS $\uparrow$	7.5		ns	
OCH	Old DO valid from RCLKS $\uparrow$		3.0	ns	
RACH	RADDR hold from RCLKS $\uparrow$	0.5		ns	
RACS	RADDR setup to RCLKS $\uparrow$	1.0		ns	
RDCH	RDB hold from RCLKS $\uparrow$	0.5		ns	
RDCS	RDB setup to RCLKS $\uparrow$	1.0		ns	
RPCA	New RPE access from RCLKS $\uparrow$	9.5		ns	
RPCH	Old RPE valid from RCLKS $\uparrow$		3.0	ns	

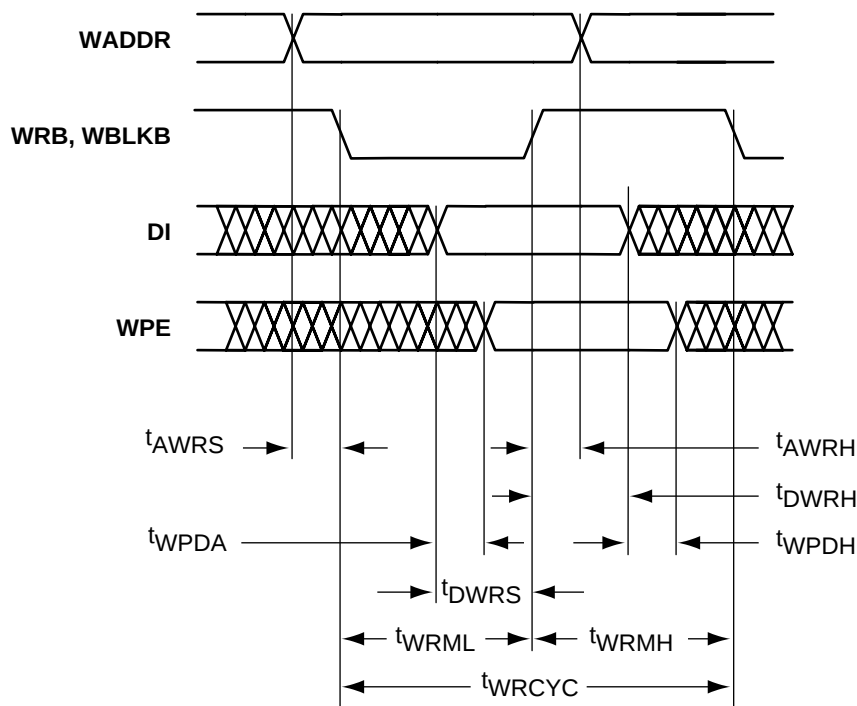
Note: -F speed grade devices are 20% slower than the standard numbers.

Figure 1-32 • Synchronous SRAM Read, Pipeline Mode Outputs (Synchronous Pipelined)

Symbol t _{xxx}	Description	Min.	Max.	Units	Notes
CCYC	Cycle time	7.5		ns	
CMH	Clock high phase	3.0		ns	
CML	Clock low phase	3.0		ns	
OCA	New DO access from RCLKS ↑	2.0		ns	
OCH	Old DO valid from RCLKS ↑		0.75	ns	
RACH	RADDR hold from RCLKS ↑	0.5		ns	
RACS	RADDR setup to RCLKS ↑	1.0		ns	
RDCH	RDB hold from RCLKS ↑	0.5		ns	
RDCS	RDB setup to RCLKS ↑	1.0		ns	
RPCA	New RPE access from RCLKS ↑	4.0		ns	
RPCH	Old RPE valid from RCLKS ↑		1.0	ns	

v3.3

Asynchronous SRAM Write



Note: The plot shows the normal operation status.

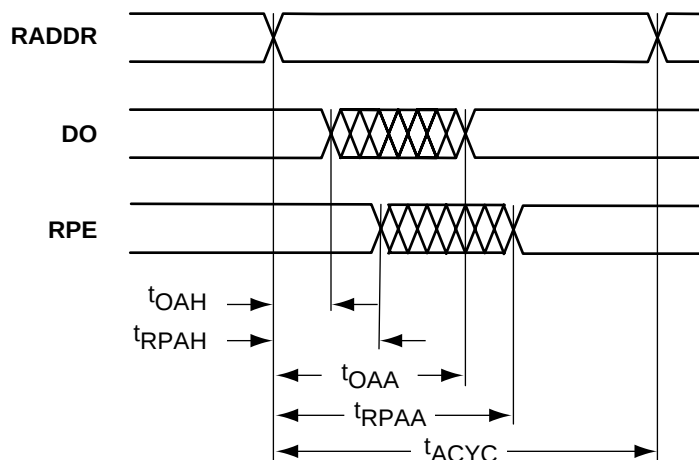
Figure 1-33 • Asynchronous SRAM Write

Table 1-35 • $T_j = 0^\circ\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
AWRH	WADDR hold from WB ↑	1.0		ns	
AWRS	WADDR setup to WB ↓	0.5		ns	
DWRH	DI hold from WB ↑	1.5		ns	
DWRS	DI setup to WB ↑	0.5		ns	PARGEN is inactive
DWRS	DI setup to WB ↑	2.5		ns	PARGEN is active
WPDA	WPE access from DI	3.0		ns	WPE is invalid while PARGEN is active
WPDH	WPE hold from DI		1.0	ns	
WRCYC	Cycle time	7.5		ns	
WRMH	WB high phase	3.0		ns	Inactive
WRML	WB low phase	3.0		ns	Active

Note: -F speed grade devices are 20% slower than the standard numbers.

Asynchronous SRAM Read, Address Controlled, RDB=0



Note: The plot shows the normal operation status.

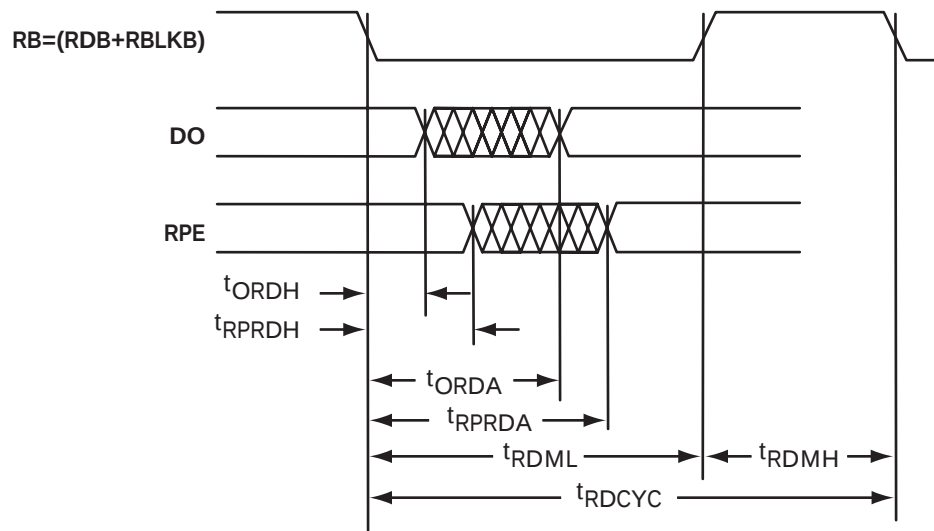
Figure 1-34 • Asynchronous SRAM Read, Address Controlled, RDB=0

Table 1-36 • $T_j = 0^\circ\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
ACYC	Read cycle time	7.5		ns	
OAA	New DO access from RADDR stable	7.5		ns	
OAH	Old DO hold from RADDR stable		3.0	ns	
RPAA	New RPE access from RADDR stable	10.0		ns	
RPAH	Old RPE hold from RADDR stable		3.0	ns	

Note: -F speed grade devices are 20% slower than the standard numbers.

Asynchronous SRAM Read, RDB Controlled



Note: The plot shows the normal operation status.

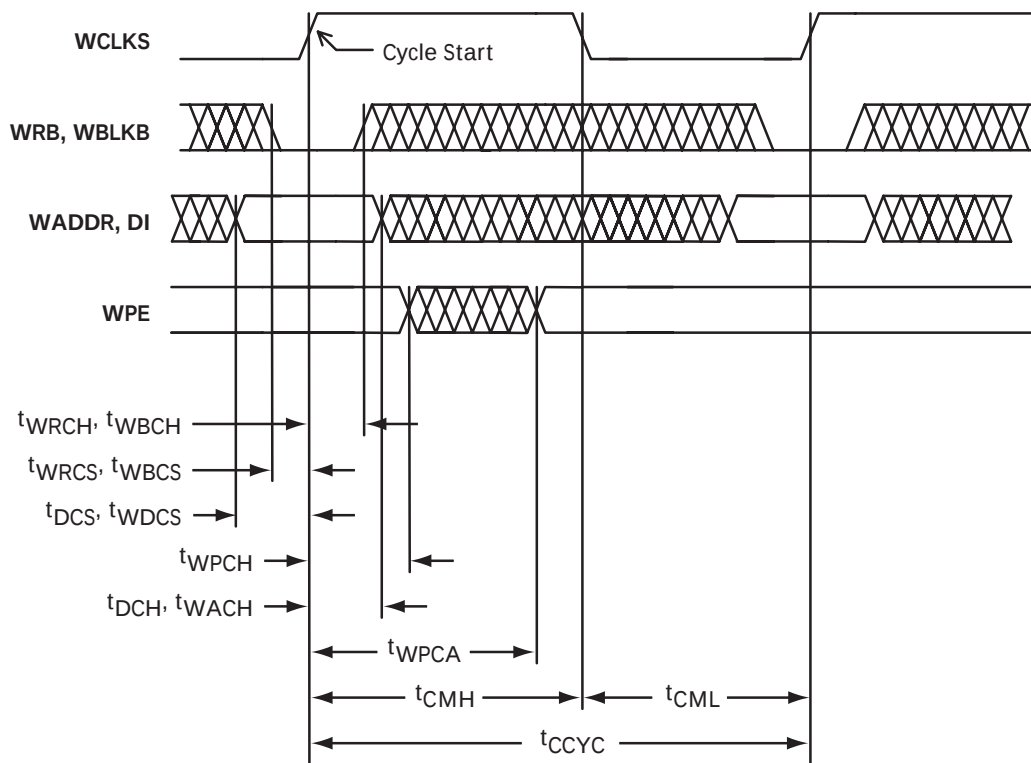
Figure 1-35 • Asynchronous SRAM Read, RDB Controlled

Table 1-37 • $T_j = 0^\circ\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
ORDA	New DO access from RB ↓	7.5		ns	
ORDH	Old DO valid from RB ↓		3.0	ns	
RDCYC	Read cycle time	7.5		ns	
RDMH	RB high phase	3.0		ns	Inactive setup to new cycle
RDML	RB low phase	3.0		ns	Active
RPRDA	New RPE access from RB ↓	9.5		ns	
RPRDH	Old RPE valid from RB ↓		3.0	ns	

Note: –F speed grade devices are 20% slower than the standard numbers.

Synchronous SRAM Write



Note: The plot shows the normal operation status.

Figure 1-36 • Synchronous SRAM Write

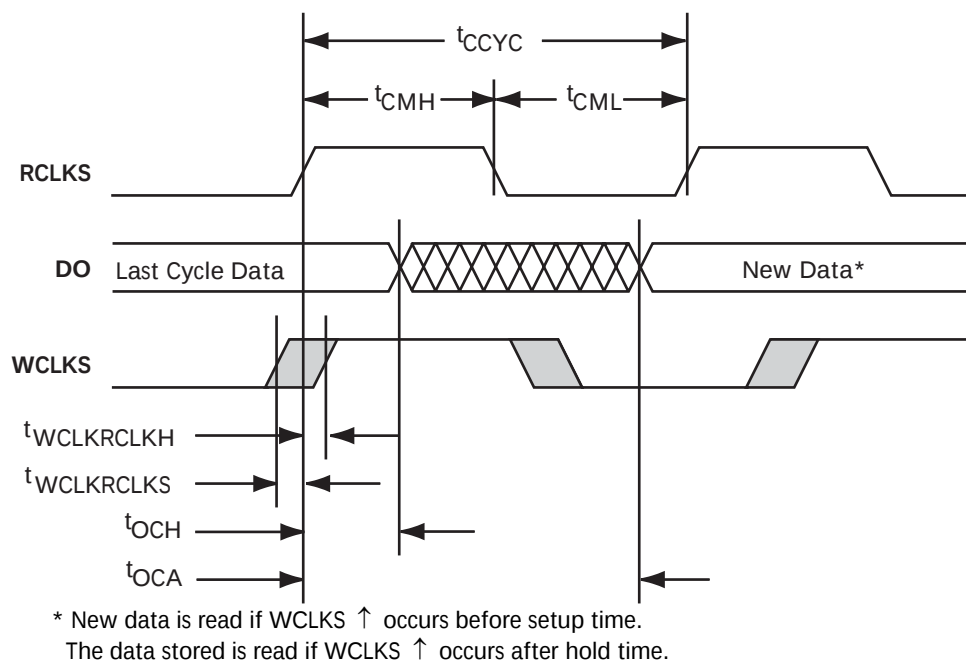
Table 1-38 • $T_J = 0^{\circ}\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
CCYC	Cycle time	7.5		ns	
CMH	Clock high phase	3.0		ns	
CML	Clock low phase	3.0		ns	
DCH	DI hold from WCLKS $\uparrow$	0.5		ns	
DCS	DI setup to WCLKS $\uparrow$	1.0		ns	
WACH	WADDR hold from WCLKS $\uparrow$	0.5		ns	
WDCS	WADDR setup to WCLKS $\uparrow$	1.0		ns	
WPCA	New WPE access from WCLKS $\uparrow$	3.0		ns	WPE is invalid while PARGEN is active
WPCH	Old WPE valid from WCLKS $\uparrow$		0.5	ns	
WRCH, WBCH	WRB & WBLKB hold from WCLKS $\uparrow$	0.5		ns	
WRCS, WBCS	WRB & WBLKB setup to WCLKS $\uparrow$	1.0		ns	

Notes:

1. On simultaneous read and write accesses to the same location DI is output to DO.
2. -F speed grade devices are 20% slower than the standard numbers.

Synchronous Write and Read to the Same Location



Note: The plot shows the normal operation status.

Figure 1-37 • Synchronous Write and Read to the Same Location

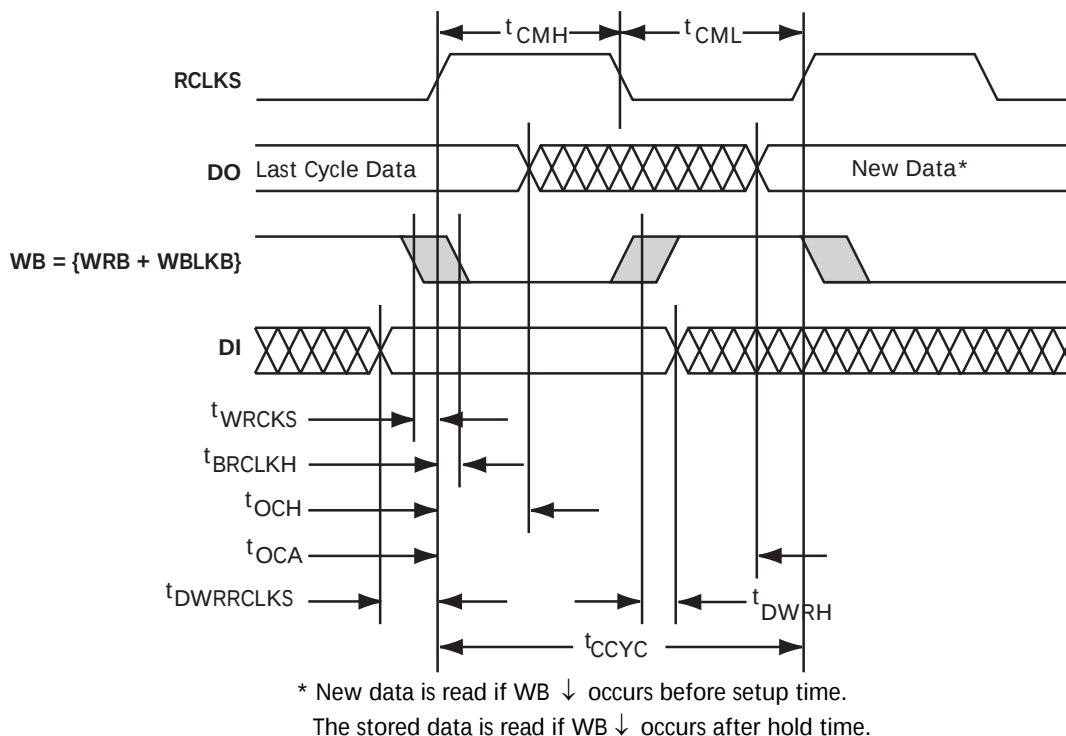
Table 1-39 • $T_J = 0^{\circ}\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
CCYC	Cycle time	7.5		ns	
CMH	Clock high phase	3.0		ns	
CML	Clock low phase	3.0		ns	
WCLKRCLKS	WCLKS ↑ to RCLKS ↑ setup time	-0.1		ns	
WCLKRCLKH	WCLKS ↑ to RCLKS ↑ hold time		7.0	ns	
OCH	Old DO valid from RCLKS ↑		3.0	ns	OCA/OCH displayed for Access Timed Output
OCA	New DO valid from RCLKS ↑	7.5		ns	

Note:

1. This behavior is valid for Access Timed Output and Pipelined Mode Output. The table shows the timings of an Access Timed Output.
2. During synchronous write and synchronous read access to the same location, the new write data will be read out if the active write clock edge occurs before or at the same time as the active read clock edge. The negative setup time insures this behavior for WCLKS and RCLKS driven by the same design signal.
3. If WCLKS changes after the hold time, the data will be read.
4. A setup or hold time violation will result in unknown output data.
5. -F speed grade devices are 20% slower than the standard numbers.

Asynchronous Write and Synchronous Read to the Same Location



Note: The plot shows the normal operation status.

Figure 1-38 • Asynchronous Write and Synchronous Read to the Same Location

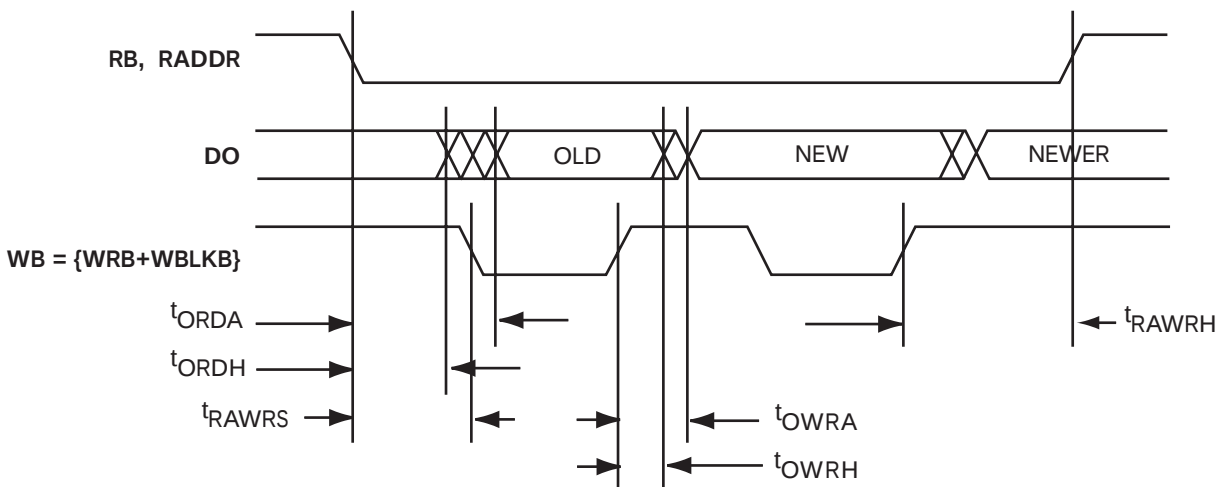
Table 1-40 • $T_J = 0^{\circ}\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
CCYC	Cycle time	7.5		ns	
CMH	Clock high phase	3.0		ns	
CML	Clock low phase	3.0		ns	
WBRCCLKS	WB ↓ to RCLKS ↑ setup time	-0.1		ns	
WBRCCLKH	WB ↓ to RCLKS ↑ hold time		7.0	ns	
OCH	Old DO valid from RCLKS ↑		3.0	ns	OCA/OCH displayed for Access Timed Output
OCA	New DO valid from RCLKS ↑	7.5		ns	
DWRRCLKS	DI to RCLKS ↑ setup time	0		ns	
DWRH	DI to WB ↑ hold time		1.5	ns	

Notes:

1. This behavior is valid for Access Timed Output and Pipelined Mode Output. The table shows the timings of an Access Timed Output.
2. In asynchronous write and synchronous read access to the same location, the new write data will be read out if the active write signal edge occurs before or at the same time as the active read clock edge. If WB changes to low after hold time, the data will be read.
3. A setup or hold time violation will result in unknown output data.
4. -F speed grade devices are 20% slower than the standard numbers.

Asynchronous Write and Read to the Same Location



Note: The plot shows the normal operation status.

Figure 1-39 • Asynchronous Write and Read to the Same Location

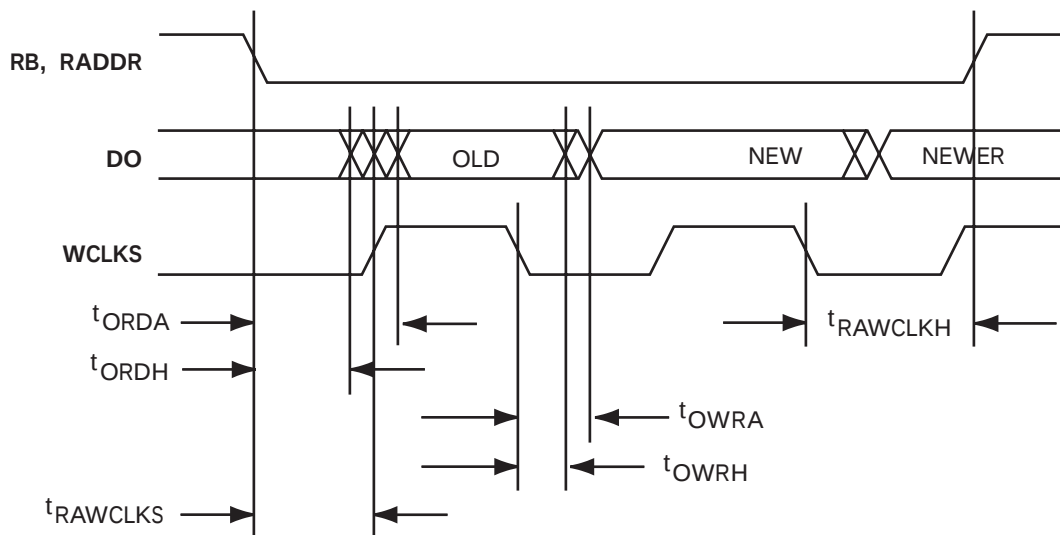
Table 1-41 • $T_J = 0^\circ\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
ORDA	New DO access from RB ↓	7.5		ns	
ORDH	Old DO valid from RB ↓		3.0	ns	
OWRA	New DO access from WB ↑	3.0		ns	
OWRH	Old DO valid from WB ↑		0.5	ns	
RAWRS	RB ↓ or RADDR from WB ↓	5.0		ns	
RAWRH	RB ↑ or RADDR from WB ↑	5.0		ns	

Notes:

1. During an asynchronous read cycle, each write operation (synchronous or asynchronous) to the same location will automatically trigger a read operation which updates the read data.
2. Violation of RAWRS will disturb access to the OLD data.
3. Violation of RAWRH will disturb access to the NEWER data.
4. –F speed grade devices are 20% slower than the standard numbers.

Synchronous Write and Asynchronous Read to the Same Location



Note: The plot shows the normal operation status.

Figure 1-40 • Synchronous Write and Asynchronous Read to the Same Location

Table 1-42 • $T_J = 0^{\circ}\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
ORDA	New DO access from RB ↓	7.5		ns	
ORDH	Old DO valid from RB ↓		3.0	ns	
OWRA	New DO access from WCLKS ↓	3.0		ns	
OWRH	Old DO valid from WCLKS ↓		0.5	ns	
RAWCLKS	RB ↓ or RADDR from WCLKS ↑	5.0		ns	
RAWCLKH	RB ↑ or RADDR from WCLKS ↓	5.0		ns	

Notes:

1. During an asynchronous read cycle, each write operation (synchronous or asynchronous) to the same location will automatically trigger a read operation which updates the read data.
2. Violation of RAWCLKS will disturb access to OLD data.
3. Violation of RAWCLKH will disturb access to NEWER data.
4. -F speed grade devices are 20% slower than the standard numbers.

Asynchronous FIFO Full and Empty Transitions

The asynchronous FIFO accepts writes and reads while not full or not empty. When the FIFO is full, all writes are inhibited. Conversely, when the FIFO is empty, all reads are inhibited. A problem is created if the FIFO is written during the transition out of full to not full or read during the transition out of empty to not empty. The exact time at which the write or read operation changes from inhibited to accepted after the read (write) signal which causes the transition from full or empty to not full or not empty is indeterminate. This indeterminate period starts 1 ns after the RB (WB) transition, which deactivates full or not empty and ends 3 ns after the RB (WB) transition for slow cycles. For fast cycles, the indeterminate period ends 3 ns (7.5 ns – RDL (WRL)) after the RB (WB) transition, whichever is later (Table 1-1 on page 1-6).

The timing diagram for write is shown in Figure 1-38 on page 1-51. The timing diagram for read is shown in Figure 1-39 on page 1-52. For basic SRAM configurations, see Table 1-11 on page 1-22.

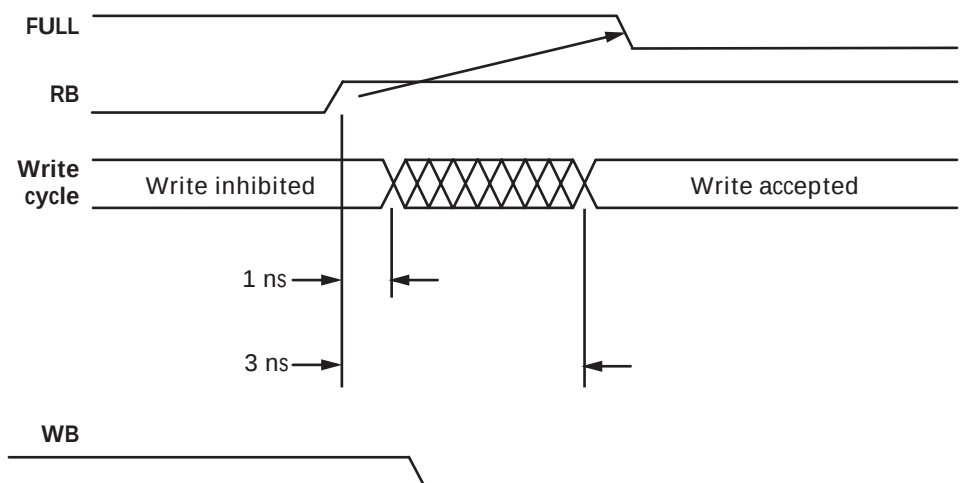
Enclosed Timing Diagrams – FIFO Mode:

- "Asynchronous FIFO Read"
- "Asynchronous FIFO Write"
- "Synchronous FIFO Read, Access Timed Output Strobe (Synchronous Transparent)"
- "Synchronous FIFO Read, Pipeline Mode Outputs (Synchronous Pipelined)"
- "Synchronous FIFO Write"
- "FIFO Reset"

Table 1-43 • Memory Block FIFO Interface Signals

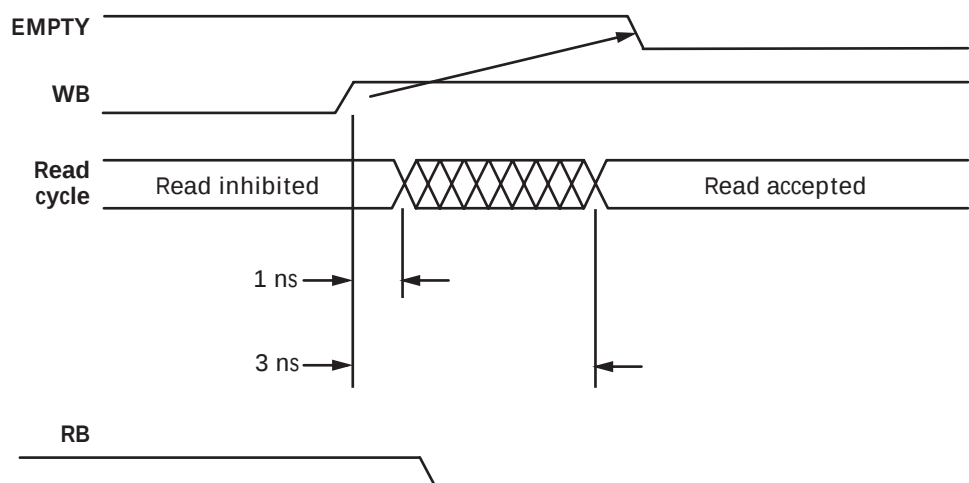
FIFO Signal	Bits	In/Out	Description
WCLKS	1	IN	Write clock used for synchronization on write side
RCLKS	1	IN	Read clock used for synchronization on read side
LEVEL <0:7>*	8	IN	Direct configuration implements static flag logic
RBLKB	1	IN	Read block select (active LOW)
RDB	1	IN	Read pulse (active LOW)
RESET	1	IN	Reset for FIFO pointers (active LOW)
WBLKB	1	IN	Write block select (active LOW)
DI<0:8>	9	IN	Input data bits <0:8>, <8> will be generated if PARGEN is true
WRB	1	IN	Write pulse (active LOW)
FULL, EMPTY	2	OUT	FIFO flags. FULL prevents write and EMPTY prevents read
EQTH, GEQTH*	2	OUT	EQTH is true when the FIFO holds the number of words specified by the LEVEL signal. GEQTH is true when the FIFO holds (LEVEL) words or more
DO<0:8>	9	OUT	Output data bits <0:8>
RPE	1	OUT	Read parity error (active HIGH)
WPE	1	OUT	Write parity error (active HIGH)
LGDEP <0:2>	3	IN	Configures DEPTH of the FIFO to 2 (LGDEP+1)
PARODD	1	IN	Selects odd parity generation/detect when high, even when low

Note: *LEVEL is always eight bits (0000.0000, 0000.0001). That means for values of DEPTH greater than 256, not all values will be possible, e.g. for DEPTH=512, the LEVEL can only have the values 2, 4, . . . , 512. The LEVEL signal circuit will generate signals that indicate whether the FIFO is exactly filled to the value of LEVEL (EQTH) or filled equal or higher (GEQTH) than the specified LEVEL. Since counting starts at 0, EQTH will become true when the FIFO holds (LEVEL+1) words for 512-bit FIFOs.



Note: –F speed grade devices are 20% slower than the standard numbers.

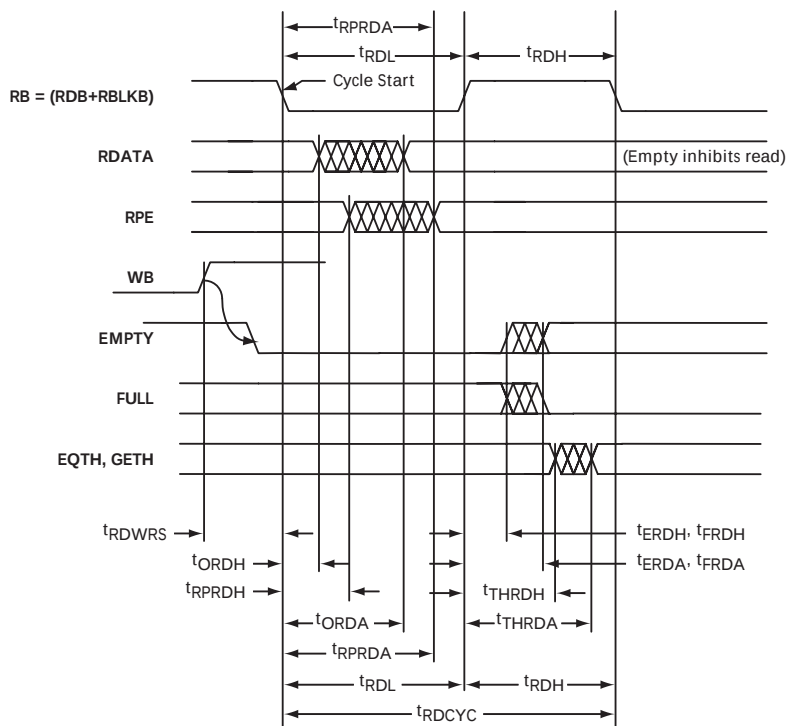
Figure 1-41 • Write Timing Diagram



Note: –F speed grade devices are 20% slower than the standard numbers.

Figure 1-42 • Read Timing Diagram

Asynchronous FIFO Read



Note: The plot shows the normal operation status.

Figure 1-43 • Asynchronous FIFO Read

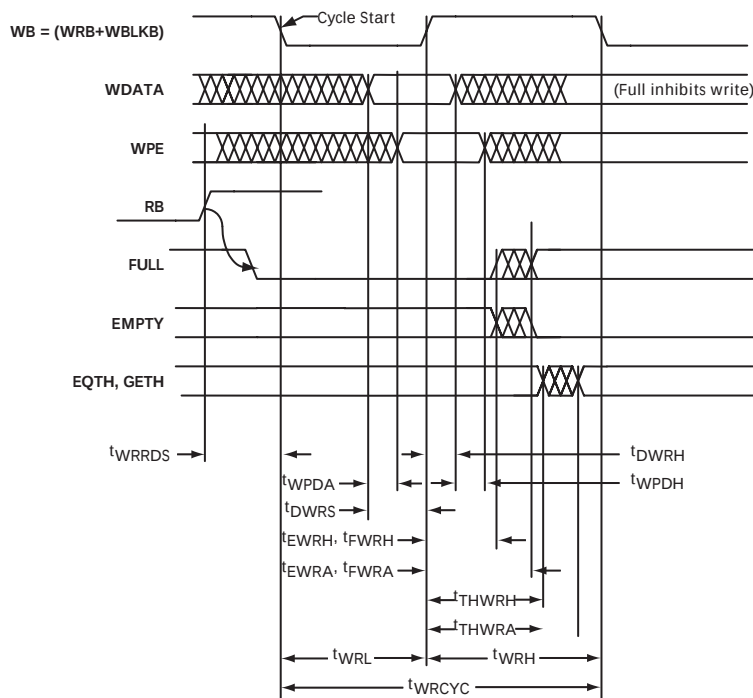
Table 1-44 • $T_J = 0^\circ\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t _{xxx}	Description	Min.	Max.	Units	Notes
ERDH, FRDH, THRDH	Old EMPTY, FULL, EQTH, & GETH valid hold time from RB $\uparrow$		0.5	ns	Empty/full/thresh are invalid from the end of hold until the new access is complete
ERDA	New EMPTY access from RB $\uparrow$	3.0 ¹		ns	
FRDA	FULL $\downarrow$ access from RB $\uparrow$	3.0 ¹		ns	
ORDA	New DO access from RB $\downarrow$	7.5		ns	
ORDH	Old DO valid from RB $\downarrow$		3.0	ns	
RDCYC	Read cycle time	7.5		ns	
RDWRS	WB $\uparrow$, clearing EMPTY, setup to RB $\downarrow$	3.0 ²		ns	Enabling the read operation
			1.0	ns	Inhibiting the read operation
RDH	RB high phase	3.0		ns	Inactive
RDL	RB low phase	3.0		ns	Active
RPRDA	New RPE access from RB $\downarrow$	9.5		ns	
RPRDH	Old RPE valid from RB $\downarrow$		4.0	ns	
THRDA	EQTH or GETH access from RB $\uparrow$	4.5		ns	

Notes:

- At fast cycles, ERDA and FRDA = MAX (7.5 ns – RDL), 3.0 ns.
- At fast cycles, RDWRS (for enabling read) = MAX (7.5 ns – WRL), 3.0 ns.
- F speed grade devices are 20% slower than the standard numbers.

Asynchronous FIFO Write



Note: The plot shows the normal operation status.

Figure 1-44 • Asynchronous FIFO Write

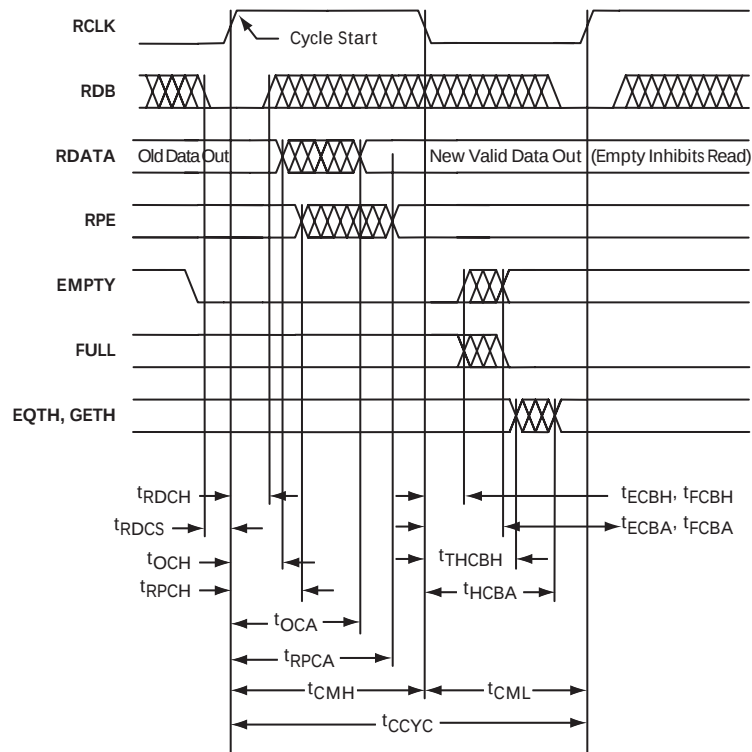
Table 1-45 • $T_J = 0^{\circ}\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
DWRH	DI hold from WB $\uparrow$	1.5		ns	
DWRS	DI setup to WB $\uparrow$	0.5		ns	PARGEN is inactive
DWRS	DI setup to WB $\uparrow$	2.5		ns	PARGEN is active
EWRH, FWRH, THWRH	Old EMPTY, FULL, EQTH, & GETH valid hold time after WB $\uparrow$		0.5	ns	Empty/full/thresh are invalid from the end of hold until the new access is complete
EWRA	EMPTY $\downarrow$ access from WB $\uparrow$	3.0 ¹		ns	
FWRA	New FULL access from WB $\uparrow$	3.0 ¹		ns	
THWRA	EQTH or GETH access from WB $\uparrow$	4.5		ns	
WPDA	WPE access from DI	3.0		ns	WPE is invalid while PARGEN is active
WPDH	WPE hold from DI		1.0	ns	
WRCYC	Cycle time	7.5		ns	
WRRDS	RB $\uparrow$, clearing FULL, setup to WB $\downarrow$	3.0 ²		ns	Enabling the write operation
			1.0		Inhibiting the write operation
WRH	WB high phase	3.0		ns	Inactive
WRL	WB low phase	3.0		ns	Active

Notes:

- At fast cycles, EWRA, FWRA = MAX (7.5 ns – WRL), 3.0 ns.
- At fast cycles, WRRDS (for enabling write) = MAX (7.5 ns – RDL), 3.0 ns.
- F speed grade devices are 20% slower than the standard numbers.

Synchronous FIFO Read, Access Timed Output Strobe (Synchronous Transparent)



Note: The plot shows the normal operation status.

Figure 1-45 • Synchronous FIFO Read, Access Timed Output Strobe (Synchronous Transparent)

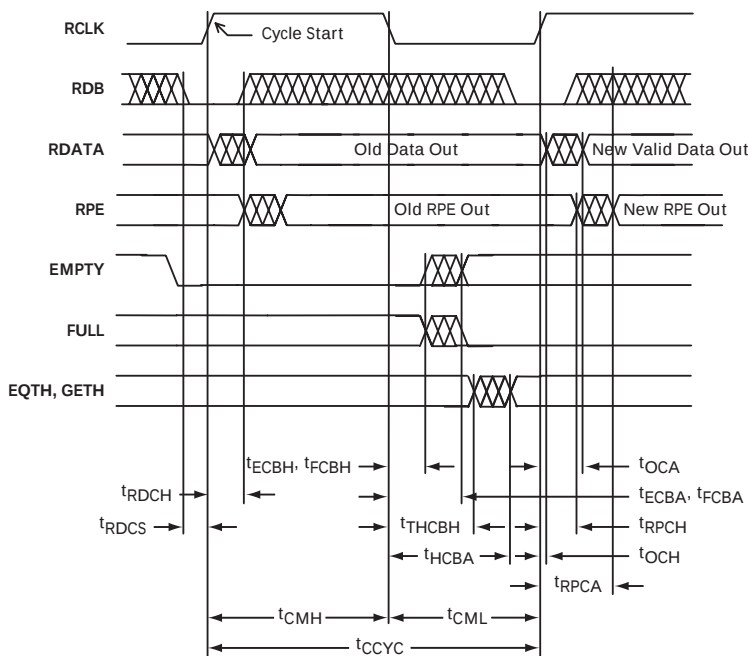
Table 1-46 • $T_J = 0^{\circ}\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
CCYC	Cycle time	7.5		ns	
CMH	Clock high phase	3.0		ns	
CML	Clock low phase	3.0		ns	
ECBA	New EMPTY access from RCLKS ↓	3.0 ¹		ns	
FCBA	FULL ↓ access from RCLKS ↓	3.0 ¹		ns	
ECBH, FCBH, THCBH	Old EMPTY, FULL, EQTH, & GETH valid hold time from RCLKS ↓		1.0	ns	Empty/full/thresh are invalid from the end of hold until the new access is complete
OCA	New DO access from RCLKS ↑	7.5		ns	
OCH	Old DO valid from RCLKS ↑		3.0	ns	
RDCH	RDB hold from RCLKS ↑	0.5		ns	
RDCS	RDB setup to RCLKS ↑	1.0		ns	
RPCA	New RPE access from RCLKS ↑	9.5		ns	
RPCB	Old RPE valid from RCLKS ↑		3.0	ns	
HCBA	EQTH or GETH access from RCLKS ↓	4.5		ns	

Notes:

1. At fast cycles, ECBA and FCBA = MAX (7.5 ns – CMH), 3.0 ns.
2. –F speed grade devices are 20% slower than the standard numbers.

Synchronous FIFO Read, Pipeline Mode Outputs (Synchronous Pipelined)



Note: The plot shows the normal operation status.

Figure 1-46 • Synchronous FIFO Read, Pipeline Mode Outputs (Synchronous Pipelined)

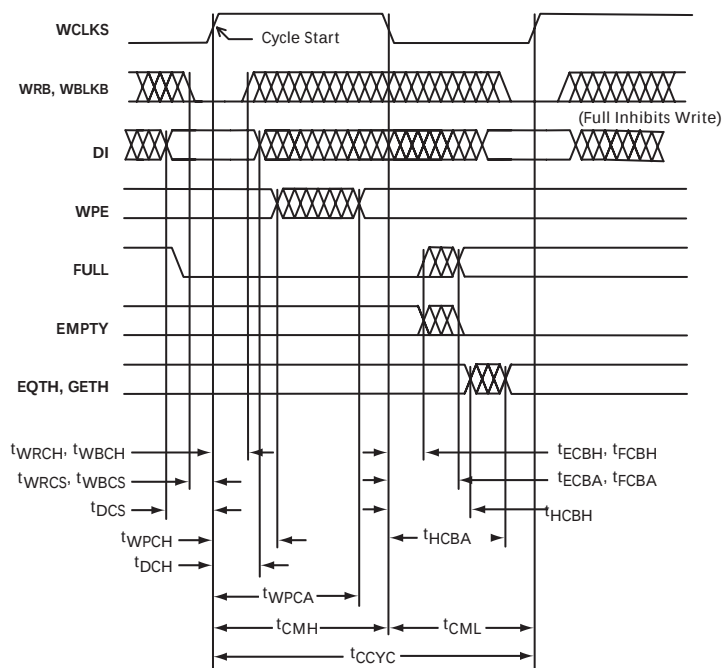
Table 1-47 • $T_J = 0^\circ\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
CCYC	Cycle time	7.5		ns	
CMH	Clock high phase	3.0		ns	
CML	Clock low phase	3.0		ns	
ECBA	New EMPTY access from RCLKS ↓	3.0 ¹		ns	
FCBA	FULL ↓ access from RCLKS ↓	3.0 ¹		ns	
ECBH, FCBH, THCBH	Old EMPTY, FULL, EQTH, & GETH valid hold time from RCLKS ↓		1.0	ns	Empty/full/thresh are invalid from the end of hold until the new access is complete
OCA	New DO access from RCLKS ↑	2.0		ns	
OCH	Old DO valid from RCLKS ↑		0.75	ns	
RDCH	RDB hold from RCLKS ↑	0.5		ns	
RDCS	RDB setup to RCLKS ↑	1.0		ns	
RPCA	New RPE access from RCLKS ↑	4.0		ns	
RPCH	Old RPE valid from RCLKS ↑		1.0	ns	
HCBA	EQTH or GETH access from RCLKS ↓	4.5		ns	

Notes:

- At fast cycles, ECBA and FCBA = MAX (7.5 ns – CMS), 3.0 ns.
- F speed grade devices are 20% slower than the standard numbers.

Synchronous FIFO Write



Note: The plot shows the normal operation status.

Figure 1-47 • Synchronous FIFO Write

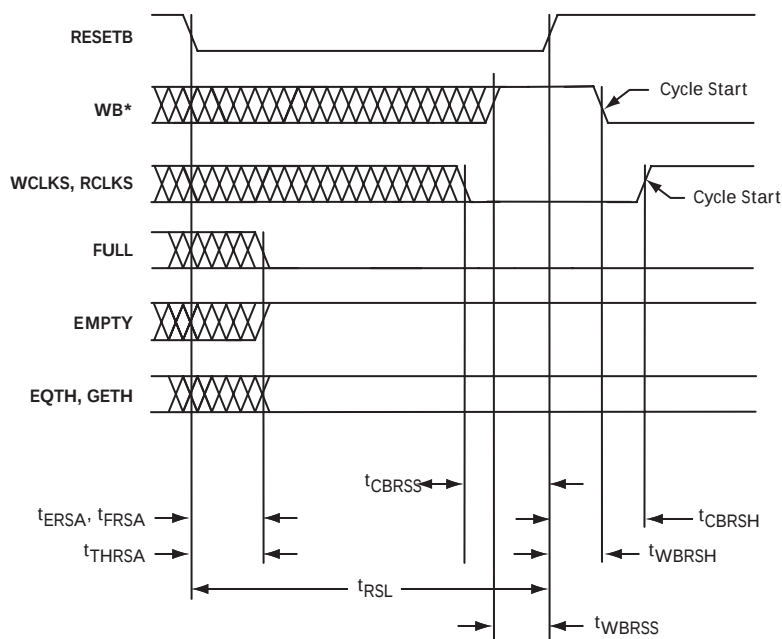
Table 1-48 • $T_j = 0^\circ\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
CCYC	Cycle time	7.5		ns	
CMH	Clock high phase	3.0		ns	
CML	Clock low phase	3.0		ns	
DCH	DI hold from WCLKS $\uparrow$	0.5		ns	
DCS	DI setup to WCLKS $\uparrow$	1.0		ns	
FCBA	New FULL access from WCLKS $\downarrow$	3.0 ¹		ns	
ECBA	EMPTY $\downarrow$ access from WCLKS $\downarrow$	3.0 ¹		ns	
ECBH, FCBH, HCBH	Old EMPTY, FULL, EQTH, & GETH valid hold time from WCLKS $\downarrow$		1.0	ns	Empty/full/thresh are invalid from the end of hold until the new access is complete
HCBA	EQTH or GETH access from WCLKS $\downarrow$	4.5		ns	
WPCA	New WPE access from WCLKS $\uparrow$	3.0		ns	WPE is invalid while PARGEN is active
WPCH	Old WPE valid from WCLKS $\uparrow$		0.5	ns	
WRCH, WBCH	WRB & WBLKB hold from WCLKS $\uparrow$	0.5		ns	
WRCS, WBCS	WRB & WBLKB setup to WCLKS $\uparrow$	1.0		ns	

Notes:

- At fast cycles, ECBA and FCBA = MAX (7.5 ns – CMH), 3.0 ns.
- F speed grade devices are 20% slower than the standard numbers.

FIFO Reset



Note: *The plot shows the normal operation status.

Figure 1-48 • FIFO Reset

Table 1-49 • $T_J = 0^\circ\text{C}$ to 110°C ; $V_{DD} = 2.3\text{V}$ to 2.7V

Symbol t_{xxx}	Description	Min.	Max.	Units	Notes
CBRSH	WCLKS or RCLKS $\uparrow$ hold from RESETB $\uparrow$	1.5		ns	Synchronous mode only
CBRSS	WCLKS or RCLKS $\downarrow$ setup to RESETB $\uparrow$	1.5		ns	Synchronous mode only
ERSA	New EMPTY $\uparrow$ access from RESETB $\downarrow$	3.0		ns	
FRSA	FULL $\downarrow$ access from RESETB $\downarrow$	3.0		ns	
RSL	RESETB low phase	7.5		ns	
THRSA	EQTH or GETH access from RESETB $\downarrow$	4.5		ns	
WBRSH	WB $\downarrow$ hold from RESETB $\uparrow$	1.5		ns	Asynchronous mode only
WBRSS	WB $\uparrow$ setup to RESETB $\uparrow$	1.5		ns	Asynchronous mode only

Note: –F speed grade devices are 20% slower than the standard numbers.

Asynchronous FIFO Full and Empty Transitions

The asynchronous FIFO accepts writes and reads while not full or not empty. When the FIFO is full, all writes are inhibited. Conversely, when the FIFO is empty, all reads are inhibited. A problem is created if the FIFO is written during the transition out of full to not full or read during the transition out of empty to not empty. The exact time at which the write or read operation changes from inhibited to accepted after the read (write) signal which causes the transition from full or empty to not full or not empty is indeterminate. This indeterminate period starts 1 ns after the RB (WB) transition, which deactivates full or not empty and ends 3 ns after the RB (WB) transition for slow cycles. For fast cycles, the indeterminate period ends 3 ns (7.5 ns – RDL (WRL)) after the RB (WB) transition, whichever is later (Table 1-43 on page 1-54).

The timing diagram for write is shown in [Figure 1-41 on page 1-55](#). The timing diagram for read is shown in [Figure 1-42 on page 1-55](#). For basic SRAM configurations, see [Table 1-11 on page 1-22](#).

Enclosed Timing Diagrams – FIFO Mode:

- [Asynchronous FIFO Read](#)
- [Asynchronous FIFO Write](#)
- [Synchronous FIFO Read, Access Timed Output Strobe \(Synchronous Transparent\)](#)
- [Synchronous FIFO Read, Pipeline Mode Outputs \(Synchronous Pipelined\)](#)
- [Synchronous FIFO Write](#)
- [FIFO Reset](#)

Pin Description

User Pins

I/O User Input/Output

The I/O pin functions as an input, output, tristate, or bidirectional buffer. Input and output signal levels are compatible with standard LVTTTL and LVCMOS specifications. Unused I/O pins are configured as inputs with pull-up resistors.

NC No Connect

To maintain compatibility with other Actel ProASICPLUS products, it is recommended that this pin not be connected to the circuitry on the board.

GL Global Pin

Low skew input pin for clock or other global signals. This pin can be configured with an internal pull-up resistor. When it is not connected to the global network or the clock conditioning circuit, it can be configured and used as a normal I/O.

GLMX Global Multiplexing Pin

Low skew input pin for clock or other global signals. This pin can be used in one of two special ways: (Please see Actel's [ProASICPLUS Clock Conditioning Circuits](#) application note for details).

1. When the external feedback option is selected for the PLL block, this pin is routed as the external feedback source to the clock conditioning circuit.
2. In applications where two different signals access the same global net (but at different times) through the use of GLMXx and GLMXLx macros, this pin will be fixed as one of the source pins.

This pin can be configured with an internal pull-up resistor. When it is not connected to the global network or the clock conditioning circuit, it can be configured and used as any normal I/O. If not used, a global will be configured as an input with pull-up.

Dedicated Pins

GND Ground

Common ground supply voltage.

V_{DD} Logic Array Power Supply Pin

2.5V supply voltage.

V_{DDP} I/O Pad Power Supply Pin

2.5V or 3.3V supply voltage.

TMS Test Mode Select

The TMS pin controls the use of boundary-scan circuitry. This pin has an internal pull-up resistor.

TCK Test Clock

Clock input pin for boundary scan (maximum 10 MHz). Actel recommends adding a nominal 20kΩ pull-up resistor to this pin.

TDI Test Data In

Serial input for boundary scan. A dedicated pull-up resistor is included to pull this pin high when not being driven.

TDO Test Data Out

Serial output for boundary scan. Actel recommends adding a nominal 20kΩ pull-up resistor to this pin.

TRST Test Reset Input

Asynchronous, active low input pin for resetting boundary-scan circuitry. This pin has an internal pull-up resistor.

Special Function Pins

RCK Running Clock

A free running clock is needed during programming if the programmer cannot guarantee that TCK will be uninterrupted. If not used, this pin has an internal pull-up and can be left floating.

NPECL User Negative Input

Provides high speed clock or data signals to the PLL block. If unused, leave the pin unconnected.

PPECL User Positive Input

Provides high speed clock or data signals to the PLL block. If unused, leave the pin unconnected.

AVDD PLL Power Supply

Analog V_{DD} should be V_{DD} (core voltage) 2.5V (nominal) and be decoupled from GND with suitable decoupling capacitors to reduce noise. For more information, refer to Actel's [Using ProASICPLUS Clock Conditioning Circuits](#) application note. If the PLLs or clock conditioning circuitry are not used in a design, AVDD should be tied high (2.5V normal).

AGND PLL Power Ground

Analog GND should be 0V and be decoupled from GND with suitable decoupling capacitors to reduce noise. For more information, refer to Actel's [ProASICPLUS Clock Conditioning Circuits](#) application note. If the PLLs or clock conditioning circuitry are not used in a design, AGND should be tied to GND.

V_{PP} **Programming Supply Pin**

This pin may be connected to any voltage between GND and 16.5V during normal operation, or it can be left unconnected.¹ For information on using this pin during programming, see the [Performing Internal In-System Programming Using Actel's ProASIC^{PLUS} Devices](#) application note. Actel recommends floating the pin or connecting it to V_{DDP}.

V_{PN} **Programming Supply Pin**

This pin may be connected to any voltage between GND and -13.8V during normal operation, or it can be left unconnected.² For information on using this pin during programming, see the [Performing Internal In-System Programming Using Actel's ProASIC^{PLUS} Devices](#) application note. Actel recommends floating the pin or connecting it to GND.

Recommended Design Practice for V_{PN}/V_{PP}

ProASIC^{PLUS} Devices – APA450, APA600, APA750, APA1000

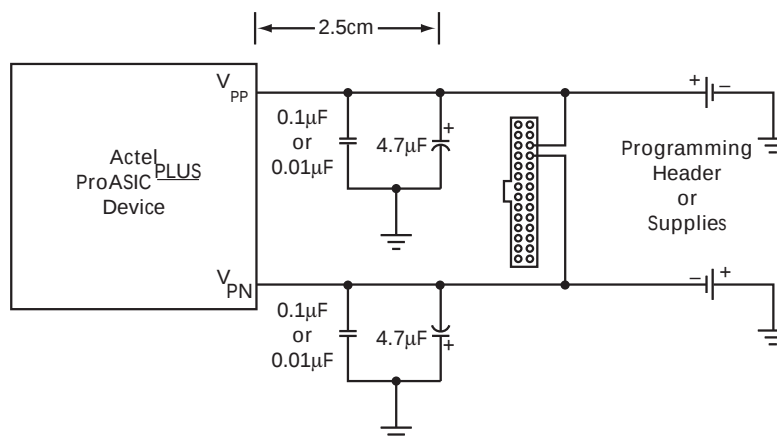
Bypass capacitors are required from V_{PP} to GND and V_{PN} to GND for all ProASIC^{PLUS} devices during programming. During the erase cycle, ProASIC^{PLUS} devices may have current surges on the V_{PP} and V_{PN} power supplies. The only way to maintain the integrity of the power distribution to the ProASIC^{PLUS} device during these current surges is to counteract the inductance of the finite length conductors that distribute the power to the device. This can be accomplished by providing sufficient bypass capacitance between the V_{PP} and V_{PN} pins and GND (using the shortest paths possible). Without sufficient bypass capacitance to counteract the inductance, the V_{PP} and V_{PN} pins may incur a voltage spike beyond the voltage that the device can withstand. This issue applies to all programming configurations.

The power supply voltage limits are defined in the "Supply Voltages" on page 1-30. The solution prevents spikes from damaging the ProASIC^{PLUS} devices. Bypass

capacitors are required for the V_{PP} and V_{PN} pads. Use a 0.01 μ F to 0.1 μ F ceramic capacitor with a 25V or greater rating. To filter low-frequency noise (decoupling), use a 4.7 μ F (low ESR, <1 Ω , tantalum, 25V or greater rating) capacitor. The capacitors should be located as close to the device pins as possible (within 2.5cm is desirable). The smaller, high-frequency capacitor should be placed closer to the device pins than the larger low-frequency capacitor. The same dual capacitor circuit should be used on both the V_{PP} and V_{PN} pins (Figure 1-49 on page 1-64).

ProASIC^{PLUS} Devices – APA075, APA150, APA300

These devices do not require bypass capacitors on the V_{PP} and V_{PN} pins as long as the total combined distance of the programming cable and the trace length on the board is less than or equal to 30 inches. Note: For trace lengths greater than 30 inches, use the bypass capacitor recommendations in the previous section.



(See the "Recommended Design Practice for V_{PN}/V_{PP}" on page 1-64)

Figure 1-49 • ProASIC^{PLUS} V_{PP} and V_{PN} Capacitor Requirements

1. There is a nominal 40k Ω pull-up resistor on V_{PP}
2. There is a nominal 40k Ω pull-down resistor on V_{PN}.

Package Pin Assignments

100-Pin TQFP

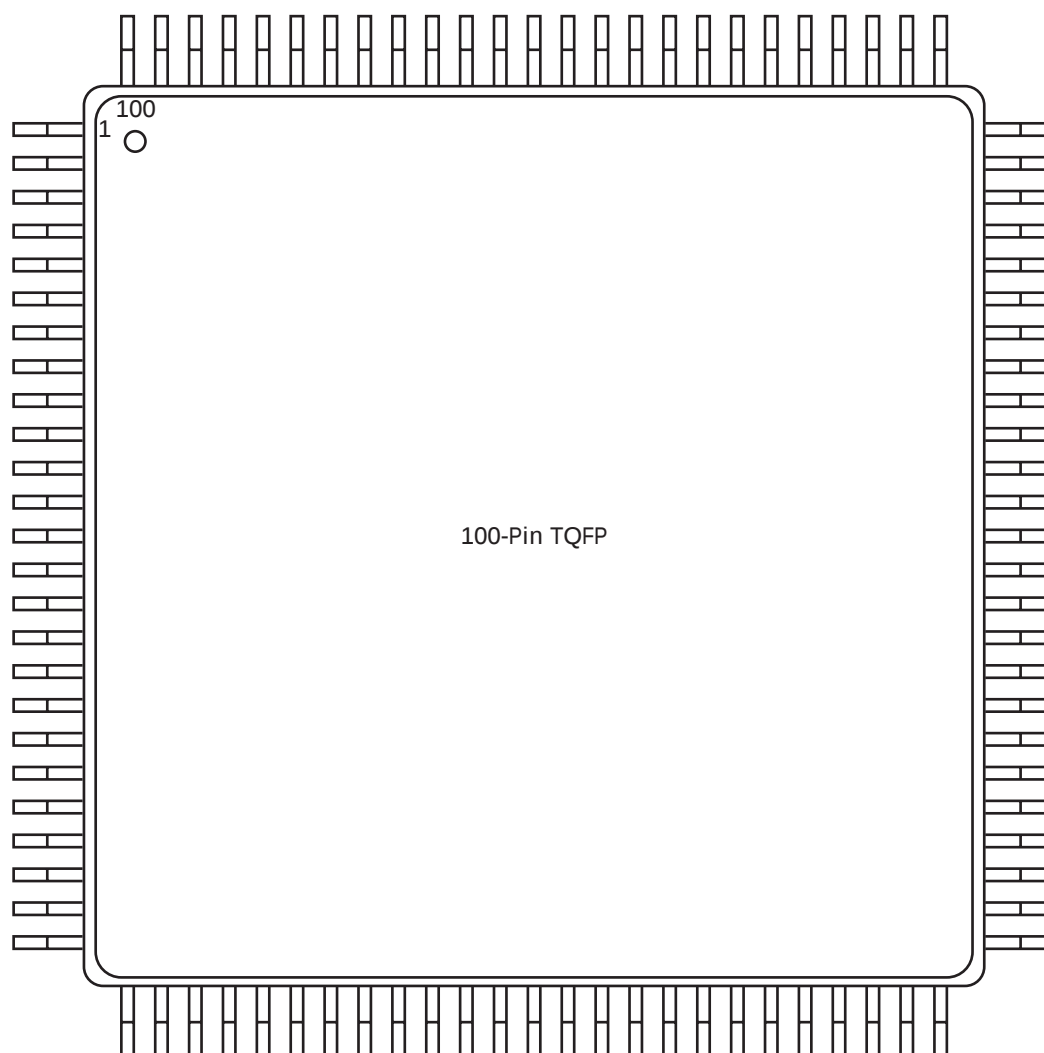


Figure 2-1 • 100-Pin TQFP

Package Pin Assignments

100-Pin TQFP		
Pin Number	APA075 Function	APA150 Function
1	GND	GND
2	I/O	I/O
3	I/O	I/O
4	I/O	I/O
5	I/O	I/O
6	I/O	I/O
7	I/O	I/O
8	I/O	I/O
9	GND	GND
10	I/O (GLMX1)	I/O (GLMX1)
11	GL1	GL1
12	AGND	AGND
13	NPECL1	NPECL1
14	AVDD	AVDD
15	PPECL1 (I/P)	PPECL1 (I/P)
16	GL2	GL2
17	V _{DD}	V _{DD}
18	I/O	I/O
19	I/O	I/O
20	I/O	I/O
21	I/O	I/O
22	I/O	I/O
23	I/O	I/O
24	I/O	I/O
25	GND	GND
26	V _{DDP}	V _{DDP}
27	I/O	I/O
28	I/O	I/O
29	I/O	I/O
30	I/O	I/O
31	I/O	I/O
32	I/O	I/O
33	I/O	I/O
34	I/O	I/O

100-Pin TQFP		
Pin Number	APA075 Function	APA150 Function
35	I/O	I/O
36	I/O	I/O
37	V _{DD}	V _{DD}
38	GND	GND
39	V _{DDP}	V _{DDP}
40	GND	GND
41	I/O	I/O
42	I/O	I/O
43	I/O	I/O
44	I/O	I/O
45	I/O	I/O
46	I/O	I/O
47	TCK	TCK
48	TDI	TDI
49	TMS	TMS
50	V _{DDP}	V _{DDP}
51	GND	GND
52	V _{PP}	V _{PP}
53	V _{PN}	V _{PN}
54	TDO	TDO
55	TRST	TRST
56	RCK	RCK
57	I/O	I/O
58	I/O	I/O
59	I/O	I/O
60	GL3	GL3
61	PPECL2 (I/P)	PPECL2 (I/P)
62	AVDD	AVDD
63	NPECL2	NPECL2
64	AGND	AGND
65	GL4	GL4
66	I/O (GLMX2)	I/O (GLMX2)
67	GND	GND
68	V _{DD}	V _{DD}

100-Pin TQFP		
Pin Number	APA075 Function	APA150 Function
69	I/O	I/O
70	I/O	I/O
71	I/O	I/O
72	I/O	I/O
73	I/O	I/O
74	I/O	I/O
75	GND	GND
76	V _{DDP}	V _{DDP}
77	I/O	I/O
78	I/O	I/O
79	I/O	I/O
80	I/O	I/O
81	I/O	I/O
82	I/O	I/O
83	I/O	I/O
84	I/O	I/O
85	I/O	I/O
86	GND	GND
87	V _{DDP}	V _{DDP}
88	GND	GND
89	V _{DD}	V _{DD}
90	I/O	I/O
91	I/O	I/O
92	I/O	I/O
93	I/O	I/O
94	I/O	I/O
95	I/O	I/O
96	I/O	I/O
97	I/O	I/O
98	I/O	I/O
99	I/O	I/O
100	V _{DDP}	V _{DDP}

144-Pin TQFP

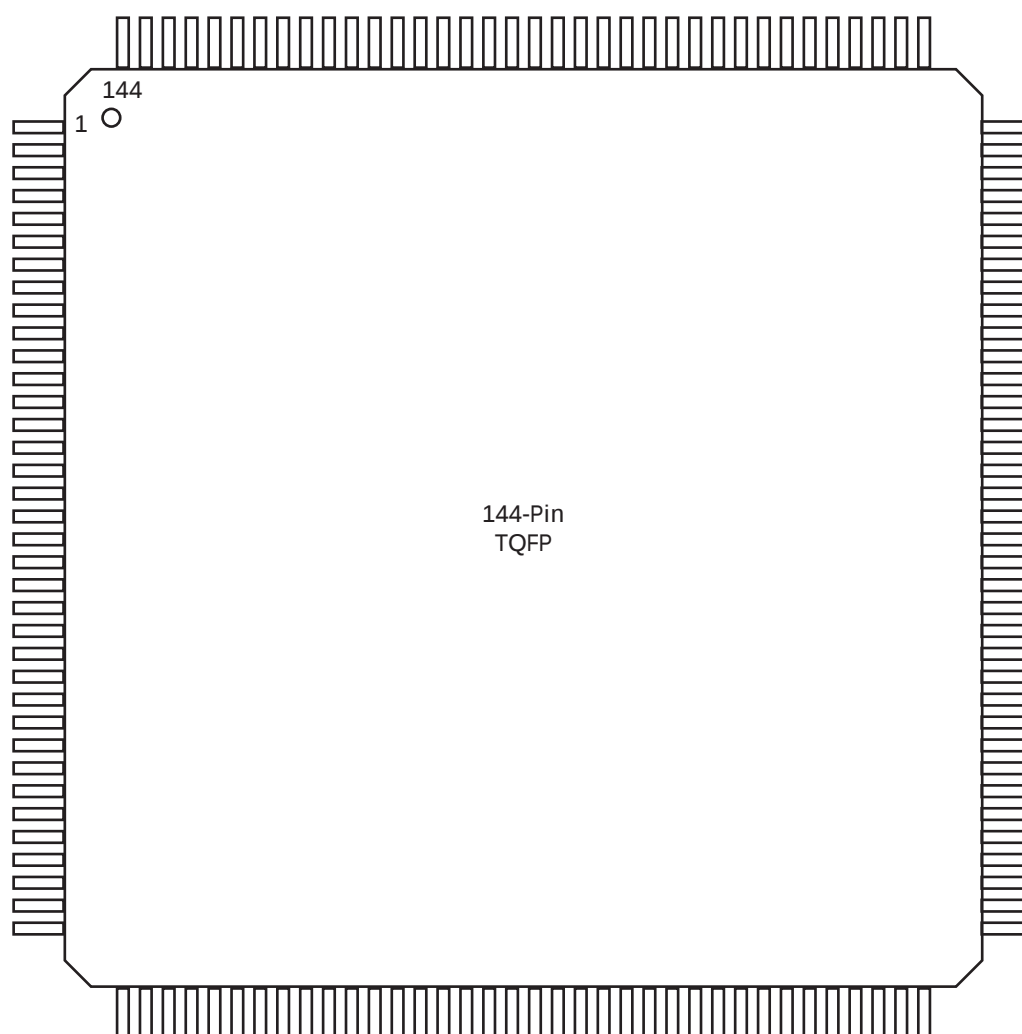


Figure 2-2 • 144-Pin TQFP

Package Pin Assignments

144-Pin TQFP		144-Pin TQFP		144-Pin TQFP		144-Pin TQFP	
Pin Number	APA075 Function	Pin Number	APA075 Function	Pin Number	APA075 Function	Pin Number	APA075 Function
1	I/O	37	I/O	73	V _{PP}	109	I/O
2	I/O	38	I/O	74	V _{PN}	110	I/O
3	I/O	39	I/O	75	TDO	111	I/O
4	I/O	40	I/O	76	TRST	112	I/O
5	I/O	41	I/O	77	RCK	113	I/O
6	I/O	42	I/O	78	I/O	114	I/O
7	I/O	43	I/O	79	I/O	115	I/O
8	I/O	44	I/O	80	I/O	116	I/O
9	V _{DD}	45	V _{DD}	81	V _{DDP}	117	V _{DDP}
10	GND	46	GND	82	GND	118	GND
11	V _{DDP}	47	V _{DDP}	83	I/O	119	V _{DD}
12	I/O	48	I/O	84	I/O	120	I/O
13	I/O	49	I/O	85	I/O	121	I/O
14	I/O	50	I/O	86	I/O	122	I/O
15	GL	51	I/O	87	I/O	123	I/O
16	GL	52	I/O	88	I/O (GLMX)	124	I/O
17	AGND	53	I/O	89	PPECL (I/P)	125	I/O
18	NPECL	54	I/O	90	AVDD	126	I/O
19	AVDD	55	I/O	91	NPECL	127	I/O
20	PPECL (I/P)	56	I/O	92	AGND	128	I/O
21	I/O (GLMX)	57	I/O	93	GL	129	I/O
22	I/O	58	I/O	94	GL	130	I/O
23	I/O	59	I/O	95	I/O	131	I/O
24	I/O	60	I/O	96	I/O	132	I/O
25	I/O	61	I/O	97	I/O	133	I/O
26	I/O	62	V _{DD}	98	V _{DDP}	134	V _{DDP}
27	GND	63	GND	99	GND	135	GND
28	V _{DDP}	64	V _{DDP}	100	V _{DD}	136	V _{DD}
29	I/O	65	I/O	101	I/O	137	I/O
30	I/O	66	I/O	102	I/O	138	I/O
31	I/O	67	I/O	103	I/O	139	I/O
32	I/O	68	I/O	104	I/O	140	I/O
33	I/O	69	TCK	105	I/O	141	I/O
34	I/O	70	TDI	106	I/O	142	I/O
35	I/O	71	TMS	107	I/O	143	I/O
36	I/O	72	NC	108	I/O	144	I/O

208-Pin PQFP

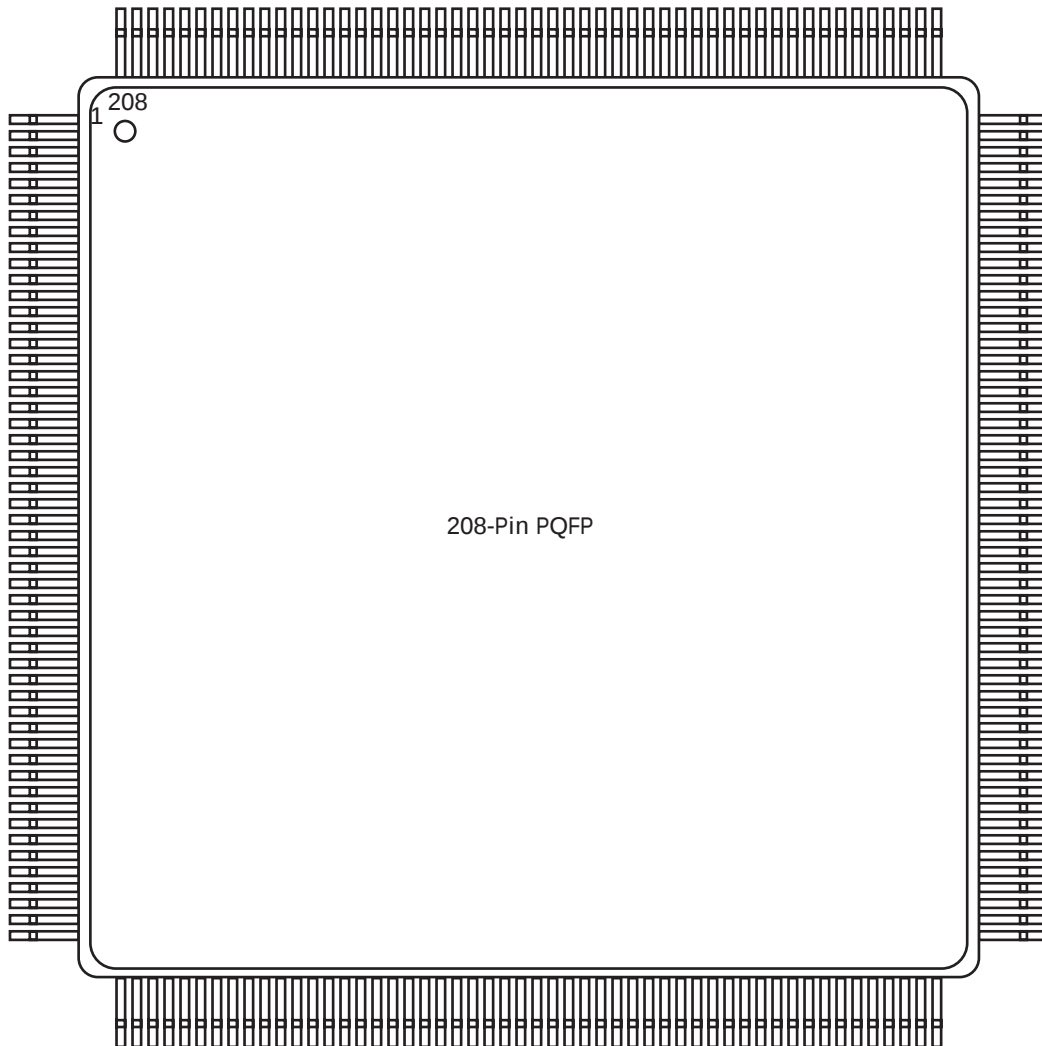


Figure 2-3 • 208-Pin PQFP

208-Pin PQFP							
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
1	GND	GND	GND	GND	GND	GND	GND
2	I/O	I/O	I/O	I/O	I/O	I/O	I/O
3	I/O	I/O	I/O	I/O	I/O	I/O	I/O
4	I/O	I/O	I/O	I/O	I/O	I/O	I/O
5	I/O	I/O	I/O	I/O	I/O	I/O	I/O
6	I/O	I/O	I/O	I/O	I/O	I/O	I/O
7	I/O	I/O	I/O	I/O	I/O	I/O	I/O
8	I/O	I/O	I/O	I/O	I/O	I/O	I/O
9	I/O	I/O	I/O	I/O	I/O	I/O	I/O
10	I/O	I/O	I/O	I/O	I/O	I/O	I/O
11	I/O	I/O	I/O	I/O	I/O	I/O	I/O
12	I/O	I/O	I/O	I/O	I/O	I/O	I/O
13	I/O	I/O	I/O	I/O	I/O	I/O	I/O
14	I/O	I/O	I/O	I/O	I/O	I/O	I/O
15	I/O	I/O	I/O	I/O	I/O	I/O	I/O
16	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
17	GND	GND	GND	GND	GND	GND	GND
18	I/O	I/O	I/O	I/O	I/O	I/O	I/O
19	I/O	I/O	I/O	I/O	I/O	I/O	I/O
20	I/O	I/O	I/O	I/O	I/O	I/O	I/O
21	I/O	I/O	I/O	I/O	I/O	I/O	I/O
22	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
23	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)
24	GL1	GL1	GL1	GL1	GL1	GL1	GL1
25	AGND	AGND	AGND	AGND	AGND	AGND	AGND
26	NPECL1	NPECL1	NPECL1	NPECL1	NPECL1	NPECL1	NPECL1
27	AVDD	AVDD	AVDD	AVDD	AVDD	AVDD	AVDD
28	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)
29	GND	GND	GND	GND	GND	GND	GND
30	GL2	GL2	GL2	GL2	GL2	GL2	GL2
31	I/O	I/O	I/O	I/O	I/O	I/O	I/O
32	I/O	I/O	I/O	I/O	I/O	I/O	I/O
33	I/O	I/O	I/O	I/O	I/O	I/O	I/O
34	I/O	I/O	I/O	I/O	I/O	I/O	I/O
35	I/O	I/O	I/O	I/O	I/O	I/O	I/O

208-Pin PQFP							
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
36	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
37	I/O	I/O	I/O	I/O	I/O	I/O	I/O
38	I/O	I/O	I/O	I/O	I/O	I/O	I/O
39	I/O	I/O	I/O	I/O	I/O	I/O	I/O
40	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
41	GND	GND	GND	GND	GND	GND	GND
42	I/O	I/O	I/O	I/O	I/O	I/O	I/O
43	I/O	I/O	I/O	I/O	I/O	I/O	I/O
44	I/O	I/O	I/O	I/O	I/O	I/O	I/O
45	I/O	I/O	I/O	I/O	I/O	I/O	I/O
46	I/O	I/O	I/O	I/O	I/O	I/O	I/O
47	I/O	I/O	I/O	I/O	I/O	I/O	I/O
48	I/O	I/O	I/O	I/O	I/O	I/O	I/O
49	I/O	I/O	I/O	I/O	I/O	I/O	I/O
50	I/O	I/O	I/O	I/O	I/O	I/O	I/O
51	I/O	I/O	I/O	I/O	I/O	I/O	I/O
52	GND	GND	GND	GND	GND	GND	GND
53	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
54	I/O	I/O	I/O	I/O	I/O	I/O	I/O
55	I/O	I/O	I/O	I/O	I/O	I/O	I/O
56	I/O	I/O	I/O	I/O	I/O	I/O	I/O
57	I/O	I/O	I/O	I/O	I/O	I/O	I/O
58	I/O	I/O	I/O	I/O	I/O	I/O	I/O
59	I/O	I/O	I/O	I/O	I/O	I/O	I/O
60	I/O	I/O	I/O	I/O	I/O	I/O	I/O
61	I/O	I/O	I/O	I/O	I/O	I/O	I/O
62	I/O	I/O	I/O	I/O	I/O	I/O	I/O
63	I/O	I/O	I/O	I/O	I/O	I/O	I/O
64	I/O	I/O	I/O	I/O	I/O	I/O	I/O
65	GND	GND	GND	GND	GND	GND	GND
66	I/O	I/O	I/O	I/O	I/O	I/O	I/O
67	I/O	I/O	I/O	I/O	I/O	I/O	I/O
68	I/O	I/O	I/O	I/O	I/O	I/O	I/O
69	I/O	I/O	I/O	I/O	I/O	I/O	I/O
70	I/O	I/O	I/O	I/O	I/O	I/O	I/O

208-Pin PQFP							
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
71	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
72	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
73	I/O	I/O	I/O	I/O	I/O	I/O	I/O
74	I/O	I/O	I/O	I/O	I/O	I/O	I/O
75	I/O	I/O	I/O	I/O	I/O	I/O	I/O
76	I/O	I/O	I/O	I/O	I/O	I/O	I/O
77	I/O	I/O	I/O	I/O	I/O	I/O	I/O
78	I/O	I/O	I/O	I/O	I/O	I/O	I/O
79	I/O	I/O	I/O	I/O	I/O	I/O	I/O
80	I/O	I/O	I/O	I/O	I/O	I/O	I/O
81	GND	GND	GND	GND	GND	GND	GND
82	I/O	I/O	I/O	I/O	I/O	I/O	I/O
83	I/O	I/O	I/O	I/O	I/O	I/O	I/O
84	I/O	I/O	I/O	I/O	I/O	I/O	I/O
85	I/O	I/O	I/O	I/O	I/O	I/O	I/O
86	I/O	I/O	I/O	I/O	I/O	I/O	I/O
87	I/O	I/O	I/O	I/O	I/O	I/O	I/O
88	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
89	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
90	I/O	I/O	I/O	I/O	I/O	I/O	I/O
91	I/O	I/O	I/O	I/O	I/O	I/O	I/O
92	I/O	I/O	I/O	I/O	I/O	I/O	I/O
93	I/O	I/O	I/O	I/O	I/O	I/O	I/O
94	I/O	I/O	I/O	I/O	I/O	I/O	I/O
95	I/O	I/O	I/O	I/O	I/O	I/O	I/O
96	I/O	I/O	I/O	I/O	I/O	I/O	I/O
97	GND	GND	GND	GND	GND	GND	GND
98	I/O	I/O	I/O	I/O	I/O	I/O	I/O
99	I/O	I/O	I/O	I/O	I/O	I/O	I/O
100	I/O	I/O	I/O	I/O	I/O	I/O	I/O
101	TCK	TCK	TCK	TCK	TCK	TCK	TCK
102	TDI	TDI	TDI	TDI	TDI	TDI	TDI
103	TMS	TMS	TMS	TMS	TMS	TMS	TMS
104	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
105	GND	GND	GND	GND	GND	GND	GND

208-Pin PQFP							
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
106	V _{PP}	V _{PP}	V _{PP}	V _{PP}	V _{PP}	V _{PP}	V _{PP}
107	V _{PN}	V _{PN}	V _{PN}	V _{PN}	V _{PN}	V _{PN}	V _{PN}
108	TDO	TDO	TDO	TDO	TDO	TDO	TDO
109	TRST	TRST	TRST	TRST	TRST	TRST	TRST
110	RCK	RCK	RCK	RCK	RCK	RCK	RCK
111	I/O	I/O	I/O	I/O	I/O	I/O	I/O
112	I/O	I/O	I/O	I/O	I/O	I/O	I/O
113	I/O	I/O	I/O	I/O	I/O	I/O	I/O
114	I/O	I/O	I/O	I/O	I/O	I/O	I/O
115	I/O	I/O	I/O	I/O	I/O	I/O	I/O
116	I/O	I/O	I/O	I/O	I/O	I/O	I/O
117	I/O	I/O	I/O	I/O	I/O	I/O	I/O
118	I/O	I/O	I/O	I/O	I/O	I/O	I/O
119	I/O	I/O	I/O	I/O	I/O	I/O	I/O
120	I/O	I/O	I/O	I/O	I/O	I/O	I/O
121	I/O	I/O	I/O	I/O	I/O	I/O	I/O
122	GND	GND	GND	GND	GND	GND	GND
123	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
124	I/O	I/O	I/O	I/O	I/O	I/O	I/O
125	I/O	I/O	I/O	I/O	I/O	I/O	I/O
126	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
127	I/O	I/O	I/O	I/O	I/O	I/O	I/O
128	GL3	GL3	GL3	GL3	GL3	GL3	GL3
129	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)
130	GND	GND	GND	GND	GND	GND	GND
131	AVDD	AVDD	AVDD	AVDD	AVDD	AVDD	AVDD
132	NPECL2	NPECL2	NPECL2	NPECL2	NPECL2	NPECL2	NPECL2
133	AGND	AGND	AGND	AGND	AGND	AGND	AGND
134	GL4	GL4	GL4	GL4	GL4	GL4	GL4
135	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)
136	I/O	I/O	I/O	I/O	I/O	I/O	I/O
137	I/O	I/O	I/O	I/O	I/O	I/O	I/O
138	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
139	I/O	I/O	I/O	I/O	I/O	I/O	I/O
140	I/O	I/O	I/O	I/O	I/O	I/O	I/O

208-Pin PQFP							
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
141	GND	GND	GND	GND	GND	GND	GND
142	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
143	I/O	I/O	I/O	I/O	I/O	I/O	I/O
144	I/O	I/O	I/O	I/O	I/O	I/O	I/O
145	I/O	I/O	I/O	I/O	I/O	I/O	I/O
146	I/O	I/O	I/O	I/O	I/O	I/O	I/O
147	I/O	I/O	I/O	I/O	I/O	I/O	I/O
148	I/O	I/O	I/O	I/O	I/O	I/O	I/O
149	I/O	I/O	I/O	I/O	I/O	I/O	I/O
150	I/O	I/O	I/O	I/O	I/O	I/O	I/O
151	I/O	I/O	I/O	I/O	I/O	I/O	I/O
152	I/O	I/O	I/O	I/O	I/O	I/O	I/O
153	I/O	I/O	I/O	I/O	I/O	I/O	I/O
154	I/O	I/O	I/O	I/O	I/O	I/O	I/O
155	I/O	I/O	I/O	I/O	I/O	I/O	I/O
156	GND	GND	GND	GND	GND	GND	GND
157	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
158	I/O	I/O	I/O	I/O	I/O	I/O	I/O
159	I/O	I/O	I/O	I/O	I/O	I/O	I/O
160	I/O	I/O	I/O	I/O	I/O	I/O	I/O
161	I/O	I/O	I/O	I/O	I/O	I/O	I/O
162	GND	GND	GND	GND	GND	GND	GND
163	I/O	I/O	I/O	I/O	I/O	I/O	I/O
164	I/O	I/O	I/O	I/O	I/O	I/O	I/O
165	I/O	I/O	I/O	I/O	I/O	I/O	I/O
166	I/O	I/O	I/O	I/O	I/O	I/O	I/O
167	I/O	I/O	I/O	I/O	I/O	I/O	I/O
168	I/O	I/O	I/O	I/O	I/O	I/O	I/O
169	I/O	I/O	I/O	I/O	I/O	I/O	I/O
170	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
171	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
172	I/O	I/O	I/O	I/O	I/O	I/O	I/O
173	I/O	I/O	I/O	I/O	I/O	I/O	I/O
174	I/O	I/O	I/O	I/O	I/O	I/O	I/O
175	I/O	I/O	I/O	I/O	I/O	I/O	I/O
176	I/O	I/O	I/O	I/O	I/O	I/O	I/O

208-Pin PQFP							
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
177	I/O	I/O	I/O	I/O	I/O	I/O	I/O
178	GND	GND	GND	GND	GND	GND	GND
179	I/O	I/O	I/O	I/O	I/O	I/O	I/O
180	I/O	I/O	I/O	I/O	I/O	I/O	I/O
181	I/O	I/O	I/O	I/O	I/O	I/O	I/O
182	I/O	I/O	I/O	I/O	I/O	I/O	I/O
183	I/O	I/O	I/O	I/O	I/O	I/O	I/O
184	I/O	I/O	I/O	I/O	I/O	I/O	I/O
185	I/O	I/O	I/O	I/O	I/O	I/O	I/O
186	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
187	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
188	I/O	I/O	I/O	I/O	I/O	I/O	I/O
189	I/O	I/O	I/O	I/O	I/O	I/O	I/O
190	I/O	I/O	I/O	I/O	I/O	I/O	I/O
191	I/O	I/O	I/O	I/O	I/O	I/O	I/O
192	I/O	I/O	I/O	I/O	I/O	I/O	I/O
193	I/O	I/O	I/O	I/O	I/O	I/O	I/O
194	I/O	I/O	I/O	I/O	I/O	I/O	I/O
195	GND	GND	GND	GND	GND	GND	GND
196	I/O	I/O	I/O	I/O	I/O	I/O	I/O
197	I/O	I/O	I/O	I/O	I/O	I/O	I/O
198	I/O	I/O	I/O	I/O	I/O	I/O	I/O
199	I/O	I/O	I/O	I/O	I/O	I/O	I/O
200	I/O	I/O	I/O	I/O	I/O	I/O	I/O
201	I/O	I/O	I/O	I/O	I/O	I/O	I/O
202	I/O	I/O	I/O	I/O	I/O	I/O	I/O
203	I/O	I/O	I/O	I/O	I/O	I/O	I/O
204	I/O	I/O	I/O	I/O	I/O	I/O	I/O
205	I/O	I/O	I/O	I/O	I/O	I/O	I/O
206	I/O	I/O	I/O	I/O	I/O	I/O	I/O
207	I/O	I/O	I/O	I/O	I/O	I/O	I/O
208	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}

456-Pin PBGA

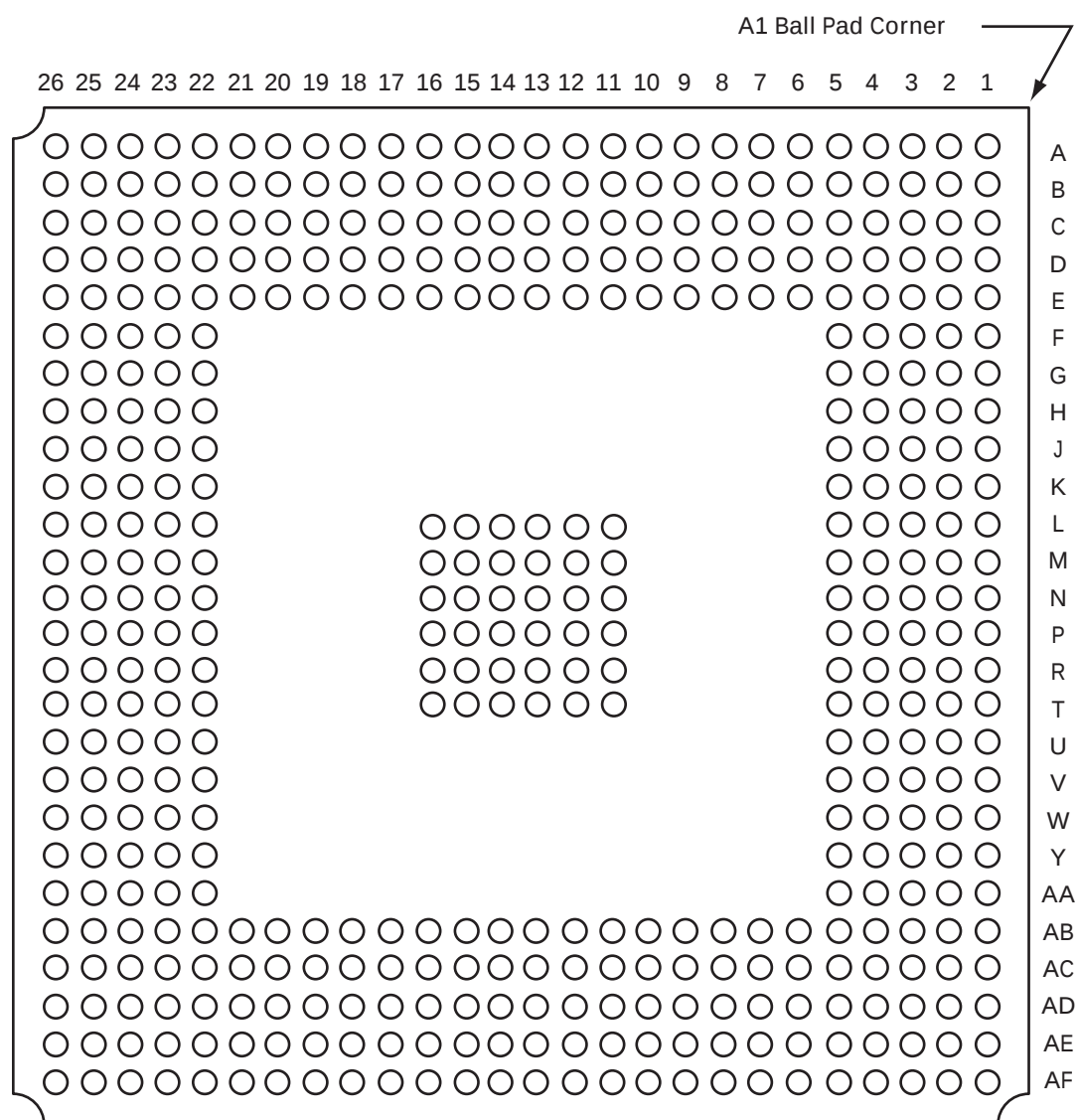


Figure 2-4 • 456-Pin PBGA (Bottom View)

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
A1	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
A2	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
A3	NC	NC	I/O	I/O	I/O	I/O
A4	NC	NC	I/O	I/O	I/O	I/O
A5	NC	NC	I/O	I/O	I/O	I/O
A6	NC	NC	I/O	I/O	I/O	I/O
A7	NC	NC	I/O	I/O	I/O	I/O
A8	I/O	I/O	I/O	I/O	I/O	I/O
A9	I/O	I/O	I/O	I/O	I/O	I/O
A10	I/O	I/O	I/O	I/O	I/O	I/O
A11	I/O	I/O	I/O	I/O	I/O	I/O
A12	I/O	I/O	I/O	I/O	I/O	I/O
A13	I/O	I/O	I/O	I/O	I/O	I/O
A14	I/O	I/O	I/O	I/O	I/O	I/O
A15	I/O	I/O	I/O	I/O	I/O	I/O
A16	I/O	I/O	I/O	I/O	I/O	I/O
A17	I/O	I/O	I/O	I/O	I/O	I/O
A18	I/O	I/O	I/O	I/O	I/O	I/O
A19	I/O	I/O	I/O	I/O	I/O	I/O
A20	NC	NC	I/O	I/O	I/O	I/O
A21	NC	NC	I/O	I/O	I/O	I/O
A22	NC	NC	I/O	I/O	I/O	I/O
A23	NC	NC	I/O	I/O	I/O	I/O
A24	NC	NC	I/O	I/O	I/O	I/O
A25	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
A26	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
B1	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
B2	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
B3	NC	NC	NC	I/O	I/O	I/O
B4	NC	NC	I/O	I/O	I/O	I/O
B5	NC	NC	I/O	I/O	I/O	I/O
B6	NC	NC	I/O	I/O	I/O	I/O
B7	NC	NC	I/O	I/O	I/O	I/O
B8	I/O	I/O	I/O	I/O	I/O	I/O

Package Pin Assignments

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
B9	I/O	I/O	I/O	I/O	I/O	I/O
B10	I/O	I/O	I/O	I/O	I/O	I/O
B11	I/O	I/O	I/O	I/O	I/O	I/O
B12	I/O	I/O	I/O	I/O	I/O	I/O
B13	I/O	I/O	I/O	I/O	I/O	I/O
B14	I/O	I/O	I/O	I/O	I/O	I/O
B15	I/O	I/O	I/O	I/O	I/O	I/O
B16	I/O	I/O	I/O	I/O	I/O	I/O
B17	I/O	I/O	I/O	I/O	I/O	I/O
B18	I/O	I/O	I/O	I/O	I/O	I/O
B19	I/O	I/O	I/O	I/O	I/O	I/O
B20	NC	NC	I/O	I/O	I/O	I/O
B21	NC	NC	I/O	I/O	I/O	I/O
B22	NC	NC	I/O	I/O	I/O	I/O
B23	NC	NC	I/O	I/O	I/O	I/O
B24	NC	NC	I/O	I/O	I/O	I/O
B25	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
B26	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
C1	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
C2	NC	I/O	I/O	I/O	I/O	I/O
C3	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
C4	NC	NC	NC	I/O	I/O	I/O
C5	NC	NC	I/O	I/O	I/O	I/O
C6	NC	NC	I/O	I/O	I/O	I/O
C7	I/O	I/O	I/O	I/O	I/O	I/O
C8	I/O	I/O	I/O	I/O	I/O	I/O
C9	I/O	I/O	I/O	I/O	I/O	I/O
C10	I/O	I/O	I/O	I/O	I/O	I/O
C11	I/O	I/O	I/O	I/O	I/O	I/O
C12	I/O	I/O	I/O	I/O	I/O	I/O
C13	I/O	I/O	I/O	I/O	I/O	I/O
C14	I/O	I/O	I/O	I/O	I/O	I/O
C15	I/O	I/O	I/O	I/O	I/O	I/O
C16	I/O	I/O	I/O	I/O	I/O	I/O

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
C17	I/O	I/O	I/O	I/O	I/O	I/O
C18	I/O	I/O	I/O	I/O	I/O	I/O
C19	I/O	I/O	I/O	I/O	I/O	I/O
C20	I/O	I/O	I/O	I/O	I/O	I/O
C21	NC	NC	I/O	I/O	I/O	I/O
C22	NC	NC	I/O	I/O	I/O	I/O
C23	NC	NC	I/O	I/O	I/O	I/O
C24	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
C25	NC	NC	NC	I/O	I/O	I/O
C26	NC	NC	NC	I/O	I/O	I/O
D1	NC	NC	NC	I/O	I/O	I/O
D2	NC	NC	NC	I/O	I/O	I/O
D3	NC	I/O	I/O	I/O	I/O	I/O
D4	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
D5	NC	NC	I/O	I/O	I/O	I/O
D6	NC	NC	I/O	I/O	I/O	I/O
D7	I/O	I/O	I/O	I/O	I/O	I/O
D8	I/O	I/O	I/O	I/O	I/O	I/O
D9	I/O	I/O	I/O	I/O	I/O	I/O
D10	I/O	I/O	I/O	I/O	I/O	I/O
D11	I/O	I/O	I/O	I/O	I/O	I/O
D12	I/O	I/O	I/O	I/O	I/O	I/O
D13	I/O	I/O	I/O	I/O	I/O	I/O
D14	I/O	I/O	I/O	I/O	I/O	I/O
D15	I/O	I/O	I/O	I/O	I/O	I/O
D16	I/O	I/O	I/O	I/O	I/O	I/O
D17	I/O	I/O	I/O	I/O	I/O	I/O
D18	I/O	I/O	I/O	I/O	I/O	I/O
D19	I/O	I/O	I/O	I/O	I/O	I/O
D20	I/O	I/O	I/O	I/O	I/O	I/O
D21	I/O	I/O	I/O	I/O	I/O	I/O
D22	NC	NC	I/O	I/O	I/O	I/O
D23	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
D24	NC	I/O	I/O	I/O	I/O	I/O

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
D25	NC	NC	NC	I/O	I/O	I/O
D26	NC	NC	NC	I/O	I/O	I/O
E1	NC	I/O	I/O	I/O	I/O	I/O
E2	NC	I/O	I/O	I/O	I/O	I/O
E3	NC	I/O	I/O	I/O	I/O	I/O
E4	NC	I/O	I/O	I/O	I/O	I/O
E5	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E6	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E7	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E8	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E9	I/O	I/O	I/O	I/O	I/O	I/O
E10	I/O	I/O	I/O	I/O	I/O	I/O
E11	I/O	I/O	I/O	I/O	I/O	I/O
E12	I/O	I/O	I/O	I/O	I/O	I/O
E13	I/O	I/O	I/O	I/O	I/O	I/O
E14	I/O	I/O	I/O	I/O	I/O	I/O
E15	I/O	I/O	I/O	I/O	I/O	I/O
E16	I/O	I/O	I/O	I/O	I/O	I/O
E17	I/O	I/O	I/O	I/O	I/O	I/O
E18	I/O	I/O	I/O	I/O	I/O	I/O
E19	I/O	I/O	I/O	I/O	I/O	I/O
E20	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E21	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E22	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E23	NC	I/O	I/O	I/O	I/O	I/O
E24	NC	I/O	I/O	I/O	I/O	I/O
E25	NC	I/O	I/O	I/O	I/O	I/O
E26	NC	I/O	I/O	I/O	I/O	I/O
F1	NC	I/O	I/O	I/O	I/O	I/O
F2	NC	I/O	I/O	I/O	I/O	I/O
F3	NC	I/O	I/O	I/O	I/O	I/O
F4	NC	I/O	I/O	I/O	I/O	I/O
F5	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
F22	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
F23	NC	I/O	I/O	I/O	I/O	I/O
F24	NC	I/O	I/O	I/O	I/O	I/O
F25	NC	I/O	I/O	I/O	I/O	I/O
F26	NC	I/O	I/O	I/O	I/O	I/O
G1	I/O	I/O	I/O	I/O	I/O	I/O
G2	I/O	I/O	I/O	I/O	I/O	I/O
G3	NC	I/O	I/O	I/O	I/O	I/O
G4	NC	I/O	I/O	I/O	I/O	I/O
G5	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
G22	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
G23	NC	I/O	I/O	I/O	I/O	I/O
G24	NC	I/O	I/O	I/O	I/O	I/O
G25	NC	I/O	I/O	I/O	I/O	I/O
G26	I/O	I/O	I/O	I/O	I/O	I/O
H1	I/O	I/O	I/O	I/O	I/O	I/O
H2	I/O	I/O	I/O	I/O	I/O	I/O
H3	I/O	I/O	I/O	I/O	I/O	I/O
H4	I/O	I/O	I/O	I/O	I/O	I/O
H5	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
H22	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
H23	I/O	I/O	I/O	I/O	I/O	I/O
H24	I/O	I/O	I/O	I/O	I/O	I/O
H25	I/O	I/O	I/O	I/O	I/O	I/O
H26	I/O	I/O	I/O	I/O	I/O	I/O
J1	I/O	I/O	I/O	I/O	I/O	I/O
J2	I/O	I/O	I/O	I/O	I/O	I/O
J3	I/O	I/O	I/O	I/O	I/O	I/O
J4	I/O	I/O	I/O	I/O	I/O	I/O
J5	I/O	I/O	I/O	I/O	I/O	I/O
J22	I/O	I/O	I/O	I/O	I/O	I/O
J23	I/O	I/O	I/O	I/O	I/O	I/O
J24	I/O	I/O	I/O	I/O	I/O	I/O
J25	I/O	I/O	I/O	I/O	I/O	I/O
J26	I/O	I/O	I/O	I/O	I/O	I/O

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
K1	I/O	I/O	I/O	I/O	I/O	I/O
K2	I/O	I/O	I/O	I/O	I/O	I/O
K3	I/O	I/O	I/O	I/O	I/O	I/O
K4	I/O	I/O	I/O	I/O	I/O	I/O
K5	I/O	I/O	I/O	I/O	I/O	I/O
K22	I/O	I/O	I/O	I/O	I/O	I/O
K23	I/O	I/O	I/O	I/O	I/O	I/O
K24	I/O	I/O	I/O	I/O	I/O	I/O
K25	I/O	I/O	I/O	I/O	I/O	I/O
K26	I/O	I/O	I/O	I/O	I/O	I/O
L1	I/O	I/O	I/O	I/O	I/O	I/O
L2	I/O	I/O	I/O	I/O	I/O	I/O
L3	I/O	I/O	I/O	I/O	I/O	I/O
L4	I/O	I/O	I/O	I/O	I/O	I/O
L5	I/O	I/O	I/O	I/O	I/O	I/O
L11	GND	GND	GND	GND	GND	GND
L12	GND	GND	GND	GND	GND	GND
L13	GND	GND	GND	GND	GND	GND
L14	GND	GND	GND	GND	GND	GND
L15	GND	GND	GND	GND	GND	GND
L16	GND	GND	GND	GND	GND	GND
L22	I/O	I/O	I/O	I/O	I/O	I/O
L23	I/O	I/O	I/O	I/O	I/O	I/O
L24	I/O	I/O	I/O	I/O	I/O	I/O
L25	I/O	I/O	I/O	I/O	I/O	I/O
L26	I/O	I/O	I/O	I/O	I/O	I/O
M1	GL1	GL1	GL1	GL1	GL1	GL1
M2	GL2	GL2	GL2	GL2	GL2	GL2
M3	I/O	I/O	I/O	I/O	I/O	I/O
M4	I/O	I/O	I/O	I/O	I/O	I/O
M5	I/O	I/O	I/O	I/O	I/O	I/O
M11	GND	GND	GND	GND	GND	GND
M12	GND	GND	GND	GND	GND	GND
M13	GND	GND	GND	GND	GND	GND

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
M14	GND	GND	GND	GND	GND	GND
M15	GND	GND	GND	GND	GND	GND
M16	GND	GND	GND	GND	GND	GND
M22	GL4	GL4	GL4	GL4	GL4	GL4
M23	I/O	I/O	I/O	I/O	I/O	I/O
M24	I/O	I/O	I/O	I/O	I/O	I/O
M25	I/O	I/O	I/O	I/O	I/O	I/O
M26	I/O	I/O	I/O	I/O	I/O	I/O
N1	I/O	I/O	I/O	I/O	I/O	I/O
N2	I/O (GLMX1)	I/O (GLMX)1	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)
N3	AGND	AGND	AGND	AGND	AGND	AGND
N4	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)
N5	AVDD	AVDD	AVDD	AVDD	AVDD	AVDD
N11	GND	GND	GND	GND	GND	GND
N12	GND	GND	GND	GND	GND	GND
N13	GND	GND	GND	GND	GND	GND
N14	GND	GND	GND	GND	GND	GND
N15	GND	GND	GND	GND	GND	GND
N16	GND	GND	GND	GND	GND	GND
N22	NPECL2	NPECL2	NPECL2	NPECL2	NPECL2	NPECL2
N23	GL3	GL3	GL3	GL3	GL3	GL3
N24	AVDD	AVDD	AVDD	AVDD	AVDD	AVDD
N25	I/O (GLMX2)	I/O (GLMX)	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)
N26	AGND	AGND	AGND	AGND	AGND	AGND
P1	I/O	I/O	I/O	I/O	I/O	I/O
P2	I/O	I/O	I/O	I/O	I/O	I/O
P3	I/O	I/O	I/O	I/O	I/O	I/O
P4	I/O	I/O	I/O	I/O	I/O	I/O
P5	NPECL1	NPECL1	NPECL1	NPECL1	NPECL1	NPECL1
P11	GND	GND	GND	GND	GND	GND
P12	GND	GND	GND	GND	GND	GND
P13	GND	GND	GND	GND	GND	GND
P14	GND	GND	GND	GND	GND	GND
P15	GND	GND	GND	GND	GND	GND

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
P16	GND	GND	GND	GND	GND	GND
P22	I/O	I/O	I/O	I/O	I/O	I/O
P23	I/O	I/O	I/O	I/O	I/O	I/O
P24	I/O	I/O	I/O	I/O	I/O	I/O
P25	I/O	I/O	I/O	I/O	I/O	I/O
P26	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)
R1	I/O	I/O	I/O	I/O	I/O	I/O
R2	I/O	I/O	I/O	I/O	I/O	I/O
R3	I/O	I/O	I/O	I/O	I/O	I/O
R4	I/O	I/O	I/O	I/O	I/O	I/O
R5	I/O	I/O	I/O	I/O	I/O	I/O
R11	GND	GND	GND	GND	GND	GND
R12	GND	GND	GND	GND	GND	GND
R13	GND	GND	GND	GND	GND	GND
R14	GND	GND	GND	GND	GND	GND
R15	GND	GND	GND	GND	GND	GND
R16	GND	GND	GND	GND	GND	GND
R22	I/O	I/O	I/O	I/O	I/O	I/O
R23	I/O	I/O	I/O	I/O	I/O	I/O
R24	I/O	I/O	I/O	I/O	I/O	I/O
R25	I/O	I/O	I/O	I/O	I/O	I/O
R26	I/O	I/O	I/O	I/O	I/O	I/O
T1	I/O	I/O	I/O	I/O	I/O	I/O
T2	I/O	I/O	I/O	I/O	I/O	I/O
T3	I/O	I/O	I/O	I/O	I/O	I/O
T4	I/O	I/O	I/O	I/O	I/O	I/O
T5	I/O	I/O	I/O	I/O	I/O	I/O
T11	GND	GND	GND	GND	GND	GND
T12	GND	GND	GND	GND	GND	GND
T13	GND	GND	GND	GND	GND	GND
T14	GND	GND	GND	GND	GND	GND
T15	GND	GND	GND	GND	GND	GND
T16	GND	GND	GND	GND	GND	GND
T22	I/O	I/O	I/O	I/O	I/O	I/O

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
T23	I/O	I/O	I/O	I/O	I/O	I/O
T24	I/O	I/O	I/O	I/O	I/O	I/O
T25	I/O	I/O	I/O	I/O	I/O	I/O
T26	I/O	I/O	I/O	I/O	I/O	I/O
U1	I/O	I/O	I/O	I/O	I/O	I/O
U2	I/O	I/O	I/O	I/O	I/O	I/O
U3	I/O	I/O	I/O	I/O	I/O	I/O
U4	I/O	I/O	I/O	I/O	I/O	I/O
U5	I/O	I/O	I/O	I/O	I/O	I/O
U22	I/O	I/O	I/O	I/O	I/O	I/O
U23	I/O	I/O	I/O	I/O	I/O	I/O
U24	I/O	I/O	I/O	I/O	I/O	I/O
U25	I/O	I/O	I/O	I/O	I/O	I/O
U26	I/O	I/O	I/O	I/O	I/O	I/O
V1	I/O	I/O	I/O	I/O	I/O	I/O
V2	I/O	I/O	I/O	I/O	I/O	I/O
V3	I/O	I/O	I/O	I/O	I/O	I/O
V4	I/O	I/O	I/O	I/O	I/O	I/O
V5	I/O	I/O	I/O	I/O	I/O	I/O
V22	I/O	I/O	I/O	I/O	I/O	I/O
V23	I/O	I/O	I/O	I/O	I/O	I/O
V24	I/O	I/O	I/O	I/O	I/O	I/O
V25	I/O	I/O	I/O	I/O	I/O	I/O
V26	I/O	I/O	I/O	I/O	I/O	I/O
W1	I/O	I/O	I/O	I/O	I/O	I/O
W2	I/O	I/O	I/O	I/O	I/O	I/O
W3	I/O	I/O	I/O	I/O	I/O	I/O
W4	I/O	I/O	I/O	I/O	I/O	I/O
W5	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
W22	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
W23	I/O	I/O	I/O	I/O	I/O	I/O
W24	I/O	I/O	I/O	I/O	I/O	I/O
W25	I/O	I/O	I/O	I/O	I/O	I/O
W26	I/O	I/O	I/O	I/O	I/O	I/O

Package Pin Assignments

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
Y1	I/O	I/O	I/O	I/O	I/O	I/O
Y2	I/O	I/O	I/O	I/O	I/O	I/O
Y3	I/O	I/O	I/O	I/O	I/O	I/O
Y4	NC	I/O	I/O	I/O	I/O	I/O
Y5	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
Y22	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
Y23	NC	I/O	I/O	I/O	I/O	I/O
Y24	NC	I/O	I/O	I/O	I/O	I/O
Y25	NC	I/O	I/O	I/O	I/O	I/O
Y26	NC	I/O	I/O	I/O	I/O	I/O
AA1	I/O	I/O	I/O	I/O	I/O	I/O
AA2	NC	I/O	I/O	I/O	I/O	I/O
AA3	NC	I/O	I/O	I/O	I/O	I/O
AA4	NC	I/O	I/O	I/O	I/O	I/O
AA5	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
AA22	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
AA23	NC	I/O	I/O	I/O	I/O	I/O
AA24	NC	I/O	I/O	I/O	I/O	I/O
AA25	NC	I/O	I/O	I/O	I/O	I/O
AA26	NC	I/O	I/O	I/O	I/O	I/O
AB1	NC	I/O	I/O	I/O	I/O	I/O
AB2	NC	I/O	I/O	I/O	I/O	I/O
AB3	NC	I/O	I/O	I/O	I/O	I/O
AB4	NC	I/O	I/O	I/O	I/O	I/O
AB5	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
AB6	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
AB7	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
AB8	I/O	I/O	I/O	I/O	I/O	I/O
AB9	I/O	I/O	I/O	I/O	I/O	I/O
AB10	I/O	I/O	I/O	I/O	I/O	I/O
AB11	I/O	I/O	I/O	I/O	I/O	I/O
AB12	I/O	I/O	I/O	I/O	I/O	I/O
AB13	I/O	I/O	I/O	I/O	I/O	I/O
AB14	I/O	I/O	I/O	I/O	I/O	I/O

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
AB15	I/O	I/O	I/O	I/O	I/O	I/O
AB16	I/O	I/O	I/O	I/O	I/O	I/O
AB17	I/O	I/O	I/O	I/O	I/O	I/O
AB18	I/O	I/O	I/O	I/O	I/O	I/O
AB19	I/O	I/O	I/O	I/O	I/O	I/O
AB20	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
AB21	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
AB22	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}	V _{DD}
AB23	NC	I/O	I/O	I/O	I/O	I/O
AB24	NC	I/O	I/O	I/O	I/O	I/O
AB25	NC	I/O	I/O	I/O	I/O	I/O
AB26	NC	NC	NC	I/O	I/O	I/O
AC1	NC	I/O	I/O	I/O	I/O	I/O
AC2	NC	I/O	I/O	I/O	I/O	I/O
AC3	NC	I/O	I/O	I/O	I/O	I/O
AC4	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AC5	NC	NC	I/O	I/O	I/O	I/O
AC6	I/O	I/O	I/O	I/O	I/O	I/O
AC7	I/O	I/O	I/O	I/O	I/O	I/O
AC8	I/O	I/O	I/O	I/O	I/O	I/O
AC9	I/O	I/O	I/O	I/O	I/O	I/O
AC10	I/O	I/O	I/O	I/O	I/O	I/O
AC11	I/O	I/O	I/O	I/O	I/O	I/O
AC12	I/O	I/O	I/O	I/O	I/O	I/O
AC13	I/O	I/O	I/O	I/O	I/O	I/O
AC14	I/O	I/O	I/O	I/O	I/O	I/O
AC15	I/O	I/O	I/O	I/O	I/O	I/O
AC16	I/O	I/O	I/O	I/O	I/O	I/O
AC17	I/O	I/O	I/O	I/O	I/O	I/O
AC18	I/O	I/O	I/O	I/O	I/O	I/O
AC19	I/O	I/O	I/O	I/O	I/O	I/O
AC20	I/O	I/O	I/O	I/O	I/O	I/O
AC21	TMS	TMS	TMS	TMS	TMS	TMS
AC22	TDO	TDO	TDO	TDO	TDO	TDO

Package Pin Assignments

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
AC23	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AC24	RCK	RCK	RCK	RCK	RCK	RCK
AC25	NC	NC	I/O	I/O	I/O	I/O
AC26	NC	I/O	I/O	I/O	I/O	I/O
AD1	NC	NC	NC	I/O	I/O	I/O
AD2	NC	I/O	I/O	I/O	I/O	I/O
AD3	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AD4	NC	NC	I/O	I/O	I/O	I/O
AD5	NC	NC	I/O	I/O	I/O	I/O
AD6	NC	NC	I/O	I/O	I/O	I/O
AD7	I/O	I/O	I/O	I/O	I/O	I/O
AD8	I/O	I/O	I/O	I/O	I/O	I/O
AD9	I/O	I/O	I/O	I/O	I/O	I/O
AD10	I/O	I/O	I/O	I/O	I/O	I/O
AD11	I/O	I/O	I/O	I/O	I/O	I/O
AD12	I/O	I/O	I/O	I/O	I/O	I/O
AD13	I/O	I/O	I/O	I/O	I/O	I/O
AD14	I/O	I/O	I/O	I/O	I/O	I/O
AD15	I/O	I/O	I/O	I/O	I/O	I/O
AD16	I/O	I/O	I/O	I/O	I/O	I/O
AD17	I/O	I/O	I/O	I/O	I/O	I/O
AD18	I/O	I/O	I/O	I/O	I/O	I/O
AD19	I/O	I/O	I/O	I/O	I/O	I/O
AD20	NC	NC	I/O	I/O	I/O	I/O
AD21	TCK	TCK	TCK	TCK	TCK	TCK
AD22	V _{PP}	V _{PP}	V _{PP}	V _{PP}	V _{PP}	V _{PP}
AD23	NC	NC	NC	I/O	I/O	I/O
AD24	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AD25	NC	NC	I/O	I/O	I/O	I/O
AD26	NC	NC	I/O	I/O	I/O	I/O
AE1	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AE2	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AE3	NC	NC	I/O	I/O	I/O	I/O
AE4	NC	NC	I/O	I/O	I/O	I/O

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
AE5	NC	NC	I/O	I/O	I/O	I/O
AE6	NC	NC	I/O	I/O	I/O	I/O
AE7	NC	NC	I/O	I/O	I/O	I/O
AE8	I/O	I/O	I/O	I/O	I/O	I/O
AE9	I/O	I/O	I/O	I/O	I/O	I/O
AE10	I/O	I/O	I/O	I/O	I/O	I/O
AE11	I/O	I/O	I/O	I/O	I/O	I/O
AE12	I/O	I/O	I/O	I/O	I/O	I/O
AE13	I/O	I/O	I/O	I/O	I/O	I/O
AE14	I/O	I/O	I/O	I/O	I/O	I/O
AE15	I/O	I/O	I/O	I/O	I/O	I/O
AE16	I/O	I/O	I/O	I/O	I/O	I/O
AE17	I/O	I/O	I/O	I/O	I/O	I/O
AE18	I/O	I/O	I/O	I/O	I/O	I/O
AE19	I/O	I/O	I/O	I/O	I/O	I/O
AE20	NC	NC	I/O	I/O	I/O	I/O
AE21	NC	NC	I/O	I/O	I/O	I/O
AE22	NC	NC	I/O	I/O	I/O	I/O
AE23	V _{PN}	V _{PN}	V _{PN}	V _{PN}	V _{PN}	V _{PN}
AE24	TRST	TRST	TRST	TRST	TRST	TRST
AE25	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AE26	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AF1	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AF2	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AF3	NC	NC	I/O	I/O	I/O	I/O
AF4	NC	NC	I/O	I/O	I/O	I/O
AF5	NC	NC	I/O	I/O	I/O	I/O
AF6	NC	NC	I/O	I/O	I/O	I/O
AF7	NC	NC	I/O	I/O	I/O	I/O
AF8	NC	NC	NC	I/O	I/O	I/O
AF9	I/O	I/O	I/O	I/O	I/O	I/O
AF10	I/O	I/O	I/O	I/O	I/O	I/O
AF11	I/O	I/O	I/O	I/O	I/O	I/O
AF12	I/O	I/O	I/O	I/O	I/O	I/O

456-Pin PBGA						
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function	APA750 Function	APA1000 Function
AF13	I/O	I/O	I/O	I/O	I/O	I/O
AF14	I/O	I/O	I/O	I/O	I/O	I/O
AF15	I/O	I/O	I/O	I/O	I/O	I/O
AF16	I/O	I/O	I/O	I/O	I/O	I/O
AF17	I/O	I/O	I/O	I/O	I/O	I/O
AF18	NC	NC	I/O	I/O	I/O	I/O
AF19	NC	NC	I/O	I/O	I/O	I/O
AF20	NC	NC	I/O	I/O	I/O	I/O
AF21	NC	NC	I/O	I/O	I/O	I/O
AF22	NC	NC	I/O	I/O	I/O	I/O
AF23	TDI	TDI	TDI	TDI	TDI	TDI
AF24	NC	NC	I/O	I/O	I/O	I/O
AF25	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
AF26	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}

144-Pin FBGA

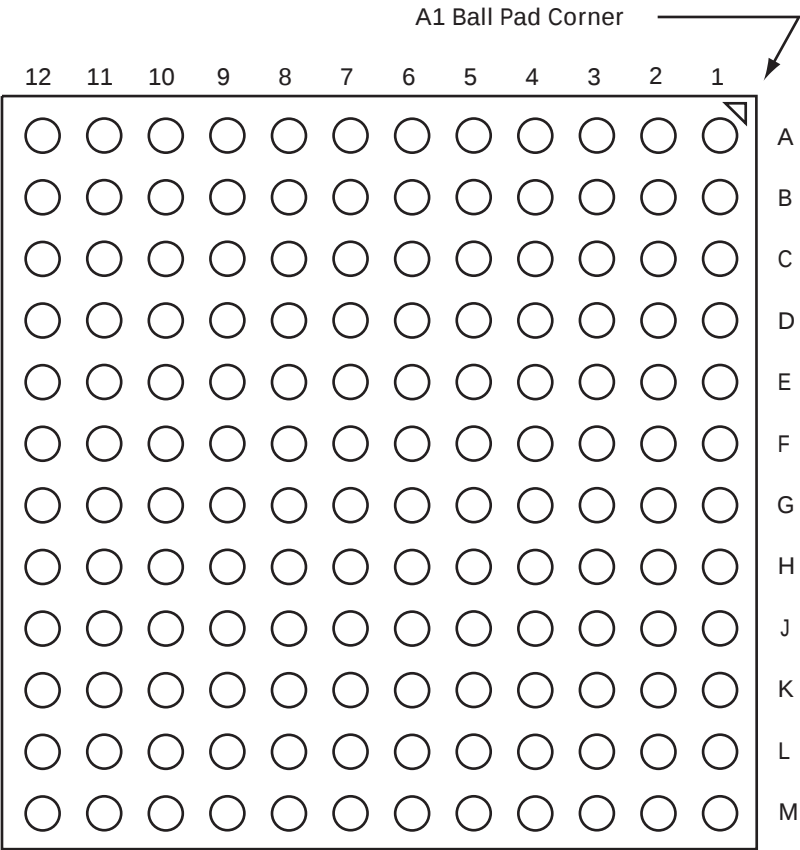


Figure 2-5 • 144-Pin FBGA (Bottom View)

Package Pin Assignments

144-FBGA Pin				
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function
A1	I/O	I/O	I/O	I/O
A2	I/O	I/O	I/O	I/O
A3	I/O	I/O	I/O	I/O
A4	I/O	I/O	I/O	I/O
A5	I/O	I/O	I/O	I/O
A6	GND	GND	GND	GND
A7	I/O	I/O	I/O	I/O
A8	V _{DD}	V _{DD}	V _{DD}	V _{DD}
A9	I/O	I/O	I/O	I/O
A10	I/O	I/O	I/O	I/O
A11	I/O	I/O	I/O	I/O
A12	I/O	I/O	I/O	I/O
B1	I/O	I/O	I/O	I/O
B2	GND	GND	GND	GND
B3	I/O	I/O	I/O	I/O
B4	I/O	I/O	I/O	I/O
B5	I/O	I/O	I/O	I/O
B6	I/O	I/O	I/O	I/O
B7	I/O	I/O	I/O	I/O
B8	I/O	I/O	I/O	I/O
B9	I/O	I/O	I/O	I/O
B10	I/O	I/O	I/O	I/O
B11	GND	GND	GND	GND
B12	I/O	I/O	I/O	I/O
C1	I/O	I/O	I/O	I/O
C2	GL2	GL2	GL2	GL2
C3	I/O	I/O	I/O	I/O
C4	V _{DD}	V _{DD}	V _{DD}	V _{DD}
C5	I/O	I/O	I/O	I/O
C6	I/O	I/O	I/O	I/O
C7	I/O	I/O	I/O	I/O
C8	I/O	I/O	I/O	I/O
C9	I/O	I/O	I/O	I/O
C10	I/O	I/O	I/O	I/O
C11	I/O	I/O	I/O	I/O
C12	I/O	I/O	I/O	I/O
D1	I/O	I/O	I/O	I/O

144-FBGA Pin				
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function
D2	I/O	I/O	I/O	I/O
D3	I/O	I/O	I/O	I/O
D4	I/O	I/O	I/O	I/O
D5	I/O	I/O	I/O	I/O
D6	I/O	I/O	I/O	I/O
D7	I/O	I/O	I/O	I/O
D8	I/O	I/O	I/O	I/O
D9	I/O	I/O	I/O	I/O
D10	I/O	I/O	I/O	I/O
D11	I/O	I/O	I/O	I/O
D12	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)
E1	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E2	I/O	I/O	I/O	I/O
E3	I/O	I/O	I/O	I/O
E4	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
E5	I/O	I/O	I/O	I/O
E6	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
E7	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
E8	AVDD	AVDD	AVDD	AVDD
E9	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
E10	V _{DD}	V _{DD}	V _{DD}	V _{DD}
E11	NPECL2	NPECL2	NPECL2	NPECL2
E12	AGND	AGND	AGND	AGND
F1	GL1	GL1	GL1	GL1
F2	AGND	AGND	AGND	AGND
F3	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)
F4	I/O	I/O	I/O	I/O
F5	GND	GND	GND	GND
F6	GND	GND	GND	GND
F7	GND	GND	GND	GND
F8	I/O	I/O	I/O	I/O
F9	GL4	GL4	GL4	GL4
F10	GND	GND	GND	GND
F11	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)
F12	GL3	GL3	GL3	GL3

144-FBGA Pin				
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function
G1	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)
G2	GND	GND	GND	GND
G3	AVDD	AVDD	AVDD	AVDD
G4	NPECL1	NPECL1	NPECL1	NPECL1
G5	GND	GND	GND	GND
G6	GND	GND	GND	GND
G7	GND	GND	GND	GND
G8	I/O	I/O	I/O	I/O
G9	I/O	I/O	I/O	I/O
G10	I/O	I/O	I/O	I/O
G11	I/O	I/O	I/O	I/O
G12	I/O	I/O	I/O	I/O
H1	V _{DD}	V _{DD}	V _{DD}	V _{DD}
H2	I/O	I/O	I/O	I/O
H3	I/O	I/O	I/O	I/O
H4	I/O	I/O	I/O	I/O
H5	V _{DD}	V _{DD}	V _{DD}	V _{DD}
H6	I/O	I/O	I/O	I/O
H7	I/O	I/O	I/O	I/O
H8	I/O	I/O	I/O	I/O
H9	I/O	I/O	I/O	I/O
H10	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
H11	I/O	I/O	I/O	I/O
H12	V _{DD}	V _{DD}	V _{DD}	V _{DD}
J1	I/O	I/O	I/O	I/O
J2	I/O	I/O	I/O	I/O
J3	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
J4	I/O	I/O	I/O	I/O
J5	I/O	I/O	I/O	I/O
J6	I/O	I/O	I/O	I/O
J7	V _{DD}	V _{DD}	V _{DD}	V _{DD}
J8	TCK	TCK	TCK	TCK
J9	I/O	I/O	I/O	I/O
J10	TDO	TDO	TDO	TDO
J11	I/O	I/O	I/O	I/O
J12	I/O	I/O	I/O	I/O

144-FBGA Pin				
Pin Number	APA075 Function	APA150 Function	APA300 Function	APA450 Function
K1	I/O	I/O	I/O	I/O
K2	I/O	I/O	I/O	I/O
K3	I/O	I/O	I/O	I/O
K4	I/O	I/O	I/O	I/O
K5	I/O	I/O	I/O	I/O
K6	I/O	I/O	I/O	I/O
K7	GND	GND	GND	GND
K8	I/O	I/O	I/O	I/O
K9	I/O	I/O	I/O	I/O
K10	GND	GND	GND	GND
K11	I/O	I/O	I/O	I/O
K12	I/O	I/O	I/O	I/O
L1	GND	GND	GND	GND
L2	I/O	I/O	I/O	I/O
L3	I/O	I/O	I/O	I/O
L4	I/O	I/O	I/O	I/O
L5	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
L6	I/O	I/O	I/O	I/O
L7	I/O	I/O	I/O	I/O
L8	I/O	I/O	I/O	I/O
L9	TMS	TMS	TMS	TMS
L10	RCK	RCK	RCK	RCK
L11	I/O	I/O	I/O	I/O
L12	TRST	TRST	TRST	TRST
M1	I/O	I/O	I/O	I/O
M2	I/O	I/O	I/O	I/O
M3	I/O	I/O	I/O	I/O
M4	I/O	I/O	I/O	I/O
M5	I/O	I/O	I/O	I/O
M6	I/O	I/O	I/O	I/O
M7	I/O	I/O	I/O	I/O
M8	I/O	I/O	I/O	I/O
M9	TDI	TDI	TDI	TDI
M10	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
M11	V _{PP}	V _{PP}	V _{PP}	V _{PP}
M12	V _{PN}	V _{PN}	V _{PN}	V _{PN}

256-Pin FBGA

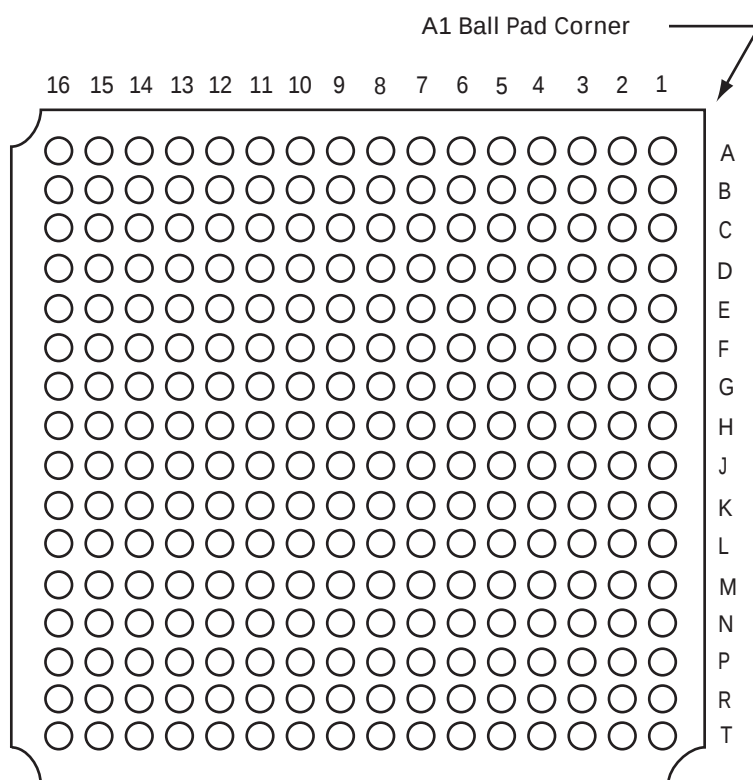


Figure 2-6 • 256-Pin FBGA

256-Pin FBGA				
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function
A1	GND	GND	GND	GND
A2	I/O	I/O	I/O	I/O
A3	I/O	I/O	I/O	I/O
A4	I/O	I/O	I/O	I/O
A5	I/O	I/O	I/O	I/O
A6	I/O	I/O	I/O	I/O
A7	I/O	I/O	I/O	I/O
A8	I/O	I/O	I/O	I/O
A9	I/O	I/O	I/O	I/O
A10	I/O	I/O	I/O	I/O
A11	I/O	I/O	I/O	I/O
A12	I/O	I/O	I/O	I/O
A13	I/O	I/O	I/O	I/O
A14	I/O	I/O	I/O	I/O
A15	I/O	I/O	I/O	I/O
A16	GND	GND	GND	GND
B1	I/O	I/O	I/O	I/O
B2	I/O	I/O	I/O	I/O
B3	I/O	I/O	I/O	I/O
B4	I/O	I/O	I/O	I/O
B5	I/O	I/O	I/O	I/O
B6	I/O	I/O	I/O	I/O
B7	I/O	I/O	I/O	I/O
B8	I/O	I/O	I/O	I/O
B9	I/O	I/O	I/O	I/O
B10	I/O	I/O	I/O	I/O
B11	I/O	I/O	I/O	I/O
B12	I/O	I/O	I/O	I/O
B13	I/O	I/O	I/O	I/O
B14	I/O	I/O	I/O	I/O
B15	I/O	I/O	I/O	I/O
B16	I/O	I/O	I/O	I/O
C1	I/O	I/O	I/O	I/O
C2	I/O	I/O	I/O	I/O
C3	I/O	I/O	I/O	I/O

256-Pin FBGA				
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function
C4	I/O	I/O	I/O	I/O
C5	I/O	I/O	I/O	I/O
C6	I/O	I/O	I/O	I/O
C7	I/O	I/O	I/O	I/O
C8	I/O	I/O	I/O	I/O
C9	I/O	I/O	I/O	I/O
C10	I/O	I/O	I/O	I/O
C11	I/O	I/O	I/O	I/O
C12	I/O	I/O	I/O	I/O
C13	I/O	I/O	I/O	I/O
C14	I/O	I/O	I/O	I/O
C15	I/O	I/O	I/O	I/O
C16	I/O	I/O	I/O	I/O
D1	I/O	I/O	I/O	I/O
D2	I/O	I/O	I/O	I/O
D3	I/O	I/O	I/O	I/O
D4	I/O	I/O	I/O	I/O
D5	I/O	I/O	I/O	I/O
D6	I/O	I/O	I/O	I/O
D7	I/O	I/O	I/O	I/O
D8	I/O	I/O	I/O	I/O
D9	I/O	I/O	I/O	I/O
D10	I/O	I/O	I/O	I/O
D11	I/O	I/O	I/O	I/O
D12	I/O	I/O	I/O	I/O
D13	I/O	I/O	I/O	I/O
D14	I/O	I/O	I/O	I/O
D15	I/O	I/O	I/O	I/O
D16	I/O	I/O	I/O	I/O
E1	I/O	I/O	I/O	I/O
E2	I/O	I/O	I/O	I/O
E3	I/O	I/O	I/O	I/O
E4	I/O	I/O	I/O	I/O
E5	I/O	I/O	I/O	I/O
E6	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}

Package Pin Assignments

256-Pin FBGA				
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function
E7	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
E8	I/O	I/O	I/O	I/O
E9	I/O	I/O	I/O	I/O
E10	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
E11	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
E12	I/O	I/O	I/O	I/O
E13	I/O	I/O	I/O	I/O
E14	I/O	I/O	I/O	I/O
E15	I/O	I/O	I/O	I/O
E16	I/O	I/O	I/O	I/O
F1	I/O	I/O	I/O	I/O
F2	I/O	I/O	I/O	I/O
F3	I/O	I/O	I/O	I/O
F4	I/O	I/O	I/O	I/O
F5	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
F6	GND	GND	GND	GND
F7	V _{DD}	V _{DD}	V _{DD}	V _{DD}
F8	V _{DD}	V _{DD}	V _{DD}	V _{DD}
F9	V _{DD}	V _{DD}	V _{DD}	V _{DD}
F10	V _{DD}	V _{DD}	V _{DD}	V _{DD}
F11	GND	GND	GND	GND
F12	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
F13	I/O	I/O	I/O	I/O
F14	I/O	I/O	I/O	I/O
F15	I/O	I/O	I/O	I/O
F16	I/O	I/O	I/O	I/O
G1	I/O	I/O	I/O	I/O
G2	I/O	I/O	I/O	I/O
G3	I/O	I/O	I/O	I/O
G4	I/O	I/O	I/O	I/O
G5	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
G6	V _{DD}	V _{DD}	V _{DD}	V _{DD}
G7	GND	GND	GND	GND
G8	GND	GND	GND	GND
G9	GND	GND	GND	GND

256-Pin FBGA				
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function
G10	GND	GND	GND	GND
G11	V _{DD}	V _{DD}	V _{DD}	V _{DD}
G12	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
G13	I/O	I/O	I/O	I/O
G14	I/O	I/O	I/O	I/O
G15	I/O	I/O	I/O	I/O
G16	I/O	I/O	I/O	I/O
H1	GL1	GL1	GL1	GL1
H2	NPECL1	NPECL1	NPECL1	NPECL1
H3	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)	I/O (GLMX1)
H4	AGND	AGND	AGND	AGND
H5	I/O	I/O	I/O	I/O
H6	V _{DD}	V _{DD}	V _{DD}	V _{DD}
H7	GND	GND	GND	GND
H8	GND	GND	GND	GND
H9	GND	GND	GND	GND
H10	GND	GND	GND	GND
H11	V _{DD}	V _{DD}	V _{DD}	V _{DD}
H12	I/O	I/O	I/O	I/O
H13	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)	I/O (GLMX2)
H14	NPECL2	NPECL2	NPECL2	NPECL2
H15	AGND	AGND	AGND	AGND
H16	GL4	GL4	GL4	GL4
J1	GL2	GL2	GL2	GL2
J2	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)	PPECL1 (I/P)
J3	AVDD	AVDD	AVDD	AVDD
J4	I/O	I/O	I/O	I/O
J5	I/O	I/O	I/O	I/O
J6	V _{DD}	V _{DD}	V _{DD}	V _{DD}
J7	GND	GND	GND	GND
J8	GND	GND	GND	GND
J9	GND	GND	GND	GND
J10	GND	GND	GND	GND

256-Pin FBGA				
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function
J11	V _{DD}	V _{DD}	V _{DD}	V _{DD}
J12	I/O	I/O	I/O	I/O
J13	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)	PPECL2 (I/P)
J14	I/O	I/O	I/O	I/O
J15	AVDD	AVDD	AVDD	AVDD
J16	GL3	GL3	GL3	GL3
K1	I/O	I/O	I/O	I/O
K2	I/O	I/O	I/O	I/O
K3	I/O	I/O	I/O	I/O
K4	I/O	I/O	I/O	I/O
K5	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
K6	V _{DD}	V _{DD}	V _{DD}	V _{DD}
K7	GND	GND	GND	GND
K8	GND	GND	GND	GND
K9	GND	GND	GND	GND
K10	GND	GND	GND	GND
K11	V _{DD}	V _{DD}	V _{DD}	V _{DD}
K12	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
K13	I/O	I/O	I/O	I/O
K14	I/O	I/O	I/O	I/O
K15	I/O	I/O	I/O	I/O
K16	I/O	I/O	I/O	I/O
L1	I/O	I/O	I/O	I/O
L2	I/O	I/O	I/O	I/O
L3	I/O	I/O	I/O	I/O
L4	I/O	I/O	I/O	I/O
L5	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
L6	GND	GND	GND	GND
L7	V _{DD}	V _{DD}	V _{DD}	V _{DD}
L8	V _{DD}	V _{DD}	V _{DD}	V _{DD}
L9	V _{DD}	V _{DD}	V _{DD}	V _{DD}
L10	V _{DD}	V _{DD}	V _{DD}	V _{DD}
L11	GND	GND	GND	GND
L12	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}

256-Pin FBGA				
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function
L13	I/O	I/O	I/O	I/O
L14	I/O	I/O	I/O	I/O
L15	I/O	I/O	I/O	I/O
L16	I/O	I/O	I/O	I/O
M1	I/O	I/O	I/O	I/O
M2	I/O	I/O	I/O	I/O
M3	I/O	I/O	I/O	I/O
M4	I/O	I/O	I/O	I/O
M5	I/O	I/O	I/O	I/O
M6	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
M7	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
M8	I/O	I/O	I/O	I/O
M9	I/O	I/O	I/O	I/O
M10	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
M11	V _{DDP}	V _{DDP}	V _{DDP}	V _{DDP}
M12	I/O	I/O	I/O	I/O
M13	I/O	I/O	I/O	I/O
M14	I/O	I/O	I/O	I/O
M15	I/O	I/O	I/O	I/O
M16	I/O	I/O	I/O	I/O
N1	I/O	I/O	I/O	I/O
N2	I/O	I/O	I/O	I/O
N3	I/O	I/O	I/O	I/O
N4	I/O	I/O	I/O	I/O
N5	I/O	I/O	I/O	I/O
N6	I/O	I/O	I/O	I/O
N7	I/O	I/O	I/O	I/O
N8	I/O	I/O	I/O	I/O
N9	I/O	I/O	I/O	I/O
N10	I/O	I/O	I/O	I/O
N11	I/O	I/O	I/O	I/O
N12	I/O	I/O	I/O	I/O
N13	I/O	I/O	I/O	I/O
N14	RCK	RCK	RCK	RCK
N15	I/O	I/O	I/O	I/O

Package Pin Assignments

256-Pin FBGA				
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function
N16	I/O	I/O	I/O	I/O
P1	I/O	I/O	I/O	I/O
P2	I/O	I/O	I/O	I/O
P3	I/O	I/O	I/O	I/O
P4	I/O	I/O	I/O	I/O
P5	I/O	I/O	I/O	I/O
P6	I/O	I/O	I/O	I/O
P7	I/O	I/O	I/O	I/O
P8	I/O	I/O	I/O	I/O
P9	I/O	I/O	I/O	I/O
P10	I/O	I/O	I/O	I/O
P11	I/O	I/O	I/O	I/O
P12	I/O	I/O	I/O	I/O
P13	TCK	TCK	TCK	TCK
P14	V _{PP}	V _{PP}	V _{PP}	V _{PP}
P15	TRST	TRST	TRST	TRST
P16	I/O	I/O	I/O	I/O
R1	I/O	I/O	I/O	I/O
R2	I/O	I/O	I/O	I/O
R3	I/O	I/O	I/O	I/O
R4	I/O	I/O	I/O	I/O
R5	I/O	I/O	I/O	I/O
R6	I/O	I/O	I/O	I/O
R7	I/O	I/O	I/O	I/O
R8	I/O	I/O	I/O	I/O
R9	I/O	I/O	I/O	I/O
R10	I/O	I/O	I/O	I/O
R11	I/O	I/O	I/O	I/O
R12	I/O	I/O	I/O	I/O
R13	I/O	I/O	I/O	I/O
R14	TDI	TDI	TDI	TDI
R15	V _{PN}	V _{PN}	V _{PN}	V _{PN}
R16	TDO	TDO	TDO	TDO
T1	GND	GND	GND	GND
T2	I/O	I/O	I/O	I/O

256-Pin FBGA				
Pin Number	APA150 Function	APA300 Function	APA450 Function	APA600 Function
T3	I/O	I/O	I/O	I/O
T4	I/O	I/O	I/O	I/O
T5	I/O	I/O	I/O	I/O
T6	I/O	I/O	I/O	I/O
T7	I/O	I/O	I/O	I/O
T8	I/O	I/O	I/O	I/O
T9	I/O	I/O	I/O	I/O
T10	I/O	I/O	I/O	I/O
T11	I/O	I/O	I/O	I/O
T12	I/O	I/O	I/O	I/O
T13	I/O	I/O	I/O	I/O
T14	I/O	I/O	I/O	I/O
T15	TMS	TMS	TMS	TMS
T16	GND	GND	GND	GND

484-Pin FBGA

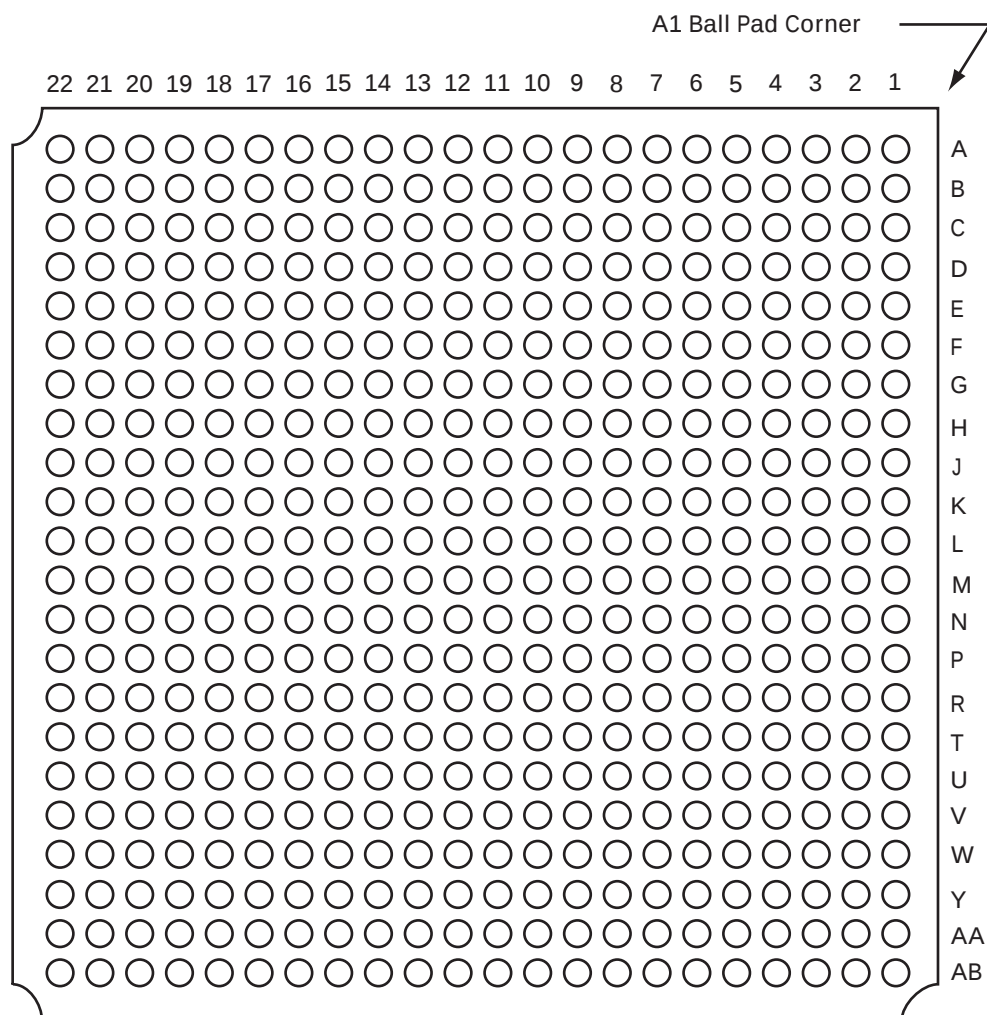


Figure 2-7 • 484-Pin FBGA (Bottom View)

Package Pin Assignments

484-Pin FBGA			484-Pin FBGA			484-Pin FBGA		
Pin Number	APA450 Function	APA600 Function	Pin Number	APA450 Function	APA600 Function	Pin Number	APA450 Function	APA600 Function
A1	GND	GND	B15	I/O	I/O	D7	I/O	I/O
A2	GND	GND	B16	I/O	I/O	D8	I/O	I/O
A3	V _{DDP}	V _{DDP}	B17	I/O	I/O	D9	I/O	I/O
A4	I/O	I/O	B18	I/O	I/O	D10	I/O	I/O
A5	I/O	I/O	B19	I/O	I/O	D11	I/O	I/O
A6	I/O	I/O	B20	I/O	I/O	D12	I/O	I/O
A7	I/O	I/O	B21	V _{DDP}	V _{DDP}	D13	I/O	I/O
A8	I/O	I/O	B22	GND	GND	D14	I/O	I/O
A9	I/O	I/O	C1	V _{DDP}	V _{DDP}	D15	I/O	I/O
A10	I/O	I/O	C2	NC	I/O	D16	I/O	I/O
A11	I/O	I/O	C3	I/O	I/O	D17	I/O	I/O
A12	I/O	I/O	C4	I/O	I/O	D18	I/O	I/O
A13	I/O	I/O	C5	GND	GND	D19	GND	GND
A14	I/O	I/O	C6	I/O	I/O	D20	I/O	I/O
A15	I/O	I/O	C7	I/O	I/O	D21	I/O	I/O
A16	I/O	I/O	C8	V _{DD}	V _{DD}	D22	I/O	I/O
A17	I/O	I/O	C9	V _{DD}	V _{DD}	E1	I/O	I/O
A18	I/O	I/O	C10	I/O	I/O	E2	NC	I/O
A19	I/O	I/O	C11	I/O	I/O	E3	GND	GND
A20	V _{DDP}	V _{DDP}	C12	NC	I/O	E4	I/O	I/O
A21	GND	GND	C13	NC	I/O	E5	I/O	I/O
A22	GND	GND	C14	V _{DD}	V _{DD}	E6	I/O	I/O
B1	GND	GND	C15	V _{DD}	V _{DD}	E7	I/O	I/O
B2	V _{DDP}	V _{DDP}	C16	NC	I/O	E8	I/O	I/O
B3	I/O	I/O	C17	I/O	I/O	E9	I/O	I/O
B4	I/O	I/O	C18	GND	GND	E10	I/O	I/O
B5	I/O	I/O	C19	I/O	I/O	E11	I/O	I/O
B6	I/O	I/O	C20	I/O	I/O	E12	I/O	I/O
B7	I/O	I/O	C21	I/O	I/O	E13	I/O	I/O
B8	I/O	I/O	C22	V _{DDP}	V _{DDP}	E14	I/O	I/O
B9	I/O	I/O	D1	I/O	I/O	E15	I/O	I/O
B10	I/O	I/O	D2	I/O	I/O	E16	I/O	I/O
B11	I/O	I/O	D3	NC	I/O	E17	I/O	I/O
B12	I/O	I/O	D4	GND	GND	E18	I/O	I/O
B13	I/O	I/O	D5	I/O	I/O	E19	I/O	I/O
B14	I/O	I/O	D6	I/O	I/O	E20	GND	GND

484-Pin FBGA			484-Pin FBGA			484-Pin FBGA		
Pin Number	APA450 Function	APA600 Function	Pin Number	APA450 Function	APA600 Function	Pin Number	APA450 Function	APA600 Function
E21	I/O	I/O	G13	I/O	I/O	J5	I/O	I/O
E22	I/O	I/O	G14	I/O	I/O	J6	I/O	I/O
F1	I/O	I/O	G15	I/O	I/O	J7	I/O	I/O
F2	I/O	I/O	G16	I/O	I/O	J8	V _{DDP}	V _{DDP}
F3	I/O	I/O	G17	I/O	I/O	J9	GND	GND
F4	I/O	I/O	G18	I/O	I/O	J10	V _{DD}	V _{DD}
F5	I/O	I/O	G19	I/O	I/O	J11	V _{DD}	V _{DD}
F6	I/O	I/O	G20	I/O	I/O	J12	V _{DD}	V _{DD}
F7	I/O	I/O	G21	I/O	I/O	J13	V _{DD}	V _{DD}
F8	I/O	I/O	G22	I/O	I/O	J14	GND	GND
F9	I/O	I/O	H1	I/O	I/O	J15	V _{DDP}	V _{DDP}
F10	I/O	I/O	H2	I/O	I/O	J16	I/O	I/O
F11	I/O	I/O	H3	V _{DD}	V _{DD}	J17	I/O	I/O
F12	I/O	I/O	H4	I/O	I/O	J18	I/O	I/O
F13	I/O	I/O	H5	I/O	I/O	J19	I/O	I/O
F14	I/O	I/O	H6	I/O	I/O	J20	NC	I/O
F15	I/O	I/O	H7	I/O	I/O	J21	I/O	I/O
F16	I/O	I/O	H8	I/O	I/O	J22	I/O	I/O
F17	I/O	I/O	H9	V _{DDP}	V _{DDP}	K1	I/O	I/O
F18	I/O	I/O	H10	V _{DDP}	V _{DDP}	K2	I/O	I/O
F19	I/O	I/O	H11	I/O	I/O	K3	NC	I/O
F20	I/O	I/O	H12	I/O	I/O	K4	I/O	I/O
F21	I/O	I/O	H13	V _{DDP}	V _{DDP}	K5	I/O	I/O
F22	NC	I/O	H14	V _{DDP}	V _{DDP}	K6	I/O	I/O
G1	I/O	I/O	H15	I/O	I/O	K7	I/O	I/O
G2	I/O	I/O	H16	I/O	I/O	K8	V _{DDP}	V _{DDP}
G3	NC	I/O	H17	I/O	I/O	K9	V _{DD}	V _{DD}
G4	I/O	I/O	H18	I/O	I/O	K10	GND	GND
G5	I/O	I/O	H19	I/O	I/O	K11	GND	GND
G6	I/O	I/O	H20	V _{DD}	V _{DD}	K12	GND	GND
G7	I/O	I/O	H21	I/O	I/O	K13	GND	GND
G8	I/O	I/O	H22	I/O	I/O	K14	V _{DD}	V _{DD}
G9	I/O	I/O	J1	I/O	I/O	K15	V _{DDP}	V _{DDP}
G10	I/O	I/O	J2	I/O	I/O	K16	I/O	I/O
G11	I/O	I/O	J3	NC	I/O	K17	I/O	I/O
G12	I/O	I/O	J4	I/O	I/O	K18	I/O	I/O

Package Pin Assignments

484-Pin FBGA			484-Pin FBGA			484-Pin FBGA		
Pin Number	APA450 Function	APA600 Function	Pin Number	APA450 Function	APA600 Function	Pin Number	APA450 Function	APA600 Function
K19	I/O	I/O	M11	GND	GND	P3	I/O	I/O
K20	I/O	I/O	M12	GND	GND	P4	I/O	I/O
K21	I/O	I/O	M13	GND	GND	P5	I/O	I/O
K22	I/O	I/O	M14	V _{DD}	V _{DD}	P6	I/O	I/O
L1	NC	I/O	M15	I/O	I/O	P7	I/O	I/O
L2	I/O	I/O	M16	PPECL2 (I/P)	PPECL2 (I/P)	P8	V _{DDP}	V _{DDP}
L3	I/O	I/O	M17	I/O	I/O	P9	GND	GND
L4	GL1	GL1	M18	AVDD	AVDD	P10	V _{DD}	V _{DD}
L5	NPECL1	NPECL1	M19	GL3	GL3	P11	V _{DD}	V _{DD}
L6	I/O (GLMX1)	I/O (GLMX1)	M20	I/O	I/O	P12	V _{DD}	V _{DD}
L7	AGND	AGND	M21	I/O	I/O	P13	V _{DD}	V _{DD}
L8	I/O	I/O	M22	I/O	I/O	P14	GND	GND
L9	V _{DD}	V _{DD}	N1	I/O	I/O	P15	V _{DDP}	V _{DDP}
L10	GND	GND	N2	I/O	I/O	P16	I/O	I/O
L11	GND	GND	N3	NC	I/O	P17	I/O	I/O
L12	GND	GND	N4	I/O	I/O	P18	I/O	I/O
L13	GND	GND	N5	I/O	I/O	P19	I/O	I/O
L14	V _{DD}	V _{DD}	N6	I/O	I/O	P20	NC	I/O
L15	I/O	I/O	N7	I/O	I/O	P21	I/O	I/O
L16	I/O (GLMX2)	I/O (GLMX2)	N8	V _{DDP}	V _{DDP}	P22	I/O	I/O
L17	NPECL2	NPECL2	N9	V _{DD}	V _{DD}	R1	I/O	I/O
L18	AGND	AGND	N10	GND	GND	R2	I/O	I/O
L19	GL4	GL4	N11	GND	GND	R3	V _{DD}	V _{DD}
L20	I/O	I/O	N12	GND	GND	R4	I/O	I/O
L21	I/O	I/O	N13	GND	GND	R5	I/O	I/O
L22	I/O	I/O	N14	V _{DD}	V _{DD}	R6	I/O	I/O
M1	I/O	I/O	N15	V _{DDP}	V _{DDP}	R7	I/O	I/O
M2	I/O	I/O	N16	I/O	I/O	R8	I/O	I/O
M3	I/O	I/O	N17	I/O	I/O	R9	V _{DDP}	V _{DDP}
M4	GL2	GL2	N18	I/O	I/O	R10	V _{DDP}	V _{DDP}
M5	PPECL1 (I/P)	PPECL1 (I/P)	N19	I/O	I/O	R11	I/O	I/O
M6	AVDD	AVDD	N20	NC	I/O	R12	I/O	I/O
M7	I/O	I/O	N21	I/O	I/O	R13	V _{DDP}	V _{DDP}
M8	I/O	I/O	N22	I/O	I/O	R14	V _{DDP}	V _{DDP}
M9	V _{DD}	V _{DD}	P1	I/O	I/O	R15	I/O	I/O
M10	GND	GND	P2	I/O	I/O	R16	I/O	I/O

484-Pin FBGA			484-Pin FBGA			484-Pin FBGA		
Pin Number	APA450 Function	APA600 Function	Pin Number	APA450 Function	APA600 Function	Pin Number	APA450 Function	APA600 Function
R17	I/O	I/O	U9	I/O	I/O	W1	NC	I/O
R18	I/O	I/O	U10	I/O	I/O	W2	I/O	I/O
R19	I/O	I/O	U11	I/O	I/O	W3	I/O	I/O
R20	V _{DD}	V _{DD}	U12	I/O	I/O	W4	GND	GND
R21	I/O	I/O	U13	I/O	I/O	W5	I/O	I/O
R22	I/O	I/O	U14	I/O	I/O	W6	I/O	I/O
T1	I/O	I/O	U15	I/O	I/O	W7	I/O	I/O
T2	I/O	I/O	U16	TCK	TCK	W8	I/O	I/O
T3	NC	I/O	U17	V _{PP}	V _{PP}	W9	I/O	I/O
T4	I/O	I/O	U18	TRST	TRST	W10	I/O	I/O
T5	I/O	I/O	U19	I/O	I/O	W11	I/O	I/O
T6	I/O	I/O	U20	NC	I/O	W12	I/O	I/O
T7	I/O	I/O	U21	I/O	I/O	W13	I/O	I/O
T8	I/O	I/O	U22	I/O	I/O	W14	I/O	I/O
T9	I/O	I/O	V1	I/O	I/O	W15	I/O	I/O
T10	I/O	I/O	V2	I/O	I/O	W16	I/O	I/O
T11	I/O	I/O	V3	GND	GND	W17	I/O	I/O
T12	I/O	I/O	V4	I/O	I/O	W18	TMS	TMS
T13	I/O	I/O	V5	I/O	I/O	W19	GND	GND
T14	I/O	I/O	V6	I/O	I/O	W20	NC	I/O
T15	I/O	I/O	V7	I/O	I/O	W21	NC	I/O
T16	I/O	I/O	V8	I/O	I/O	W22	I/O	I/O
T17	RCK	RCK	V9	I/O	I/O	Y1	V _{DDP}	V _{DDP}
T18	I/O	I/O	V10	I/O	I/O	Y2	I/O	I/O
T19	I/O	I/O	V11	I/O	I/O	Y3	I/O	I/O
T20	NC	I/O	V12	I/O	I/O	Y4	I/O	I/O
T21	I/O	I/O	V13	I/O	I/O	Y5	GND	GND
T22	I/O	I/O	V14	I/O	I/O	Y6	I/O	I/O
U1	I/O	I/O	V15	I/O	I/O	Y7	I/O	I/O
U2	I/O	I/O	V16	I/O	I/O	Y8	V _{DD}	V _{DD}
U3	I/O	I/O	V17	TDI	TDI	Y9	V _{DD}	V _{DD}
U4	I/O	I/O	V18	V _{PN}	V _{PN}	Y10	I/O	I/O
U5	I/O	I/O	V19	TDO	TDO	Y11	I/O	I/O
U6	I/O	I/O	V20	GND	GND	Y12	I/O	I/O
U7	I/O	I/O	V21	NC	I/O	Y13	I/O	I/O
U8	I/O	I/O	V22	I/O	I/O	Y14	V _{DD}	V _{DD}

Package Pin Assignments

484-Pin FBGA		
Pin Number	APA450 Function	APA600 Function
Y15	V _{DD}	V _{DD}
Y16	I/O	I/O
Y17	I/O	I/O
Y18	GND	GND
Y19	I/O	I/O
Y20	I/O	I/O
Y21	NC	I/O
Y22	V _{DDP}	V _{DDP}
AA1	GND	GND
AA2	V _{DDP}	V _{DDP}
AA3	I/O	I/O
AA4	I/O	I/O
AA5	I/O	I/O
AA6	I/O	I/O
AA7	I/O	I/O
AA8	I/O	I/O
AA9	I/O	I/O
AA10	I/O	I/O
AA11	I/O	I/O
AA12	I/O	I/O
AA13	I/O	I/O
AA14	I/O	I/O
AA15	I/O	I/O
AA16	I/O	I/O
AA17	I/O	I/O
AA18	NC	I/O
AA19	NC	I/O
AA20	I/O	I/O
AA21	V _{DDP}	V _{DDP}
AA22	GND	GND
AB1	GND	GND
AB2	GND	GND
AB3	V _{DDP}	V _{DDP}
AB4	I/O	I/O
AB5	I/O	I/O
AB6	I/O	I/O

484-Pin FBGA		
Pin Number	APA450 Function	APA600 Function
AB7	I/O	I/O
AB8	I/O	I/O
AB9	I/O	I/O
AB10	I/O	I/O
AB11	I/O	I/O
AB12	I/O	I/O
AB13	I/O	I/O
AB14	I/O	I/O
AB15	I/O	I/O
AB16	I/O	I/O
AB17	I/O	I/O
AB18	NC	I/O
AB19	I/O	I/O
AB20	V _{DDP}	V _{DDP}
AB21	GND	GND
AB22	GND	GND

676-Pin FBGA

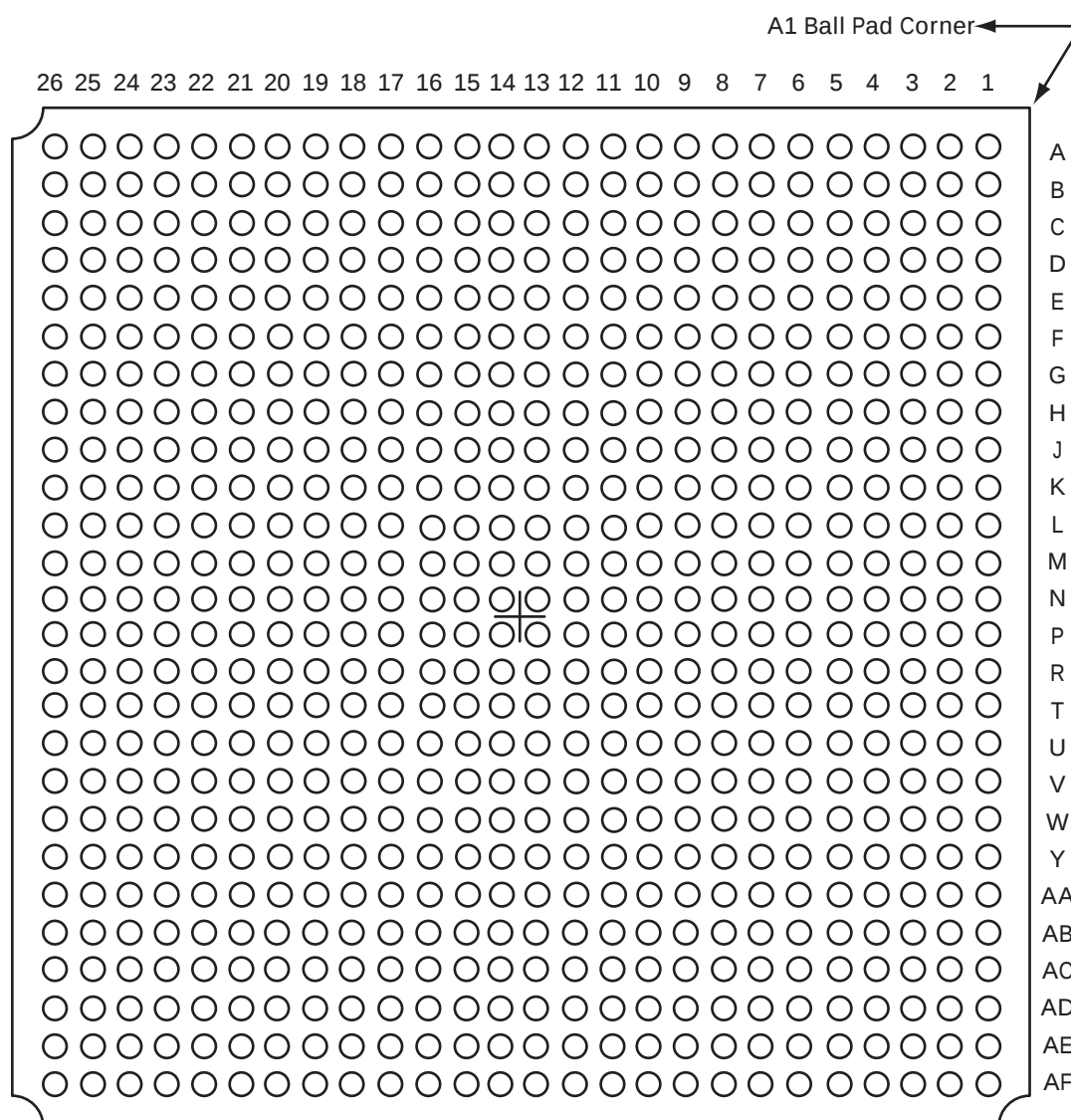


Figure 2-8 • 676-Pin FBGA (Bottom View)

Package Pin Assignments

676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function
A1	GND	GND
A2	GND	GND
A3	I/O	I/O
A4	I/O	I/O
A5	I/O	I/O
A6	I/O	I/O
A7	I/O	I/O
A8	I/O	I/O
A9	I/O	I/O
A10	I/O	I/O
A11	I/O	I/O
A12	I/O	I/O
A13	I/O	I/O
A14	I/O	I/O
A15	I/O	I/O
A16	I/O	I/O
A17	I/O	I/O
A18	I/O	I/O
A19	I/O	I/O
A20	I/O	I/O
A21	I/O	I/O
A22	I/O	I/O
A23	I/O	I/O
A24	I/O	I/O
A25	GND	GND
A26	GND	GND
B1	GND	GND
B2	GND	GND
B3	GND	GND
B4	GND	GND
B5	I/O	I/O
B6	I/O	I/O
B7	I/O	I/O
B8	I/O	I/O
B9	I/O	I/O

676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function
B10	I/O	I/O
B11	I/O	I/O
B12	I/O	I/O
B13	I/O	I/O
B14	I/O	I/O
B15	I/O	I/O
B16	I/O	I/O
B17	I/O	I/O
B18	I/O	I/O
B19	I/O	I/O
B20	I/O	I/O
B21	I/O	I/O
B22	I/O	I/O
B23	I/O	I/O
B24	I/O	I/O
B25	GND	GND
B26	GND	GND
C1	GND	GND
C2	GND	GND
C3	GND	GND
C4	GND	GND
C5	I/O	I/O
C6	I/O	I/O
C7	I/O	I/O
C8	I/O	I/O
C9	I/O	I/O
C10	I/O	I/O
C11	I/O	I/O
C12	I/O	I/O
C13	I/O	I/O
C14	I/O	I/O
C15	I/O	I/O
C16	I/O	I/O
C17	I/O	I/O
C18	I/O	I/O

676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function
C19	I/O	I/O
C20	I/O	I/O
C21	I/O	I/O
C22	I/O	I/O
C23	I/O	I/O
C24	I/O	I/O
C25	I/O	I/O
C26	I/O	I/O
D1	I/O	I/O
D2	I/O	I/O
D3	GND	GND
D4	I/O	I/O
D5	I/O	I/O
D6	I/O	I/O
D7	I/O	I/O
D8	I/O	I/O
D9	I/O	I/O
D10	I/O	I/O
D11	I/O	I/O
D12	I/O	I/O
D13	I/O	I/O
D14	I/O	I/O
D15	I/O	I/O
D16	I/O	I/O
D17	I/O	I/O
D18	I/O	I/O
D19	I/O	I/O
D20	I/O	I/O
D21	I/O	I/O
D22	I/O	I/O
D23	I/O	I/O
D24	I/O	I/O
D25	I/O	I/O
D26	I/O	I/O
E1	I/O	I/O

676-Pin FBGA			676-Pin FBGA			676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function	Pin Number	APA600 Function	APA750 Function	Pin Number	APA600 Function	APA750 Function
E2	I/O	I/O	F11	I/O	I/O	G20	NC	NC
E3	I/O	I/O	F12	I/O	I/O	G21	I/O	I/O
E4	I/O	I/O	F13	I/O	I/O	G22	I/O	I/O
E5	I/O	I/O	F14	I/O	I/O	G23	I/O	I/O
E6	I/O	I/O	F15	I/O	I/O	G24	I/O	I/O
E7	I/O	I/O	F16	I/O	I/O	G25	I/O	I/O
E8	I/O	I/O	F17	I/O	I/O	G26	I/O	I/O
E9	I/O	I/O	F18	I/O	I/O	H1	I/O	I/O
E10	I/O	I/O	F19	I/O	I/O	H2	I/O	I/O
E11	I/O	I/O	F20	I/O	I/O	H3	I/O	I/O
E12	I/O	I/O	F21	I/O	I/O	H4	I/O	I/O
E13	I/O	I/O	F22	I/O	I/O	H5	I/O	I/O
E14	I/O	I/O	F23	I/O	I/O	H6	I/O	I/O
E15	I/O	I/O	F24	I/O	I/O	H7	V _{DDP}	V _{DDP}
E16	I/O	I/O	F25	I/O	I/O	H8	V _{DD}	V _{DD}
E17	I/O	I/O	F26	I/O	I/O	H9	V _{DDP}	V _{DDP}
E18	I/O	I/O	G1	I/O	I/O	H10	V _{DDP}	V _{DDP}
E19	I/O	I/O	G2	I/O	I/O	H11	V _{DDP}	V _{DDP}
E20	I/O	I/O	G3	I/O	I/O	H12	V _{DDP}	V _{DDP}
E21	I/O	I/O	G4	I/O	I/O	H13	V _{DDP}	V _{DDP}
E22	I/O	I/O	G5	I/O	I/O	H14	V _{DDP}	V _{DDP}
E23	I/O	I/O	G6	I/O	I/O	H15	V _{DDP}	V _{DDP}
E24	I/O	I/O	G7	I/O	I/O	H16	V _{DDP}	V _{DDP}
E25	I/O	I/O	G8	V _{DD}	V _{DD}	H17	V _{DDP}	V _{DDP}
E26	I/O	I/O	G9	NC	NC	H18	V _{DDP}	V _{DDP}
F1	I/O	I/O	G10	I/O	I/O	H19	V _{DD}	V _{DD}
F2	I/O	I/O	G11	NC	NC	H20	V _{DD}	V _{DD}
F3	I/O	I/O	G12	I/O	I/O	H21	I/O	I/O
F4	I/O	I/O	G13	NC	NC	H22	I/O	I/O
F5	GND	GND	G14	I/O	I/O	H23	I/O	I/O
F6	I/O	I/O	G15	NC	NC	H24	I/O	I/O
F7	NC	NC	G16	I/O	I/O	H25	I/O	I/O
F8	I/O	I/O	G17	NC	NC	H26	I/O	I/O
F9	I/O	I/O	G18	I/O	I/O	J1	I/O	I/O
F10	I/O	I/O	G19	V _{DDP}	V _{DDP}	J2	I/O	I/O

Package Pin Assignments

676-Pin FBGA			676-Pin FBGA			676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function	Pin Number	APA600 Function	APA750 Function	Pin Number	APA600 Function	APA750 Function
J3	I/O	I/O	K12	GND	GND	L21	I/O	I/O
J4	I/O	I/O	K13	GND	GND	L22	I/O	I/O
J5	I/O	I/O	K14	GND	GND	L23	I/O	I/O
J6	I/O	I/O	K15	GND	GND	L24	I/O	I/O
J7	NC	NC	K16	GND	GND	L25	I/O	I/O
J8	V _{DDP}	V _{DDP}	K17	GND	GND	L26	I/O	I/O
J9	V _{DD}	V _{DD}	K18	V _{DD}	V _{DD}	M1	I/O	I/O
J10	V _{DD}	V _{DD}	K19	V _{DDP}	V _{DDP}	M2	I/O	I/O
J11	V _{DD}	V _{DD}	K20	I/O	I/O	M3	I/O	I/O
J12	V _{DD}	V _{DD}	K21	I/O	I/O	M4	I/O	I/O
J13	V _{DD}	V _{DD}	K22	I/O	I/O	M5	I/O	I/O
J14	V _{DD}	V _{DD}	K23	I/O	I/O	M6	I/O	I/O
J15	V _{DD}	V _{DD}	K24	I/O	I/O	M7	I/O	I/O
J16	V _{DD}	V _{DD}	K25	I/O	I/O	M8	V _{DDP}	V _{DDP}
J17	V _{DD}	V _{DD}	K26	I/O	I/O	M9	V _{DD}	V _{DD}
J18	V _{DD}	V _{DD}	L1	I/O	I/O	M10	GND	GND
J19	V _{DDP}	V _{DDP}	L2	I/O	I/O	M11	GND	GND
J20	NC	NC	L3	I/O	I/O	M12	GND	GND
J21	I/O	I/O	L4	I/O	I/O	M13	GND	GND
J22	I/O	I/O	L5	I/O	I/O	M14	GND	GND
J23	I/O	I/O	L6	I/O	I/O	M15	GND	GND
J24	I/O	I/O	L7	NC	NC	M16	GND	GND
J25	I/O	I/O	L8	V _{DDP}	V _{DDP}	M17	GND	GND
J26	I/O	I/O	L9	V _{DD}	V _{DD}	M18	V _{DD}	V _{DD}
K1	I/O	I/O	L10	GND	GND	M19	V _{DDP}	V _{DDP}
K2	I/O	I/O	L11	GND	GND	M20	I/O	I/O
K3	I/O	I/O	L12	GND	GND	M21	I/O	I/O
K4	I/O	I/O	L13	GND	GND	M22	I/O	I/O
K5	I/O	I/O	L14	GND	GND	M23	I/O	I/O
K6	I/O	I/O	L15	GND	GND	M24	I/O	I/O
K7	I/O	I/O	L16	GND	GND	M25	I/O	I/O
K8	V _{DDP}	V _{DDP}	L17	GND	GND	M26	I/O	I/O
K9	V _{DD}	V _{DD}	L18	V _{DD}	V _{DD}	N1	GL1	GL1
K10	GND	GND	L19	V _{DDP}	V _{DDP}	N2	AGND	AGND
K11	GND	GND	L20	NC	NC	N3	I/O (GLMX1)	I/O (GLMX1)

676-Pin FBGA			676-Pin FBGA			676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function	Pin Number	APA600 Function	APA750 Function	Pin Number	APA600 Function	APA750 Function
N4	I/O	I/O	P13	GND	GND	R22	I/O	I/O
N5	NPECL1	NPECL1	P14	GND	GND	R23	I/O	I/O
N6	I/O	I/O	P15	GND	GND	R24	I/O	I/O
N7	NC	NC	P16	GND	GND	R25	I/O	I/O
N8	V _{DDP}	V _{DDP}	P17	GND	GND	R26	I/O	I/O
N9	V _{DD}	V _{DD}	P18	V _{DD}	V _{DD}	T1	I/O	I/O
N10	GND	GND	P19	V _{DDP}	V _{DDP}	T2	I/O	I/O
N11	GND	GND	P20	I/O	I/O	T3	I/O	I/O
N12	GND	GND	P21	I/O	I/O	T4	I/O	I/O
N13	GND	GND	P22	I/O (GLMX2)	I/O (GLMX2)	T5	I/O	I/O
N14	GND	GND	P23	I/O	I/O	T6	I/O	I/O
N15	GND	GND	P24	PPECL2 (I/P)	PPECL2 (I/P)	T7	I/O	I/O
N16	GND	GND	P25	AVDD	AVDD	T8	V _{DDP}	V _{DDP}
N17	GND	GND	P26	AGND	AGND	T9	V _{DD}	V _{DD}
N18	V _{DD}	V _{DD}	R1	I/O	I/O	T10	GND	GND
N19	V _{DDP}	V _{DDP}	R2	I/O	I/O	T11	GND	GND
N20	NC	NC	R3	I/O	I/O	T12	GND	GND
N21	I/O	I/O	R4	I/O	I/O	T13	GND	GND
N22	GL3	GL3	R5	I/O	I/O	T14	GND	GND
N23	I/O	I/O	R6	I/O	I/O	T15	GND	GND
N24	NPECL2	NPECL2	R7	NC	NC	T16	GND	GND
N25	GL4	GL4	R8	V _{DDP}	V _{DDP}	T17	GND	GND
N26	I/O	I/O	R9	V _{DD}	V _{DD}	T18	V _{DD}	V _{DD}
P1	GL2	GL2	R10	GND	GND	T19	V _{DDP}	V _{DDP}
P2	AVDD	AVDD	R11	GND	GND	T20	I/O	I/O
P3	I/O	I/O	R12	GND	GND	T21	I/O	I/O
P4	I/O	I/O	R13	GND	GND	T22	I/O	I/O
P5	PPECL1 (I/P)	PPECL1 (I/P)	R14	GND	GND	T23	I/O	I/O
P6	I/O	I/O	R15	GND	GND	T24	I/O	I/O
P7	I/O	I/O	R16	GND	GND	T25	I/O	I/O
P8	V _{DDP}	V _{DDP}	R17	GND	GND	T26	I/O	I/O
P9	V _{DD}	V _{DD}	R18	V _{DD}	V _{DD}	U1	I/O	I/O
P10	GND	GND	R19	V _{DDP}	V _{DDP}	U2	I/O	I/O
P11	GND	GND	R20	NC	NC	U3	I/O	I/O
P12	GND	GND	R21	I/O	I/O	U4	I/O	I/O

Package Pin Assignments

676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function
U5	I/O	I/O
U6	I/O	I/O
U7	NC	NC
U8	V _{DDP}	V _{DDP}
U9	V _{DD}	V _{DD}
U10	GND	GND
U11	GND	GND
U12	GND	GND
U13	GND	GND
U14	GND	GND
U15	GND	GND
U16	GND	GND
U17	GND	GND
U18	V _{DD}	V _{DD}
U19	V _{DDP}	V _{DDP}
U20	NC	NC
U21	I/O	I/O
U22	I/O	I/O
U23	I/O	I/O
U24	I/O	I/O
U25	I/O	I/O
U26	I/O	I/O
V1	I/O	I/O
V2	I/O	I/O
V3	I/O	I/O
V4	I/O	I/O
V5	I/O	I/O
V6	I/O	I/O
V7	I/O	I/O
V8	V _{DDP}	V _{DDP}
V9	V _{DD}	V _{DD}
V10	V _{DD}	V _{DD}
V11	V _{DD}	V _{DD}
V12	V _{DD}	V _{DD}
V13	V _{DD}	V _{DD}

676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function
V14	V _{DD}	V _{DD}
V15	V _{DD}	V _{DD}
V16	V _{DD}	V _{DD}
V17	V _{DD}	V _{DD}
V18	V _{DD}	V _{DD}
V19	V _{DDP}	V _{DDP}
V20	I/O	I/O
V21	I/O	I/O
V22	I/O	I/O
V23	I/O	I/O
V24	I/O	I/O
V25	I/O	I/O
V26	I/O	I/O
W1	I/O	I/O
W2	I/O	I/O
W3	I/O	I/O
W4	I/O	I/O
W5	I/O	I/O
W6	I/O	I/O
W7	V _{DD}	V _{DD}
W8	V _{DD}	V _{DD}
W9	V _{DDP}	V _{DDP}
W10	V _{DDP}	V _{DDP}
W11	V _{DDP}	V _{DDP}
W12	V _{DDP}	V _{DDP}
W13	V _{DDP}	V _{DDP}
W14	V _{DDP}	V _{DDP}
W15	V _{DDP}	V _{DDP}
W16	V _{DDP}	V _{DDP}
W17	V _{DDP}	V _{DDP}
W18	V _{DDP}	V _{DDP}
W19	V _{DD}	V _{DD}
W20	V _{DDP}	V _{DDP}
W21	I/O	I/O
W22	I/O	I/O

676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function
W23	I/O	I/O
W24	I/O	I/O
W25	I/O	I/O
W26	I/O	I/O
Y1	I/O	I/O
Y2	I/O	I/O
Y3	I/O	I/O
Y4	I/O	I/O
Y5	I/O	I/O
Y6	I/O	I/O
Y7	I/O	I/O
Y8	V _{DDP}	V _{DDP}
Y9	NC	NC
Y10	I/O	I/O
Y11	NC	NC
Y12	I/O	I/O
Y13	NC	NC
Y14	I/O	I/O
Y15	NC	NC
Y16	I/O	I/O
Y17	NC	NC
Y18	I/O	I/O
Y19	V _{DD}	V _{DD}
Y20	V _{PP}	V _{PP}
Y21	I/O	I/O
Y22	I/O	I/O
Y23	I/O	I/O
Y24	I/O	I/O
Y25	I/O	I/O
Y26	I/O	I/O
AA1	I/O	I/O
AA2	I/O	I/O
AA3	I/O	I/O
AA4	I/O	I/O
AA5	I/O	I/O

676-Pin FBGA			676-Pin FBGA			676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function	Pin Number	APA600 Function	APA750 Function	Pin Number	APA600 Function	APA750 Function
AA6	GND	GND	AB15	I/O	I/O	AC24	I/O	I/O
AA7	I/O	I/O	AB16	I/O	I/O	AC25	I/O	I/O
AA8	I/O	I/O	AB17	I/O	I/O	AC26	I/O	I/O
AA9	I/O	I/O	AB18	I/O	I/O	AD1	I/O	I/O
AA10	I/O	I/O	AB19	I/O	I/O	AD2	I/O	I/O
AA11	I/O	I/O	AB20	I/O	I/O	AD3	I/O	I/O
AA12	I/O	I/O	AB21	TCK	TCK	AD4	I/O	I/O
AA13	I/O	I/O	AB22	TRST	TRST	AD5	I/O	I/O
AA14	I/O	I/O	AB23	I/O	I/O	AD6	I/O	I/O
AA15	I/O	I/O	AB24	I/O	I/O	AD7	I/O	I/O
AA16	I/O	I/O	AB25	I/O	I/O	AD8	I/O	I/O
AA17	I/O	I/O	AB26	I/O	I/O	AD9	I/O	I/O
AA18	I/O	I/O	AC1	I/O	I/O	AD10	I/O	I/O
AA19	I/O	I/O	AC2	I/O	I/O	AD11	I/O	I/O
AA20	I/O	I/O	AC3	I/O	I/O	AD12	I/O	I/O
AA21	TDO	TDO	AC4	I/O	I/O	AD13	I/O	I/O
AA22	GND	GND	AC5	GND	GND	AD14	I/O	I/O
AA23	GND	GND	AC6	I/O	I/O	AD15	I/O	I/O
AA24	I/O	I/O	AC7	I/O	I/O	AD16	I/O	I/O
AA25	I/O	I/O	AC8	I/O	I/O	AD17	I/O	I/O
AA26	I/O	I/O	AC9	GND	GND	AD18	I/O	I/O
AB1	I/O	I/O	AC10	I/O	I/O	AD19	I/O	I/O
AB2	I/O	I/O	AC11	I/O	I/O	AD20	I/O	I/O
AB3	I/O	I/O	AC12	I/O	I/O	AD21	I/O	I/O
AB4	I/O	I/O	AC13	I/O	I/O	AD22	I/O	I/O
AB5	I/O	I/O	AC14	I/O	I/O	AD23	TDI	TDI
AB6	GND	GND	AC15	I/O	I/O	AD24	V _{PN}	V _{PN}
AB7	GND	GND	AC16	I/O	I/O	AD25	I/O	I/O
AB8	I/O	I/O	AC17	I/O	I/O	AD26	I/O	I/O
AB9	I/O	I/O	AC18	I/O	I/O	AE1	GND	GND
AB10	I/O	I/O	AC19	I/O	I/O	AE2	GND	GND
AB11	I/O	I/O	AC20	I/O	I/O	AE3	GND	GND
AB12	I/O	I/O	AC21	I/O	I/O	AE4	I/O	I/O
AB13	I/O	I/O	AC22	TMS	TMS	AE5	I/O	I/O
AB14	I/O	I/O	AC23	RCK	RCK	AE6	I/O	I/O

Package Pin Assignments

676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function
AE7	I/O	I/O
AE8	I/O	I/O
AE9	I/O	I/O
AE10	I/O	I/O
AE11	I/O	I/O
AE12	I/O	I/O
AE13	I/O	I/O
AE14	I/O	I/O
AE15	I/O	I/O
AE16	I/O	I/O
AE17	I/O	I/O
AE18	I/O	I/O
AE19	I/O	I/O
AE20	I/O	I/O
AE21	I/O	I/O
AE22	I/O	I/O
AE23	I/O	I/O
AE24	I/O	I/O
AE25	GND	GND
AE26	GND	GND
AF1	GND	GND
AF2	GND	GND
AF3	GND	GND
AF4	GND	GND
AF5	I/O	I/O
AF6	I/O	I/O
AF7	I/O	I/O
AF8	I/O	I/O
AF9	I/O	I/O
AF10	I/O	I/O
AF11	I/O	I/O
AF12	I/O	I/O
AF13	I/O	I/O
AF14	I/O	I/O
AF15	I/O	I/O

676-Pin FBGA		
Pin Number	APA600 Function	APA750 Function
AF16	I/O	I/O
AF17	I/O	I/O
AF18	I/O	I/O
AF19	I/O	I/O
AF20	I/O	I/O
AF21	I/O	I/O
AF22	I/O	I/O
AF23	I/O	I/O
AF24	I/O	I/O
AF25	GND	GND
AF26	GND	GND

896-Pin FBGA

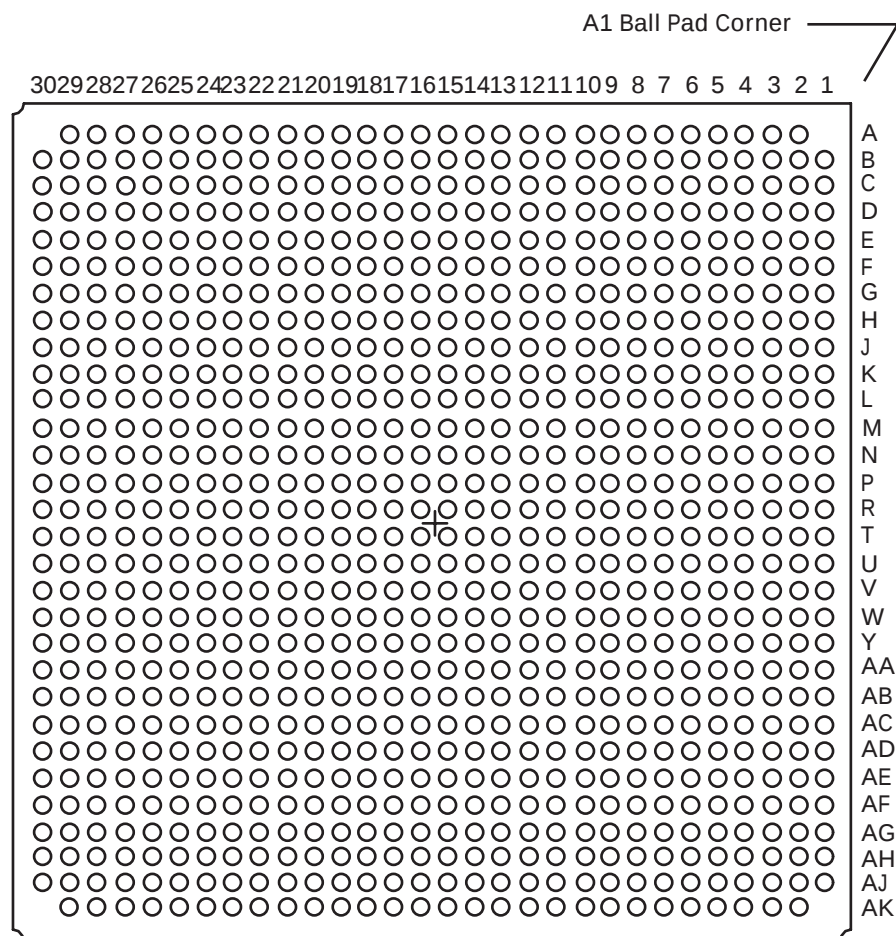


Figure 2-9 • 896-Pin FBGA (Bottom View)

Package Pin Assignments

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
A2	GND	GND
A3	GND	GND
A4	I/O	I/O
A5	GND	GND
A6	I/O	I/O
A7	GND	GND
A8	I/O	I/O
A9	I/O	I/O
A10	I/O	I/O
A11	I/O	I/O
A12	I/O	I/O
A13	I/O	I/O
A14	I/O	I/O
A15	I/O	I/O
A16	I/O	I/O
A17	I/O	I/O
A18	I/O	I/O
A19	I/O	I/O
A20	I/O	I/O
A21	I/O	I/O
A22	I/O	I/O
A23	I/O	I/O
A24	GND	GND
A25	I/O	I/O
A26	GND	GND
A27	I/O	I/O
A28	GND	GND
A29	GND	GND
B1	GND	GND
B2	GND	GND
B3	I/O	I/O
B4	V _{DD}	V _{DD}
B5	I/O	I/O
B6	V _{DD}	V _{DD}

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
B7	I/O	I/O
B8	I/O	I/O
B9	I/O	I/O
B10	I/O	I/O
B11	I/O	I/O
B12	I/O	I/O
B13	I/O	I/O
B14	I/O	I/O
B15	I/O	I/O
B16	I/O	I/O
B17	I/O	I/O
B18	I/O	I/O
B19	I/O	I/O
B20	I/O	I/O
B21	I/O	I/O
B22	I/O	I/O
B23	I/O	I/O
B24	I/O	I/O
B25	V _{DD}	V _{DD}
B26	I/O	I/O
B27	V _{DD}	V _{DD}
B28	I/O	I/O
B29	GND	GND
B30	GND	GND
C1	GND	GND
C2	I/O	I/O
C3	V _{DD}	V _{DD}
C4	I/O	I/O
C5	V _{DDP}	V _{DDP}
C6	I/O	I/O
C7	I/O	I/O
C8	I/O	I/O
C9	I/O	I/O
C10	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
C11	I/O	I/O
C12	I/O	I/O
C13	I/O	I/O
C14	I/O	I/O
C15	I/O	I/O
C16	I/O	I/O
C17	I/O	I/O
C18	I/O	I/O
C19	I/O	I/O
C20	I/O	I/O
C21	I/O	I/O
C22	I/O	I/O
C23	I/O	I/O
C24	I/O	I/O
C25	I/O	I/O
C26	V _{DDP}	V _{DDP}
C27	I/O	I/O
C28	V _{DD}	V _{DD}
C29	NC	I/O
C30	GND	GND
D1	I/O	I/O
D2	V _{DD}	V _{DD}
D3	I/O	I/O
D4	GND	GND
D5	I/O	I/O
D6	I/O	I/O
D7	I/O	I/O
D8	I/O	I/O
D9	I/O	I/O
D10	I/O	I/O
D11	I/O	I/O
D12	I/O	I/O
D13	I/O	I/O
D14	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
D15	I/O	I/O
D16	I/O	I/O
D17	I/O	I/O
D18	I/O	I/O
D19	I/O	I/O
D20	I/O	I/O
D21	I/O	I/O
D22	I/O	I/O
D23	I/O	I/O
D24	I/O	I/O
D25	I/O	I/O
D26	I/O	I/O
D27	GND	GND
D28	I/O	I/O
D29	V _{DD}	V _{DD}
D30	I/O	I/O
E1	GND	GND
E2	I/O	I/O
E3	V _{DDP}	V _{DDP}
E4	I/O	I/O
E5	V _{DD}	V _{DD}
E6	I/O	I/O
E7	V _{DDP}	V _{DDP}
E8	I/O	I/O
E9	I/O	I/O
E10	I/O	I/O
E11	I/O	I/O
E12	I/O	I/O
E13	I/O	I/O
E14	I/O	I/O
E15	I/O	I/O
E16	I/O	I/O
E17	I/O	I/O
E18	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
E19	I/O	I/O
E20	I/O	I/O
E21	I/O	I/O
E22	I/O	I/O
E23	I/O	I/O
E24	V _{DDP}	V _{DDP}
E25	I/O	I/O
E26	V _{DD}	V _{DD}
E27	I/O	I/O
E28	V _{DDP}	V _{DDP}
E29	I/O	I/O
E30	GND	GND
F1	I/O	I/O
F2	V _{DD}	V _{DD}
F3	I/O	I/O
F4	I/O	I/O
F5	I/O	I/O
F6	GND	GND
F7	I/O	I/O
F8	I/O	I/O
F9	I/O	I/O
F10	I/O	I/O
F11	I/O	I/O
F12	I/O	I/O
F13	I/O	I/O
F14	I/O	I/O
F15	I/O	I/O
F16	I/O	I/O
F17	I/O	I/O
F18	I/O	I/O
F19	I/O	I/O
F20	I/O	I/O
F21	I/O	I/O
F22	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
F23	I/O	I/O
F24	I/O	I/O
F25	GND	GND
F26	I/O	I/O
F27	I/O	I/O
F28	I/O	I/O
F29	V _{DD}	V _{DD}
F30	I/O	I/O
G1	GND	GND
G2	I/O	I/O
G3	I/O	I/O
G4	I/O	I/O
G5	V _{DDP}	V _{DDP}
G6	I/O	I/O
G7	V _{DD}	V _{DD}
G8	I/O	I/O
G9	V _{DDP}	V _{DDP}
G10	I/O	I/O
G11	I/O	I/O
G12	I/O	I/O
G13	I/O	I/O
G14	I/O	I/O
G15	I/O	I/O
G16	I/O	I/O
G17	I/O	I/O
G18	I/O	I/O
G19	I/O	I/O
G20	I/O	I/O
G21	I/O	I/O
G22	V _{DDP}	V _{DDP}
G23	I/O	I/O
G24	V _{DD}	V _{DD}
G25	I/O	I/O
G26	V _{DDP}	V _{DDP}

Package Pin Assignments

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
G27	I/O	I/O
G28	I/O	I/O
G29	I/O	I/O
G30	GND	GND
H1	I/O	I/O
H2	I/O	I/O
H3	I/O	I/O
H4	I/O	I/O
H5	I/O	I/O
H6	I/O	I/O
H7	I/O	I/O
H8	GND	GND
H9	NC	I/O
H10	NC	I/O
H11	NC	I/O
H12	NC	I/O
H13	NC	I/O
H14	NC	I/O
H15	NC	I/O
H16	NC	I/O
H17	NC	I/O
H18	NC	I/O
H19	NC	I/O
H20	NC	I/O
H21	NC	I/O
H22	NC	I/O
H23	GND	GND
H24	I/O	I/O
H25	I/O	I/O
H26	I/O	I/O
H27	I/O	I/O
H28	I/O	I/O
H29	I/O	I/O
H30	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
J1	I/O	I/O
J2	I/O	I/O
J3	I/O	I/O
J4	I/O	I/O
J5	I/O	I/O
J6	I/O	I/O
J7	V _{DDP}	V _{DDP}
J8	I/O	I/O
J9	V _{DD}	V _{DD}
J10	NC	I/O
J11	NC	I/O
J12	NC	I/O
J13	NC	I/O
J14	NC	I/O
J15	NC	I/O
J16	NC	I/O
J17	NC	I/O
J18	NC	I/O
J19	NC	I/O
J20	NC	I/O
J21	NC	I/O
J22	V _{DD}	V _{DD}
J23	I/O	I/O
J24	V _{DDP}	V _{DDP}
J25	I/O	I/O
J26	I/O	I/O
J27	I/O	I/O
J28	I/O	I/O
J29	I/O	I/O
J30	I/O	I/O
K1	I/O	I/O
K2	I/O	I/O
K3	I/O	I/O
K4	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
K5	I/O	I/O
K6	I/O	I/O
K7	I/O	I/O
K8	I/O	I/O
K9	NC	I/O
K10	V _{DD}	V _{DD}
K11	NC	I/O
K12	V _{DDP}	V _{DDP}
K13	V _{DDP}	V _{DDP}
K14	V _{DDP}	V _{DDP}
K15	V _{DDP}	V _{DDP}
K16	V _{DDP}	V _{DDP}
K17	V _{DDP}	V _{DDP}
K18	V _{DDP}	V _{DDP}
K19	V _{DDP}	V _{DDP}
K20	NC	I/O
K21	V _{DD}	V _{DD}
K22	NC	I/O
K23	I/O	I/O
K24	I/O	I/O
K25	I/O	I/O
K26	I/O	I/O
K27	I/O	I/O
K28	I/O	I/O
K29	I/O	I/O
K30	I/O	I/O
L1	I/O	I/O
L2	I/O	I/O
L3	I/O	I/O
L4	I/O	I/O
L5	I/O	I/O
L6	I/O	I/O
L7	I/O	I/O
L8	I/O	I/O

896-Pin FBGA			896-Pin FBGA			896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function	Pin Number	APA750 Function	APA1000 Function	Pin Number	APA750 Function	APA1000 Function
L9	NC	I/O	M13	GND	GND	N17	GND	GND
L10	NC	I/O	M14	GND	GND	N18	GND	GND
L11	V _{DD}	V _{DD}	M15	GND	GND	N19	GND	GND
L12	V _{DD}	V _{DD}	M16	GND	GND	N20	V _{DD}	V _{DD}
L13	V _{DD}	V _{DD}	M17	GND	GND	N21	V _{DDP}	V _{DDP}
L14	V _{DD}	V _{DD}	M18	GND	GND	N22	NC	I/O
L15	V _{DD}	V _{DD}	M19	GND	GND	N23	I/O	I/O
L16	V _{DD}	V _{DD}	M20	V _{DD}	V _{DD}	N24	I/O	I/O
L17	V _{DD}	V _{DD}	M21	V _{DDP}	V _{DDP}	N25	I/O	I/O
L18	V _{DD}	V _{DD}	M22	NC	I/O	N26	I/O	I/O
L19	V _{DD}	V _{DD}	M23	I/O	I/O	N27	I/O	I/O
L20	V _{DD}	V _{DD}	M24	I/O	I/O	N28	I/O	I/O
L21	NC	I/O	M25	I/O	I/O	N29	I/O	I/O
L22	NC	I/O	M26	I/O	I/O	N30	I/O	I/O
L23	I/O	I/O	M27	I/O	I/O	P1	I/O	I/O
L24	I/O	I/O	M28	I/O	I/O	P2	I/O	I/O
L25	I/O	I/O	M29	I/O	I/O	P3	I/O	I/O
L26	I/O	I/O	M30	I/O	I/O	P4	I/O	I/O
L27	I/O	I/O	N1	I/O	I/O	P5	I/O	I/O
L28	I/O	I/O	N2	I/O	I/O	P6	I/O	I/O
L29	I/O	I/O	N3	I/O	I/O	P7	I/O	I/O
L30	I/O	I/O	N4	I/O	I/O	P8	I/O	I/O
M1	I/O	I/O	N5	I/O	I/O	P9	I/O	I/O
M2	I/O	I/O	N6	I/O	I/O	P10	V _{DDP}	V _{DDP}
M3	I/O	I/O	N7	I/O	I/O	P11	V _{DD}	V _{DD}
M4	I/O	I/O	N8	I/O	I/O	P12	GND	GND
M5	I/O	I/O	N9	NC	I/O	P13	GND	GND
M6	I/O	I/O	N10	V _{DDP}	V _{DDP}	P14	GND	GND
M7	I/O	I/O	N11	V _{DD}	V _{DD}	P15	GND	GND
M8	I/O	I/O	N12	GND	GND	P16	GND	GND
M9	NC	I/O	N13	GND	GND	P17	GND	GND
M10	V _{DDP}	V _{DDP}	N14	GND	GND	P18	GND	GND
M11	V _{DD}	V _{DD}	N15	GND	GND	P19	GND	GND
M12	GND	GND	N16	GND	GND	P20	V _{DD}	V _{DD}

Package Pin Assignments

896-Pin FBGA			896-Pin FBGA			896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function	Pin Number	APA750 Function	APA1000 Function	Pin Number	APA750 Function	APA1000 Function
P21	V _{DDP}	V _{DDP}	R25	I/O	I/O	T29	AVDD	AVDD
P22	I/O	I/O	R26	I/O	I/O	T30	I/O	I/O
P23	I/O	I/O	R27	NPECL2	NPECL2	U1	I/O	I/O
P24	I/O	I/O	R28	AGND	AGND	U2	I/O	I/O
P25	I/O	I/O	R29	I/O (GLMX2)	I/O (GLMX2)	U3	I/O	I/O
P26	I/O	I/O	R30	I/O	I/O	U4	I/O	I/O
P27	I/O	I/O	T1	I/O	I/O	U5	I/O	I/O
P28	I/O	I/O	T2	AVDD	AVDD	U6	I/O	I/O
P29	I/O	I/O	T3	GL2	GL2	U7	I/O	I/O
P30	I/O	I/O	T4	PPECL1 (I/P)	PPECL1 (I/P)	U8	I/O	I/O
R1	I/O	I/O	T5	I/O	I/O	U9	NC	I/O
R2	I/O (GLMX1)	I/O (GLMX1)	T6	I/O	I/O	U10	V _{DDP}	V _{DDP}
R3	AGND	AGND	T7	I/O	I/O	U11	V _{DD}	V _{DD}
R4	NPECL1	NPECL1	T8	I/O	I/O	U12	GND	GND
R5	GL1	GL1	T9	I/O	I/O	U13	GND	GND
R6	I/O	I/O	T10	V _{DDP}	V _{DDP}	U14	GND	GND
R7	I/O	I/O	T11	V _{DD}	V _{DD}	U15	GND	GND
R8	I/O	I/O	T12	GND	GND	U16	GND	GND
R9	NC	I/O	T13	GND	GND	U17	GND	GND
R10	V _{DDP}	V _{DDP}	T14	GND	GND	U18	GND	GND
R11	V _{DD}	V _{DD}	T15	GND	GND	U19	GND	GND
R12	GND	GND	T16	GND	GND	U20	V _{DD}	V _{DD}
R13	GND	GND	T17	GND	GND	U21	V _{DDP}	V _{DDP}
R14	GND	GND	T18	GND	GND	U22	NC	I/O
R15	GND	GND	T19	GND	GND	U23	I/O	I/O
R16	GND	GND	T20	V _{DD}	V _{DD}	U24	I/O	I/O
R17	GND	GND	T21	V _{DDP}	V _{DDP}	U25	I/O	I/O
R18	GND	GND	T22	I/O	I/O	U26	I/O	I/O
R19	GND	GND	T23	I/O	I/O	U27	I/O	I/O
R20	V _{DD}	V _{DD}	T24	I/O	I/O	U28	I/O	I/O
R21	V _{DDP}	V _{DDP}	T25	I/O	I/O	U29	I/O	I/O
R22	I/O	I/O	T26	PPECL2 (I/P)	PPECL2 (I/P)	U30	I/O	I/O
R23	I/O	I/O	T27	GL4	GL4	V1	I/O	I/O
R24	I/O	I/O	T28	GL3	GL3	V2	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
V3	I/O	I/O
V4	I/O	I/O
V5	I/O	I/O
V6	I/O	I/O
V7	I/O	I/O
V8	I/O	I/O
V9	NC	I/O
V10	V _{DDP}	V _{DDP}
V11	V _{DD}	V _{DD}
V12	GND	GND
V13	GND	GND
V14	GND	GND
V15	GND	GND
V16	GND	GND
V17	GND	GND
V18	GND	GND
V19	GND	GND
V20	V _{DD}	V _{DD}
V21	V _{DDP}	V _{DDP}
V22	NC	I/O
V23	I/O	I/O
V24	I/O	I/O
V25	I/O	I/O
V26	I/O	I/O
V27	I/O	I/O
V28	I/O	I/O
V29	I/O	I/O
V30	I/O	I/O
W1	I/O	I/O
W2	I/O	I/O
W3	I/O	I/O
W4	I/O	I/O
W5	I/O	I/O
W6	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
W7	I/O	I/O
W8	I/O	I/O
W9	NC	I/O
W10	V _{DDP}	V _{DDP}
W11	V _{DD}	V _{DD}
W12	GND	GND
W13	GND	GND
W14	GND	GND
W15	GND	GND
W16	GND	GND
W17	GND	GND
W18	GND	GND
W19	GND	GND
W20	V _{DD}	V _{DD}
W21	V _{DDP}	V _{DDP}
W22	NC	I/O
W23	I/O	I/O
W24	I/O	I/O
W25	I/O	I/O
W26	I/O	I/O
W27	I/O	I/O
W28	I/O	I/O
W29	I/O	I/O
W30	I/O	I/O
Y1	I/O	I/O
Y2	I/O	I/O
Y3	I/O	I/O
Y4	I/O	I/O
Y5	I/O	I/O
Y6	I/O	I/O
Y7	I/O	I/O
Y8	I/O	I/O
Y9	NC	I/O
Y10	NC	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
Y11	V _{DD}	V _{DD}
Y12	V _{DD}	V _{DD}
Y13	V _{DD}	V _{DD}
Y14	V _{DD}	V _{DD}
Y15	V _{DD}	V _{DD}
Y16	V _{DD}	V _{DD}
Y17	V _{DD}	V _{DD}
Y18	V _{DD}	V _{DD}
Y19	V _{DD}	V _{DD}
Y20	V _{DD}	V _{DD}
Y21	NC	I/O
Y22	NC	I/O
Y23	I/O	I/O
Y24	I/O	I/O
Y25	I/O	I/O
Y26	I/O	I/O
Y27	I/O	I/O
Y28	I/O	I/O
Y29	I/O	I/O
Y30	I/O	I/O
AA1	I/O	I/O
AA2	I/O	I/O
AA3	I/O	I/O
AA4	I/O	I/O
AA5	I/O	I/O
AA6	I/O	I/O
AA7	I/O	I/O
AA8	I/O	I/O
AA9	NC	I/O
AA10	V _{DD}	V _{DD}
AA11	NC	I/O
AA12	V _{DDP}	V _{DDP}
AA13	V _{DDP}	V _{DDP}
AA14	V _{DDP}	V _{DDP}

Package Pin Assignments

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
AA15	V _{DDP}	V _{DDP}
AA16	V _{DDP}	V _{DDP}
AA17	V _{DDP}	V _{DDP}
AA18	V _{DDP}	V _{DDP}
AA19	V _{DDP}	V _{DDP}
AA20	NC	I/O
AA21	V _{DD}	V _{DD}
AA22	NC	I/O
AA23	I/O	I/O
AA24	I/O	I/O
AA25	I/O	I/O
AA26	I/O	I/O
AA27	I/O	I/O
AA28	I/O	I/O
AA29	I/O	I/O
AA30	I/O	I/O
AB1	I/O	I/O
AB2	I/O	I/O
AB3	I/O	I/O
AB4	I/O	I/O
AB5	I/O	I/O
AB6	I/O	I/O
AB7	V _{DDP}	V _{DDP}
AB8	I/O	I/O
AB9	V _{DD}	V _{DD}
AB10	NC	I/O
AB11	NC	I/O
AB12	NC	I/O
AB13	NC	I/O
AB14	NC	I/O
AB15	NC	I/O
AB16	NC	I/O
AB17	NC	I/O
AB18	NC	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
AB19	NC	I/O
AB20	NC	I/O
AB21	NC	I/O
AB22	V _{DD}	V _{DD}
AB23	I/O	I/O
AB24	V _{DDP}	V _{DDP}
AB25	I/O	I/O
AB26	I/O	I/O
AB27	I/O	I/O
AB28	I/O	I/O
AB29	I/O	I/O
AB30	I/O	I/O
AC1	I/O	I/O
AC2	I/O	I/O
AC3	I/O	I/O
AC4	I/O	I/O
AC5	I/O	I/O
AC6	I/O	I/O
AC7	I/O	I/O
AC8	GND	GND
AC9	NC	I/O
AC10	NC	I/O
AC11	NC	I/O
AC12	NC	I/O
AC13	NC	I/O
AC14	NC	I/O
AC15	NC	I/O
AC16	NC	I/O
AC17	NC	I/O
AC18	NC	I/O
AC19	NC	I/O
AC20	NC	I/O
AC21	NC	I/O
AC22	NC	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
AC23	GND	GND
AC24	I/O	I/O
AC25	I/O	I/O
AC26	I/O	I/O
AC27	I/O	I/O
AC28	I/O	I/O
AC29	I/O	I/O
AC30	I/O	I/O
AD1	GND	GND
AD2	I/O	I/O
AD3	I/O	I/O
AD4	I/O	I/O
AD5	V _{DDP}	V _{DDP}
AD6	I/O	I/O
AD7	V _{DD}	V _{DD}
AD8	I/O	I/O
AD9	V _{DDP}	V _{DDP}
AD10	I/O	I/O
AD11	I/O	I/O
AD12	I/O	I/O
AD13	I/O	I/O
AD14	I/O	I/O
AD15	I/O	I/O
AD16	I/O	I/O
AD17	I/O	I/O
AD18	I/O	I/O
AD19	I/O	I/O
AD20	I/O	I/O
AD21	I/O	I/O
AD22	V _{DDP}	V _{DDP}
AD23	TCK	TCK
AD24	V _{DD}	V _{DD}
AD25	TRST	TRST
AD26	V _{DDP}	V _{DDP}

896-Pin FBGA			896-Pin FBGA			896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function	Pin Number	APA750 Function	APA1000 Function	Pin Number	APA750 Function	APA1000 Function
AD27	I/O	I/O	AF1	GND	GND	AG5	I/O	I/O
AD28	I/O	I/O	AF2	I/O	I/O	AG6	I/O	I/O
AD29	I/O	I/O	AF3	V _{DDP}	V _{DDP}	AG7	I/O	I/O
AD30	GND	GND	AF4	I/O	I/O	AG8	I/O	I/O
AE1	I/O	I/O	AF5	V _{DD}	V _{DD}	AG9	I/O	I/O
AE2	V _{DD}	V _{DD}	AF6	I/O	I/O	AG10	I/O	I/O
AE3	I/O	I/O	AF7	V _{DDP}	V _{DDP}	AG11	I/O	I/O
AE4	I/O	I/O	AF8	I/O	I/O	AG12	I/O	I/O
AE5	I/O	I/O	AF9	I/O	I/O	AG13	I/O	I/O
AE6	GND	GND	AF10	I/O	I/O	AG14	I/O	I/O
AE7	I/O	I/O	AF11	I/O	I/O	AG15	I/O	I/O
AE8	I/O	I/O	AF12	I/O	I/O	AG16	I/O	I/O
AE9	I/O	I/O	AF13	I/O	I/O	AG17	I/O	I/O
AE10	I/O	I/O	AF14	I/O	I/O	AG18	I/O	I/O
AE11	I/O	I/O	AF15	I/O	I/O	AG19	I/O	I/O
AE12	I/O	I/O	AF16	I/O	I/O	AG20	I/O	I/O
AE13	I/O	I/O	AF17	I/O	I/O	AG21	I/O	I/O
AE14	I/O	I/O	AF18	I/O	I/O	AG22	I/O	I/O
AE15	I/O	I/O	AF19	I/O	I/O	AG23	I/O	I/O
AE16	I/O	I/O	AF20	I/O	I/O	AG24	I/O	I/O
AE17	I/O	I/O	AF21	I/O	I/O	AG25	I/O	I/O
AE18	I/O	I/O	AF22	I/O	I/O	AG26	I/O	I/O
AE19	I/O	I/O	AF23	I/O	I/O	AG27	GND	GND
AE20	I/O	I/O	AF24	V _{DDP}	V _{DDP}	AG28	RCK	RCK
AE21	I/O	I/O	AF25	I/O	I/O	AG29	V _{DD}	V _{DD}
AE22	I/O	I/O	AF26	V _{DD}	V _{DD}	AG30	I/O	I/O
AE23	I/O	I/O	AF27	TDO	TDO	AH1	GND	GND
AE24	I/O	I/O	AF28	V _{DDP}	V _{DDP}	AH2	I/O	I/O
AE25	GND	GND	AF29	V _{PN}	V _{PN}	AH3	V _{DD}	V _{DD}
AE26	I/O	I/O	AF30	GND	GND	AH4	I/O	I/O
AE27	I/O	I/O	AG1	I/O	I/O	AH5	V _{DDP}	V _{DDP}
AE28	I/O	I/O	AG2	V _{DD}	V _{DD}	AH6	I/O	I/O
AE29	V _{DD}	V _{DD}	AG3	I/O	I/O	AH7	I/O	I/O
AE30	I/O	I/O	AG4	GND	GND	AH8	I/O	I/O

Package Pin Assignments

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
AH9	I/O	I/O
AH10	I/O	I/O
AH11	I/O	I/O
AH12	I/O	I/O
AH13	I/O	I/O
AH14	I/O	I/O
AH15	I/O	I/O
AH16	I/O	I/O
AH17	I/O	I/O
AH18	I/O	I/O
AH19	I/O	I/O
AH20	I/O	I/O
AH21	I/O	I/O
AH22	I/O	I/O
AH23	I/O	I/O
AH24	I/O	I/O
AH25	I/O	I/O
AH26	V _{DDP}	V _{DDP}
AH27	TDI	TDI
AH28	V _{DD}	V _{DD}
AH29	V _{PP}	V _{PP}
AH30	GND	GND
AJ1	GND	GND
AJ2	GND	GND
AJ3	I/O	I/O
AJ4	V _{DD}	V _{DD}
AJ5	I/O	I/O
AJ6	V _{DD}	V _{DD}
AJ7	I/O	I/O
AJ8	I/O	I/O
AJ9	I/O	I/O
AJ10	I/O	I/O
AJ11	I/O	I/O
AJ12	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
AJ13	I/O	I/O
AJ14	I/O	I/O
AJ15	I/O	I/O
AJ16	I/O	I/O
AJ17	I/O	I/O
AJ18	I/O	I/O
AJ19	I/O	I/O
AJ20	I/O	I/O
AJ21	I/O	I/O
AJ22	I/O	I/O
AJ23	I/O	I/O
AJ24	I/O	I/O
AJ25	V _{DD}	V _{DD}
AJ26	I/O	I/O
AJ27	V _{DD}	V _{DD}
AJ28	TMS	TMS
AJ29	GND	GND
AJ30	GND	GND
AK2	GND	GND
AK3	GND	GND
AK4	I/O	I/O
AK5	GND	GND
AK6	I/O	I/O
AK7	GND	GND
AK8	I/O	I/O
AK9	I/O	I/O
AK10	I/O	I/O
AK11	I/O	I/O
AK12	I/O	I/O
AK13	I/O	I/O
AK14	I/O	I/O
AK15	I/O	I/O
AK16	I/O	I/O
AK17	I/O	I/O

896-Pin FBGA		
Pin Number	APA750 Function	APA1000 Function
AK18	I/O	I/O
AK19	I/O	I/O
AK20	I/O	I/O
AK21	I/O	I/O
AK22	I/O	I/O
AK23	I/O	I/O
AK24	GND	GND
AK25	I/O	I/O
AK26	GND	GND
AK27	I/O	I/O
AK28	GND	GND
AK29	GND	GND

1152-Pin FBGA

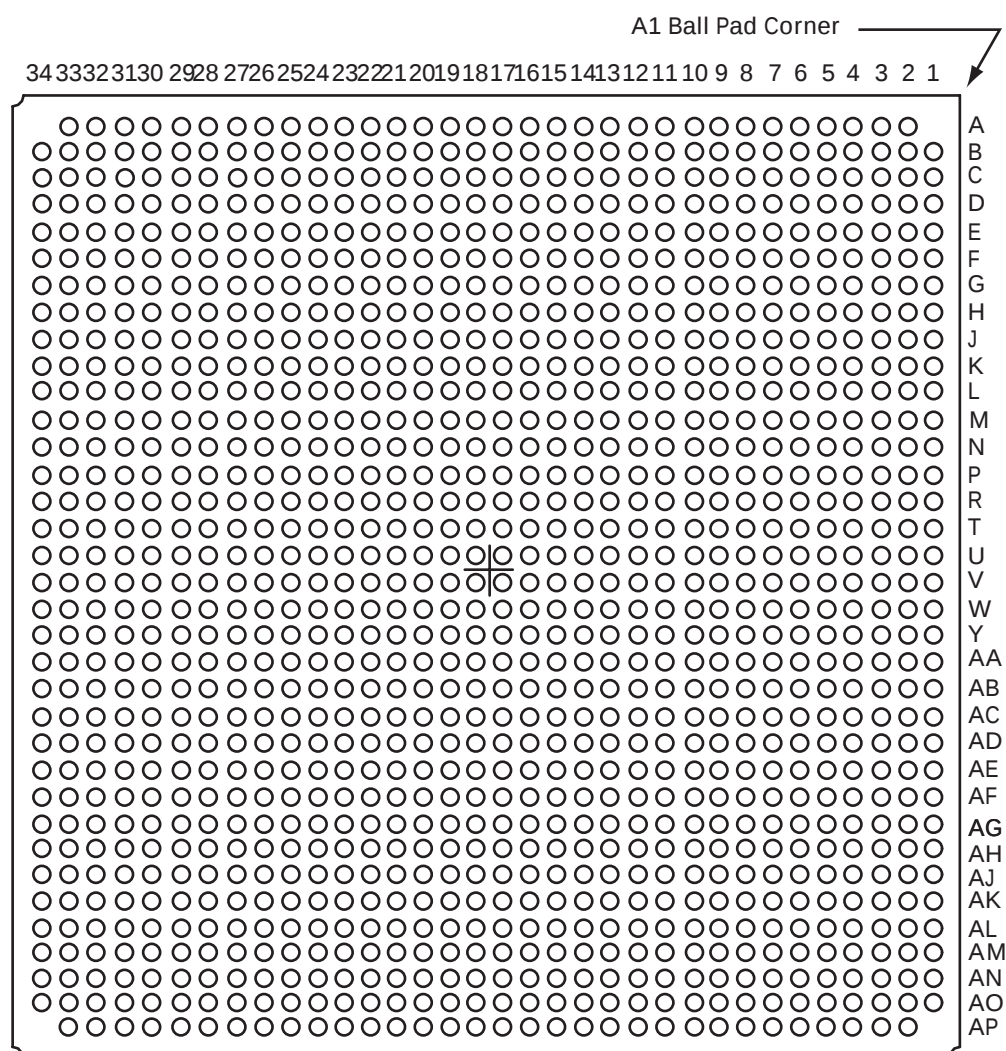


Figure 2-10 • 1152-Pin FBGA (Bottom View)

Package Pin Assignments

1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA	
Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function
A2	NC	B5	GND	C7	GND	D9	I/O
A3	GND	B6	NC	C8	I/O	D10	I/O
A4	GND	B7	I/O	C9	GND	D11	I/O
A5	GND	B8	NC	C10	I/O	D12	I/O
A6	I/O	B9	I/O	C11	I/O	D13	I/O
A7	V _{DD}	B10	NC	C12	I/O	D14	I/O
A8	V _{DD}	B11	I/O	C13	I/O	D15	I/O
A9	V _{DD}	B12	GND	C14	I/O	D16	I/O
A10	V _{DD}	B13	I/O	C15	I/O	D17	I/O
A11	I/O	B14	V _{DDP}	C16	I/O	D18	I/O
A12	GND	B15	V _{DDP}	C17	I/O	D19	I/O
A13	I/O	B16	I/O	C18	I/O	D20	I/O
A14	V _{DDP}	B17	GND	C19	I/O	D21	I/O
A15	V _{DDP}	B18	GND	C20	I/O	D22	I/O
A16	I/O	B19	I/O	C21	I/O	D23	I/O
A17	GND	B20	V _{DDP}	C22	I/O	D24	I/O
A18	GND	B21	V _{DDP}	C23	I/O	D25	I/O
A19	I/O	B22	I/O	C24	I/O	D26	I/O
A20	V _{DDP}	B23	GND	C25	I/O	D27	V _{DD}
A21	V _{DDP}	B24	I/O	C26	GND	D28	I/O
A22	I/O	B25	NC	C27	I/O	D29	V _{DD}
A23	GND	B26	I/O	C28	GND	D30	I/O
A24	I/O	B27	NC	C29	I/O	D31	GND
A25	V _{DD}	B28	I/O	C30	GND	D32	GND
A26	V _{DD}	B29	NC	C31	GND	D33	GND
A27	V _{DD}	B30	GND	C32	NC	D34	GND
A28	V _{DD}	B31	GND	C33	GND	E1	GND
A29	I/O	B32	GND	C34	GND	E2	GND
A30	GND	B33	NC	D1	GND	E3	GND
A31	GND	B34	NC	D2	GND	E4	I/O
A32	GND	C1	GND	D3	GND	E5	V _{DD}
A33	NC	C2	GND	D4	GND	E6	I/O
B1	NC	C3	NC	D5	I/O	E7	V _{DDP}
B2	NC	C4	GND	D6	V _{DD}	E8	I/O
B3	GND	C5	GND	D7	I/O	E9	I/O
B4	GND	C6	I/O	D8	V _{DD}	E10	I/O

1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA	
Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function
E11	I/O	F13	I/O	G15	I/O	H17	I/O
E12	I/O	F14	I/O	G16	I/O	H18	I/O
E13	I/O	F15	I/O	G17	I/O	H19	I/O
E14	I/O	F16	I/O	G18	I/O	H20	I/O
E15	I/O	F17	I/O	G19	I/O	H21	I/O
E16	I/O	F18	I/O	G20	I/O	H22	I/O
E17	I/O	F19	I/O	G21	I/O	H23	I/O
E18	I/O	F20	I/O	G22	I/O	H24	I/O
E19	I/O	F21	I/O	G23	I/O	H25	I/O
E20	I/O	F22	I/O	G24	I/O	H26	I/O
E21	I/O	F23	I/O	G25	I/O	H27	GND
E22	I/O	F24	I/O	G26	V _{DDP}	H28	I/O
E23	I/O	F25	I/O	G27	I/O	H29	I/O
E24	I/O	F26	I/O	G28	V _{DD}	H30	I/O
E25	I/O	F27	I/O	G29	I/O	H31	V _{DD}
E26	I/O	F28	I/O	G30	V _{DDP}	H32	I/O
E27	I/O	F29	GND	G31	I/O	H33	NC
E28	V _{DDP}	F30	I/O	G32	GND	H34	V _{DD}
E29	I/O	F31	V _{DD}	G33	I/O	J1	V _{DD}
E30	V _{DD}	F32	I/O	G34	V _{DD}	J2	I/O
E31	I/O	F33	NC	H1	V _{DD}	J3	GND
E32	GND	F34	NC	H2	NC	J4	I/O
E33	GND	G1	V _{DD}	H3	I/O	J5	I/O
E34	GND	G2	I/O	H4	V _{DD}	J6	I/O
F1	I/O	G3	GND	H5	I/O	J7	V _{DDP}
F2	NC	G4	I/O	H6	I/O	J8	I/O
F3	I/O	G5	V _{DDP}	H7	I/O	J9	V _{DD}
F4	V _{DD}	G6	I/O	H8	GND	J10	I/O
F5	I/O	G7	V _{DD}	H9	I/O	J11	V _{DDP}
F6	GND	G8	I/O	H10	I/O	J12	I/O
F7	I/O	G9	V _{DDP}	H11	I/O	J13	I/O
F8	I/O	G10	I/O	H12	I/O	J14	I/O
F9	I/O	G11	I/O	H13	I/O	J15	I/O
F10	I/O	G12	I/O	H14	I/O	J16	I/O
F11	I/O	G13	I/O	H15	I/O	J17	I/O
F12	I/O	G14	I/O	H16	I/O	J18	I/O

Package Pin Assignments

1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA	
Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function
J19	I/O	K21	I/O	L23	I/O	M25	I/O
J20	I/O	K22	I/O	L24	V _{DD}	M26	I/O
J21	I/O	K23	I/O	L25	I/O	M27	I/O
J22	I/O	K24	I/O	L26	V _{DDP}	M28	I/O
J23	I/O	K25	GND	L27	I/O	M29	I/O
J24	V _{DDP}	K26	I/O	L28	I/O	M30	I/O
J25	I/O	K27	I/O	L29	I/O	M31	I/O
J26	V _{DD}	K28	I/O	L30	I/O	M32	I/O
J27	I/O	K29	I/O	L31	I/O	M33	GND
J28	V _{DDP}	K30	I/O	L32	I/O	M34	GND
J29	I/O	K31	I/O	L33	I/O	N1	I/O
J30	I/O	K32	I/O	L34	I/O	N2	I/O
J31	I/O	K33	NC	M1	GND	N3	I/O
J32	GND	K34	V _{DD}	M2	GND	N4	I/O
J33	I/O	L1	I/O	M3	I/O	N5	I/O
J34	V _{DD}	L2	I/O	M4	I/O	N6	I/O
K1	V _{DD}	L3	I/O	M5	I/O	N7	I/O
K2	NC	L4	I/O	M6	I/O	N8	I/O
K3	I/O	L5	I/O	M7	I/O	N9	I/O
K4	I/O	L6	I/O	M8	I/O	N10	I/O
K5	I/O	L7	I/O	M9	I/O	N11	I/O
K6	I/O	L8	I/O	M10	I/O	N12	I/O
K7	I/O	L9	V _{DDP}	M11	I/O	N13	V _{DD}
K8	I/O	L10	I/O	M12	V _{DD}	N14	V _{DD}
K9	I/O	L11	V _{DD}	M13	I/O	N15	V _{DD}
K10	GND	L12	I/O	M14	V _{DDP}	N16	V _{DD}
K11	I/O	L13	I/O	M15	V _{DDP}	N17	V _{DD}
K12	I/O	L14	I/O	M16	V _{DDP}	N18	V _{DD}
K13	I/O	L15	I/O	M17	V _{DDP}	N19	V _{DD}
K14	I/O	L16	I/O	M18	V _{DDP}	N20	V _{DD}
K15	I/O	L17	I/O	M19	V _{DDP}	N21	V _{DD}
K16	I/O	L18	I/O	M20	V _{DDP}	N22	V _{DD}
K17	I/O	L19	I/O	M21	V _{DDP}	N23	I/O
K18	I/O	L20	I/O	M22	I/O	N24	I/O
K19	I/O	L21	I/O	M23	V _{DD}	N25	I/O
K20	I/O	L22	I/O	M24	I/O	N26	I/O

1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA	
Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function
N27	I/O	P29	I/O	R31	I/O	T33	I/O
N28	I/O	P30	I/O	R32	I/O	T34	I/O
N29	I/O	P31	I/O	R33	V _{DDP}	U1	GND
N30	I/O	P32	I/O	R34	V _{DDP}	U2	GND
N31	I/O	P33	V _{DDP}	T1	I/O	U3	I/O
N32	I/O	P34	V _{DDP}	T2	I/O	U4	I/O (GLMX1)
N33	I/O	R1	V _{DDP}	T3	I/O	U5	AGND
N34	I/O	R2	V _{DDP}	T4	I/O	U6	NPECL1
P1	V _{DDP}	R3	I/O	T5	I/O	U7	GL1
P2	V _{DDP}	R4	I/O	T6	I/O	U8	I/O
P3	I/O	R5	I/O	T7	I/O	U9	I/O
P4	I/O	R6	I/O	T8	I/O	U10	I/O
P5	I/O	R7	I/O	T9	I/O	U11	I/O
P6	I/O	R8	I/O	T10	I/O	U12	V _{DDP}
P7	I/O	R9	I/O	T11	I/O	U13	V _{DD}
P8	I/O	R10	I/O	T12	V _{DDP}	U14	GND
P9	I/O	R11	I/O	T13	V _{DD}	U15	GND
P10	I/O	R12	V _{DDP}	T14	GND	U16	GND
P11	I/O	R13	V _{DD}	T15	GND	U17	GND
P12	V _{DDP}	R14	GND	T16	GND	U18	GND
P13	V _{DD}	R15	GND	T17	GND	U19	GND
P14	GND	R16	GND	T18	GND	U20	GND
P15	GND	R17	GND	T19	GND	U21	GND
P16	GND	R18	GND	T20	GND	U22	V _{DD}
P17	GND	R19	GND	T21	GND	U23	V _{DDP}
P18	GND	R20	GND	T22	V _{DD}	U24	I/O
P19	GND	R21	GND	T23	V _{DDP}	U25	I/O
P20	GND	R22	V _{DD}	T24	I/O	U26	I/O
P21	GND	R23	V _{DDP}	T25	I/O	U27	I/O
P22	V _{DD}	R24	I/O	T26	I/O	U28	I/O
P23	V _{DDP}	R25	I/O	T27	I/O	U29	NPECL2
P24	I/O	R26	I/O	T28	I/O	U30	AGND
P25	I/O	R27	I/O	T29	I/O	U31	I/O (GLMX2)
P26	I/O	R28	I/O	T30	I/O	U32	I/O
P27	I/O	R29	I/O	T31	I/O	U33	GND
P28	I/O	R30	I/O	T32	I/O	U34	GND

Package Pin Assignments

1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA	
Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function
V1	GND	W3	I/O	Y5	I/O	AA7	I/O
V2	GND	W4	I/O	Y6	I/O	AA8	I/O
V3	I/O	W5	I/O	Y7	I/O	AA9	I/O
V4	AVDD	W6	I/O	Y8	I/O	AA10	I/O
V5	GL2	W7	I/O	Y9	I/O	AA11	I/O
V6	PPECL1 (I/P)	W8	I/O	Y10	I/O	AA12	V _{DDP}
V7	I/O	W9	I/O	Y11	I/O	AA13	V _{DD}
V8	I/O	W10	I/O	Y12	V _{DDP}	AA14	GND
V9	I/O	W11	I/O	Y13	V _{DD}	AA15	GND
V10	I/O	W12	V _{DDP}	Y14	GND	AA16	GND
V11	I/O	W13	V _{DD}	Y15	GND	AA17	GND
V12	V _{DDP}	W14	GND	Y16	GND	AA18	GND
V13	V _{DD}	W15	GND	Y17	GND	AA19	GND
V14	GND	W16	GND	Y18	GND	AA20	GND
V15	GND	W17	GND	Y19	GND	AA21	GND
V16	GND	W18	GND	Y20	GND	AA22	V _{DD}
V17	GND	W19	GND	Y21	GND	AA23	V _{DDP}
V18	GND	W20	GND	Y22	V _{DD}	AA24	I/O
V19	GND	W21	GND	Y23	V _{DDP}	AA25	I/O
V20	GND	W22	V _{DD}	Y24	I/O	AA26	I/O
V21	GND	W23	V _{DDP}	Y25	I/O	AA27	I/O
V22	V _{DD}	W24	I/O	Y26	I/O	AA28	I/O
V23	V _{DDP}	W25	I/O	Y27	I/O	AA29	I/O
V24	I/O	W26	I/O	Y28	I/O	AA30	I/O
V25	I/O	W27	I/O	Y29	I/O	AA31	I/O
V26	I/O	W28	I/O	Y30	I/O	AA32	I/O
V27	I/O	W29	I/O	Y31	I/O	AA33	V _{DDP}
V28	PPECL2 (I/P)	W30	I/O	Y32	I/O	AA34	V _{DDP}
V29	GL4	W31	I/O	Y33	V _{DDP}	AB1	I/O
V30	GL3	W32	I/O	Y34	V _{DDP}	AB2	I/O
V31	AVDD	W33	I/O	AA1	V _{DDP}	AB3	I/O
V32	I/O	W34	I/O	AA2	V _{DDP}	AB4	I/O
V33	GND	Y1	V _{DDP}	AA3	I/O	AB5	I/O
V34	GND	Y2	V _{DDP}	AA4	I/O	AB6	I/O
W1	I/O	Y3	I/O	AA5	I/O	AB7	I/O
W2	I/O	Y4	I/O	AA6	I/O	AB8	I/O

1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA	
Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function
AB9	I/O	AC11	I/O	AD13	I/O	AE15	I/O
AB10	I/O	AC12	V _{DD}	AD14	I/O	AE16	I/O
AB11	I/O	AC13	I/O	AD15	I/O	AE17	I/O
AB12	I/O	AC14	V _{DDP}	AD16	I/O	AE18	I/O
AB13	V _{DD}	AC15	V _{DDP}	AD17	I/O	AE19	I/O
AB14	V _{DD}	AC16	V _{DDP}	AD18	I/O	AE20	I/O
AB15	V _{DD}	AC17	V _{DDP}	AD19	I/O	AE21	I/O
AB16	V _{DD}	AC18	V _{DDP}	AD20	I/O	AE22	I/O
AB17	V _{DD}	AC19	V _{DDP}	AD21	I/O	AE23	I/O
AB18	V _{DD}	AC20	V _{DDP}	AD22	I/O	AE24	I/O
AB19	V _{DD}	AC21	V _{DDP}	AD23	I/O	AE25	GND
AB20	V _{DD}	AC22	I/O	AD24	V _{DD}	AE26	I/O
AB21	V _{DD}	AC23	V _{DD}	AD25	I/O	AE27	I/O
AB22	V _{DD}	AC24	I/O	AD26	V _{DDP}	AE28	I/O
AB23	I/O	AC25	I/O	AD27	I/O	AE29	I/O
AB24	I/O	AC26	I/O	AD28	I/O	AE30	I/O
AB25	I/O	AC27	I/O	AD29	I/O	AE31	I/O
AB26	I/O	AC28	I/O	AD30	I/O	AE32	I/O
AB27	I/O	AC29	I/O	AD31	I/O	AE33	NC
AB28	I/O	AC30	I/O	AD32	I/O	AE34	V _{DD}
AB29	I/O	AC31	I/O	AD33	I/O	AF1	V _{DD}
AB30	I/O	AC32	I/O	AD34	I/O	AF2	I/O
AB31	I/O	AC33	GND	AE1	V _{DD}	AF3	GND
AB32	I/O	AC34	GND	AE2	NC	AF4	I/O
AB33	I/O	AD1	I/O	AE3	I/O	AF5	I/O
AB34	I/O	AD2	I/O	AE4	I/O	AF6	I/O
AC1	GND	AD3	I/O	AE5	I/O	AF7	V _{DDP}
AC2	GND	AD4	I/O	AE6	I/O	AF8	I/O
AC3	I/O	AD5	I/O	AE7	I/O	AF9	V _{DD}
AC4	I/O	AD6	I/O	AE8	I/O	AF10	I/O
AC5	I/O	AD7	I/O	AE9	I/O	AF11	V _{DDP}
AC6	I/O	AD8	I/O	AE10	GND	AF12	I/O
AC7	I/O	AD9	V _{DDP}	AE11	I/O	AF13	I/O
AC8	I/O	AD10	I/O	AE12	I/O	AF14	I/O
AC9	I/O	AD11	V _{DD}	AE13	I/O	AF15	I/O
AC10	I/O	AD12	I/O	AE14	I/O	AF16	I/O

Package Pin Assignments

1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA	
Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function
AF17	I/O	AG19	I/O	AH21	I/O	AJ23	I/O
AF18	I/O	AG20	I/O	AH22	I/O	AJ24	I/O
AF19	I/O	AG21	I/O	AH23	I/O	AJ25	I/O
AF20	I/O	AG22	I/O	AH24	I/O	AJ26	I/O
AF21	I/O	AG23	I/O	AH25	I/O	AJ27	I/O
AF22	I/O	AG24	I/O	AH26	V _{DDP}	AJ28	I/O
AF23	I/O	AG25	I/O	AH27	I/O	AJ29	GND
AF24	V _{DDP}	AG26	I/O	AH28	V _{DD}	AJ30	RCK
AF25	TCK	AG27	GND	AH29	TDO	AJ31	V _{DD}
AF26	V _{DD}	AG28	I/O	AH30	V _{DDP}	AJ32	I/O
AF27	TRST	AG29	I/O	AH31	V _{PN}	AJ33	NC
AF28	V _{DDP}	AG30	I/O	AH32	GND	AJ34	NC
AF29	I/O	AG31	V _{DD}	AH33	I/O	AK1	GND
AF30	I/O	AG32	I/O	AH34	V _{DD}	AK2	GND
AF31	I/O	AG33	NC	AJ1	I/O	AK3	GND
AF32	GND	AG34	V _{DD}	AJ2	NC	AK4	I/O
AF33	I/O	AH1	V _{DD}	AJ3	I/O	AK5	V _{DD}
AF34	V _{DD}	AH2	I/O	AJ4	V _{DD}	AK6	I/O
AG1	V _{DD}	AH3	GND	AJ5	I/O	AK7	V _{DDP}
AG2	NC	AH4	I/O	AJ6	GND	AK8	I/O
AG3	I/O	AH5	V _{DDP}	AJ7	I/O	AK9	I/O
AG4	V _{DD}	AH6	I/O	AJ8	I/O	AK10	I/O
AG5	I/O	AH7	V _{DD}	AJ9	I/O	AK11	I/O
AG6	I/O	AH8	I/O	AJ10	I/O	AK12	I/O
AG7	I/O	AH9	V _{DDP}	AJ11	I/O	AK13	I/O
AG8	GND	AH10	I/O	AJ12	I/O	AK14	I/O
AG9	I/O	AH11	I/O	AJ13	I/O	AK15	I/O
AG10	I/O	AH12	I/O	AJ14	I/O	AK16	I/O
AG11	I/O	AH13	I/O	AJ15	I/O	AK17	I/O
AG12	I/O	AH14	I/O	AJ16	I/O	AK18	I/O
AG13	I/O	AH15	I/O	AJ17	I/O	AK19	I/O
AG14	I/O	AH16	I/O	AJ18	I/O	AK20	I/O
AG15	I/O	AH17	I/O	AJ19	I/O	AK21	I/O
AG16	I/O	AH18	I/O	AJ20	I/O	AK22	I/O
AG17	I/O	AH19	I/O	AJ21	I/O	AK23	I/O
AG18	I/O	AH20	I/O	AJ22	I/O	AK24	I/O

1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA		1152-Pin FBGA	
Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function	Pin Number	APA1000 Function
AK25	I/O	AL27	V _{DD}	AM29	I/O	AN31	GND
AK26	I/O	AL28	I/O	AM30	GND	AN32	GND
AK27	I/O	AL29	V _{DD}	AM31	GND	AN33	NC
AK28	V _{DDP}	AL30	TMS	AM32	NC	AN34	NC
AK29	TDI	AL31	GND	AM33	GND	AP2	NC
AK30	V _{DD}	AL32	GND	AM34	GND	AP3	GND
AK31	V _{PP}	AL33	GND	AN1	NC	AP4	GND
AK32	GND	AL34	GND	AN2	NC	AP5	GND
AK33	GND	AM1	GND	AN3	GND	AP6	I/O
AK34	GND	AM2	GND	AN4	GND	AP7	V _{DD}
AL1	GND	AM3	NC	AN5	GND	AP8	V _{DD}
AL2	GND	AM4	GND	AN6	NC	AP9	V _{DD}
AL3	GND	AM5	GND	AN7	I/O	AP10	V _{DD}
AL4	GND	AM6	I/O	AN8	NC	AP11	I/O
AL5	I/O	AM7	GND	AN9	I/O	AP12	GND
AL6	V _{DD}	AM8	I/O	AN10	NC	AP13	I/O
AL7	I/O	AM9	GND	AN11	I/O	AP14	V _{DDP}
AL8	V _{DD}	AM10	I/O	AN12	GND	AP15	V _{DDP}
AL9	I/O	AM11	I/O	AN13	I/O	AP16	I/O
AL10	I/O	AM12	I/O	AN14	V _{DDP}	AP17	GND
AL11	I/O	AM13	I/O	AN15	V _{DDP}	AP18	GND
AL12	I/O	AM14	I/O	AN16	I/O	AP19	I/O
AL13	I/O	AM15	I/O	AN17	GND	AP20	V _{DDP}
AL14	I/O	AM16	I/O	AN18	GND	AP21	V _{DDP}
AL15	I/O	AM17	I/O	AN19	I/O	AP22	I/O
AL16	I/O	AM18	I/O	AN20	V _{DDP}	AP23	GND
AL17	I/O	AM19	I/O	AN21	V _{DDP}	AP24	I/O
AL18	I/O	AM20	I/O	AN22	I/O	AP25	V _{DD}
AL19	I/O	AM21	I/O	AN23	GND	AP26	V _{DD}
AL20	I/O	AM22	I/O	AN24	I/O	AP27	V _{DD}
AL21	I/O	AM23	I/O	AN25	NC	AP28	V _{DD}
AL22	I/O	AM24	I/O	AN26	I/O	AP29	I/O
AL23	I/O	AM25	I/O	AN27	NC	AP30	GND
AL24	I/O	AM26	GND	AN28	I/O	AP31	GND
AL25	I/O	AM27	I/O	AN29	NC	AP32	GND
AL26	I/O	AM28	GND	AN30	GND	AP33	NC

List of Changes

The following table lists critical changes that were made in the current version of the document.

Previous version	Changes in current version (Advanced v3.3)	Page
Advanced v3.2	The "ProASICPLUS Clock Management System" was updated.	page 1-11
	Figure 1-14 was updated.	page 1-13
	Table 1-7 is new.	page 1-14
	Figure 1-20 was updated.	page 1-18
	The "PLL Electrical Specifications" was updated.	page 1-19
	Figure 1-26 was updated.	page 1-25
	In the "Calculating Typical Power Dissipation", P9 was changed to 7.5 mW.	page 1-28
	The "Programming, Storage and Operating Limits" was updated.	page 1-30
	The "Recommended Design Practice for VPN/VPP" was updated.	page 1-64
v3.1	The datasheet was updated to include references to guidelines concerning the use of certain ProASIC ^{PLUS} I/O standards.	
v3.0	In Table 1-2 on page 1-7, the Memory Rows – Bottom coordinates were changed.	page 1-7
	Figure 1-8 was updated.	page 1-7
	The V_{IL} Minimum in the "DC Electrical Specifications ($V_{DDP} = 3.3V \pm 0.3V$ and $V_{DD} 2.5V \pm 0.2V$)1" was changed from 0.3 to –0.3.	page 1-33
	In the "Output Buffer Delays", the OB25LPLL t_{DHL} Standard changed to 5.3.	page 1-38
	In the "Sample Macrocell Library Listing", the AND2 Standard maximum changed to 0.7 and the –F maximum changed to 0.8.	page 1-41

Previous version	Changes in current version (Advanced v3.3)	Page																							
v2.0	The Table 1 was updated.	page i-i																							
	The "Ordering Information" was updated.	page i-ii																							
	The "Plastic Device Resources" was updated.	page i-ii																							
	The "ProASICPLUS Architecture" was updated.	page 1-2																							
	Table 1-2 was updated.	page 1-7																							
	Table 1-8 is new.	page 1-15																							
	Figure 1-11 is new.	page 1-9																							
	The "Introduction" in the "ProASICPLUS Clock Management System" was updated.	page 1-11																							
	The "Physical Implementation" was updated.	page 1-12																							
	The "Functional Description" on page 1-12 was updated.	page 1-12																							
	Figure 1-14 on page 1-13 through Figure 1-20 on page 1-18 were updated.	page 1-13 to page 1-18																							
	The "PLL Electrical Specifications" on page 1-19 was updated.	page 1-19																							
	Figure 1-25 on page 1-24 was updated.	page 1-24																							
	The "Calculating Typical Power Dissipation" on page 1-28 was updated.	page 1-28																							
	The "Supply Voltages" was updated.	page 1-30																							
	The "DC Electrical Specifications (VDDP = 3.3V ±0.3V and VDD 2.5V ±0.2V)1" on page 1-33 was updated.	page 1-33																							
	The "Tristate Buffer Delays" on page 1-37 was updated.	page 1-37																							
	The "Output Buffer Delays" on page 1-38 was updated.	page 1-38																							
	The "Input Buffer Delays" on page 1-39 was updated.	page 1-39																							
	"Global Routing Skew" on page 1-40 was updated.	page 1-40																							
	The "Sample Macrocell Library Listing" on page 1-41 was updated.	page 1-41																							
	The "Pin Description" on page 1-63 was updated.	page 1-63																							
	The following pins have been changed in the "100-Pin TQFP" table :	page 2-2																							
	<table><tr><th>Pin Number</th><th>Function</th><th>Pin Number</th><th>Function</th></tr><tr><td>10</td><td>I/O (GLMX1)</td><td>60</td><td>GL3</td></tr><tr><td>11</td><td>GL1</td><td>61</td><td>PPECL2 (I/P)</td></tr><tr><td>13</td><td>NPECL1</td><td>63</td><td>NPECL2</td></tr><tr><td>15</td><td>PPECL1(I/P)</td><td>65</td><td>GL4</td></tr><tr><td>16</td><td>GL2</td><td>66</td><td>I/O (GLMX2)</td></tr></table>	Pin Number	Function	Pin Number	Function	10	I/O (GLMX1)	60	GL3	11	GL1	61	PPECL2 (I/P)	13	NPECL1	63	NPECL2	15	PPECL1(I/P)	65	GL4	16	GL2	66	I/O (GLMX2)
Pin Number	Function	Pin Number	Function																						
10	I/O (GLMX1)	60	GL3																						
11	GL1	61	PPECL2 (I/P)																						
13	NPECL1	63	NPECL2																						
15	PPECL1(I/P)	65	GL4																						
16	GL2	66	I/O (GLMX2)																						
"144-Pin TQFP" is new.	page 2-3																								
The following pins have been changed in the "208-Pin PQFP":	page 2-6																								
<table><tr><th>Pin Number</th><th>Function</th><th>Pin Number</th><th>Function</th></tr><tr><td>23</td><td>I/O (GLMX1)</td><td>128</td><td>GL3</td></tr><tr><td>24</td><td>GL1</td><td>129</td><td>PPECL2 (I/P)</td></tr><tr><td>26</td><td>NPECL1</td><td>132</td><td>NPECL2</td></tr><tr><td>28</td><td>PPECL1 (I/P)</td><td>134</td><td>GL4</td></tr><tr><td>30</td><td>GL2</td><td>135</td><td>I/O (GLMX2)</td></tr></table>	Pin Number	Function	Pin Number	Function	23	I/O (GLMX1)	128	GL3	24	GL1	129	PPECL2 (I/P)	26	NPECL1	132	NPECL2	28	PPECL1 (I/P)	134	GL4	30	GL2	135	I/O (GLMX2)	
Pin Number	Function	Pin Number	Function																						
23	I/O (GLMX1)	128	GL3																						
24	GL1	129	PPECL2 (I/P)																						
26	NPECL1	132	NPECL2																						
28	PPECL1 (I/P)	134	GL4																						
30	GL2	135	I/O (GLMX2)																						
The following pins have been changed in the "456-Pin PBGA":	page 2-13																								
<table><tr><th>Pin Number</th><th>Function</th><th>Pin Number</th><th>Function</th></tr><tr><td>M1</td><td>GL1</td><td>N22</td><td>NPECL2</td></tr><tr><td>M2</td><td>GL2</td><td>N23</td><td>GL3</td></tr><tr><td>M22</td><td>GL4</td><td>N25</td><td>I/O (GLMX2)</td></tr><tr><td>N2</td><td>I/O (GLMX1)</td><td>P5</td><td>NPECL1</td></tr><tr><td>N4</td><td>PPECL1 (I/P)</td><td>P26</td><td>PPECL2 (I/P)</td></tr></table>	Pin Number	Function	Pin Number	Function	M1	GL1	N22	NPECL2	M2	GL2	N23	GL3	M22	GL4	N25	I/O (GLMX2)	N2	I/O (GLMX1)	P5	NPECL1	N4	PPECL1 (I/P)	P26	PPECL2 (I/P)	
Pin Number	Function	Pin Number	Function																						
M1	GL1	N22	NPECL2																						
M2	GL2	N23	GL3																						
M22	GL4	N25	I/O (GLMX2)																						
N2	I/O (GLMX1)	P5	NPECL1																						
N4	PPECL1 (I/P)	P26	PPECL2 (I/P)																						

Previous version	Changes in current version (Advanced v3.3)				Page
v2.0 (continued)	The following pins have been changed in the "144-FBGA Pin" table :				page 2-28
	Pin Number	Function	Pin Number	Function	
	C2	GL2	F9	GL4	
	D12	I/O (GLMX2	)F11	PPECL2 (I/P	
	E11	NPECL2	F12	GL3	
	F1	GL1	G1	PPECL1 (I/P)	
	F3	I/O (GLMX1)	G4	NPECL1	
	The following pins have been changed in the "256-Pin FBGA" table :				page 2-31
Pin Number	Function	Pin Number	Function		
H1	GL1	H16	GL4		
H2	NPECL1	J1	GL2		
H3	I/O (GLMX1)	J2	PPECL1 (I/P)		
H13	I/O (GLMX2)	J13	PPECL2 (I/P)		
H14	NPECL2	J16	GL3		
The following pins have been changed in the "484-Pin FBGA" table :				page 2-35	
Pin Number	Function	Pin Number	Function		
L4	GL1	L19	GL4		
L5	NPECL1	M4	GL2		
L6	I/O (GLMX1)	M5	PPECL1 (I/P)		
L16	I/O (GLMX2)	M16	PPECL2 (I/P)		
L17	NPECL2	M19	GL3		
The following pins have been changed in the "676-Pin FBGA" table :				page 2-42	
Pin Number	Function	Pin Number	Function		
N1	GL1	N25	GL4		
N3	I/O (GLMX1)	P1	GL2		
N5	NPECL1	P5	PPECL1 (I/P)		
N22	GL3	P22	I/O (GLMX2)		
N24	NPECL2	P24	PPECL2 (I/P)		
The following pins have been changed in the "896-Pin FBGA" table :				page 2-50	
Pin Number	Function	Pin Number	Function		
R2	I/O (GLMX1)	T3	GL2		
R4	NPECL1	T4	PPECL1 (I/P)		
R5	GL1	T26	PPECL2 (I/P)		
R27	NPECL2	T27	GL4		
R29	I/O (GLMX2)	T28	GL3		
The following pins have been changed in the "1152-Pin FBGA" table :				page 2-60	
Pin Number	Function	Pin Number	Function		
U4	I/O (GLMX1)	U29	NPECL2		
U6	NPECL1	U31	I/O (GLMX2)		
U7	GL1	V28	PPECL2 (I/P)		
V5	GL2	V29	GL4		
V6	PPECL1 (I/P)	V30	GL3		

Previous version	Changes in current version (Advanced v3.3)	Page
Advanced v0.7	The "ProASICPLUS Architecture" was updated.	page 1-2
	The "Array Coordinates" and Table 1-2 are new.	page 1-6
	The "Power-Up Sequencing" is new.	page 1-9
	"I/O Features" was updated.	page 1-8
	The "Timing Control and Characteristics" was updated. "Physical Implementation", "Functional Description", "Lock Signal", and "PLL Configuration Options" are new.	page 1-11 to page 1-12
	"PLL Block – Top-Level View and Detailed PLL Block Diagram" was updated.	page 1-13
	Figure 1-15 was updated.	page 1-14
	"Sample Implementations", "Adjustable Clock Delay", and the "Clock Skew Minimization" are new.	page 1-15
	Figure 1-16, Figure 1-17, Figure 1-18, Figure 1-19, and Figure 1-20 are new.	page 1-16 to page 1-18
	The "PLL Electrical Specifications" is new.	page 1-19
	The "Design Environment" was updated.	page 1-24
	Figure 1-26 was updated.	page 1-25
	The "Calculating Typical Power Dissipation" was updated.	page 1-28
	The "DC Electrical Specifications (VDDP = 2.5V $\pm$ 0.2V) ¹ " was updated.	page 1-31
	The "DC Electrical Specifications (VDDP = 3.3V $\pm$ 0.3V and VDD 2.5V $\pm$ 0.2V) ¹ " was updated.	page 1-33
	The "DC Specifications (3.3V PCI Operation) ¹ " was updated.	page 1-35
	The "Tristate Buffer Delays" (the figure and table) have been updated.	page 1-37
	The "Output Buffer Delays" (the figure and table) have been updated.	page 1-38
	The "Input Buffer Delays" was updated.	page 1-39
	The "Global Input Buffer Delays" was updated.	page 1-40
	The "Predicted Global Routing Delay" was updated.	page 1-40
	The "Global Routing Skew" was updated.	page 1-40
	The "Sample Macrocell Library Listing" was updated.	page 1-41
	The "Pin Description" was updated. GLMX is new.	page 1-63
	The "Recommended Design Practice for VPN/VPP" was updated.	page 1-64
	Pin AK31 of FG1152 for the APA1000 changed to V _{pp} .	page 2-67

Previous version	Changes in current version (Advanced v3.3)	Page
(Advanced v0.6)	The "Features and Benefits" on page i-i were updated.	page i-i
	The "ProASICPLUS Product Profile" on page i-i was updated.	page i-i
	The "Ordering Information" on page i-ii was updated.	page i-ii
	The "Plastic Device Resources" on page i-ii was updated.	page i-ii
	The "ProASICPLUS Architecture" on page 1-2 was updated.	page 1-2
	Table 1-1 was updated.	page 1-6
	Figure 1-14 was updated.	page 1-13
	The "Design Environment" was updated.	page 1-24
	The "Package Thermal Characteristics" was updated.	page 1-27
	The "Calculating Typical Power Dissipation" was updated.	page 1-28
	The "Absolute Maximum Ratings*" was updated.	page 1-30
	The "Programming, Storage and Operating Limits" was updated.	page 1-30
	The "Supply Voltages" was updated.	page 1-30
	The "Recommended Operating Conditions" was updated.	page 1-31
	The "DC Electrical Specifications (VDDP = 2.5V $\pm$ 0.2V) ¹ " was updated.	page 1-31
	The "DC Electrical Specifications (VDDP = 3.3V $\pm$ 0.3V and VDD 2.5V $\pm$ 0.2V) ¹ " was updated.	page 1-33
	The "Synchronous Write and Read to the Same Location" was updated.	page 1-50
	The "Asynchronous Write and Synchronous Read to the Same Location" was updated.	page 1-51
	The "Asynchronous FIFO Read" was updated.	page 1-56
	The "Pin Description" has been updated.	page 1-63
	The "Recommended Design Practice for VPN/VPP" is new.	page 1-64
Advanced v0.5	The "100-Pin TQFP" is new.	page 2-1
	The "484-Pin FBGA" is new.	page 2-35
Advanced v0.4	The description for the V _{PN} pin has changed.	page 1-64
Advanced v0.4	The "Plastic Device Resources" has been updated.	page i-ii
	Figure 1-12 and Figure 1-13 have been updated.	page 1-13
	The "Tristate Buffer Delays" has been updated.	page 1-37
	The "Output Buffer Delays" has been updated.	page 1-38
	The "Input Buffer Delays" has been updated.	page 1-39
	The "Global Input Buffer Delays" has been updated.	page 1-40
	The "456-Pin PBGA" has been updated.	page 2-13
	The "676-Pin FBGA" has been updated.	page 2-42

Previous version	Changes in current version (Advanced v3.3)	Page
Advanced v0.3	The "ProASICPLUS Product Profile" has been changed.	page i-i
	The "Plastic Device Resources" has been updated.	page i-ii
	The "ProASICPLUS I/O Power Supply Voltages" has been updated.	page 1-8
	WDATA has ben changed to DI, and RDATA has been changed to DO to make them consistent with the signal names found in the <i>Macro Library Guide</i> .	
	Figure 1-21 and Figure 1-22 have been updated.	page 1-21 and page 1-22
	The "Design Environment" and Figure 1-26 have been updated.	page 1-24 and page 1-25
	The table in the "Package Thermal Characteristics" has been updated.	page 1-27
	The "Calculating Typical Power Dissipation" is new.	page 1-28
	The "Programming, Storage and Operating Limits" is new.	page 1-30
	The "Supply Voltages" has been updated.	page 1-30
	The "DC Electrical Specifications (VDDP = 2.5V $\pm$ 0.2V) ¹ " was updated.	page 1-31
	The "DC Electrical Specifications (VDDP = 3.3V $\pm$ 0.3V and VDD 2.5V $\pm$ 0.2V) ¹ " was updated.	page 1-33
	The "Recommended Operating Conditions" was updated.	page 1-31
	The "ProASICPLUS Clock Management System" was updated.	page 1-11
	Figure 1-14 was updated.	page 1-13
	Figure 1-13 is new.	page 1-11
	Tables 5, 6, and 7 from Advanced v0.3 were removed.	
	The "Memory Block SRAM Interface Signals" was updated.	page 1-22
	The "Memory Block FIFO Interface Signals" was updated.	page 1-23
	All pinout tables have been updated, and several packages are new: 208-Pin PQFP – APA150, APA300, APA450, APA600 456-Pin PBGA – APA150, APA300, APA450, APA600 144-Pin FBGA – APA150, APA300, APA450 256-Pin FBGA – APA150, APA300, APA450, APA600 676-Pin FBGA – APA600	
Advanced v0.1	Figure 1-23 has been updated	page 1-23

Data Sheet Categories

In order to provide the latest information to designers, some datasheets are published before data has been fully characterized. Datasheets are designated as "Product Brief," "Advanced," "Production," and "Datasheet Supplement." The definition of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advanced or production) containing general product information. This brief gives an overview of specific device and family information.

Advanced

This datasheet version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production.

Unmarked (production)

This datasheet version contains information that is considered to be final.

Datasheet Supplement

The datasheet supplement gives specific device information for a derivative family that differs from the general family datasheet. The supplement is to be used in conjunction with the datasheet to obtain more detailed information and for specifications that do not differ between the two families.

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